

# HP ProLiant ML350e Gen8 v2 Server User Guide

## Abstract

This document is for the person who installs, administers, and troubleshoots servers and storage systems. HP assumes you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels.



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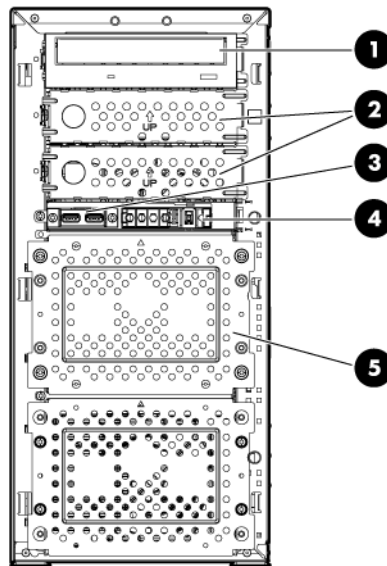
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# Component identification

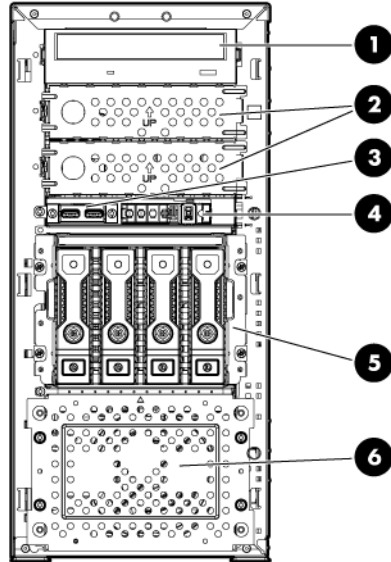
## Front panel components

- Non-hot-plug drive configuration



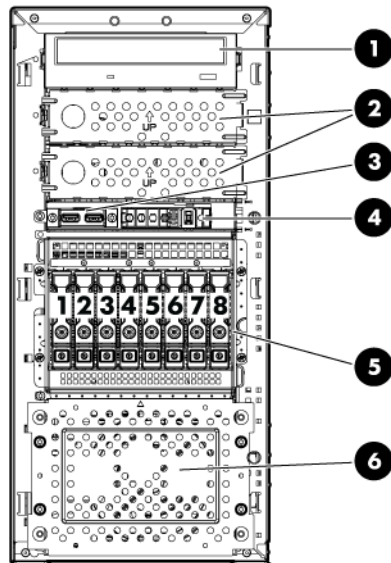
Item	Description
1	Optical drive
2	Optional media bay (2)
3	USB 2.0 connectors (2)
4	Thermal sensor
5	LFF drives (4)

- Four-bay LFF drive configuration



Item	Description
1	Optical drive
2	Optional media bay (2)
3	USB 2.0 connectors (2)
4	Thermal sensor
5	LFF drives (4)
6	Optional drive bay

- Eight-bay SFF drive configuration

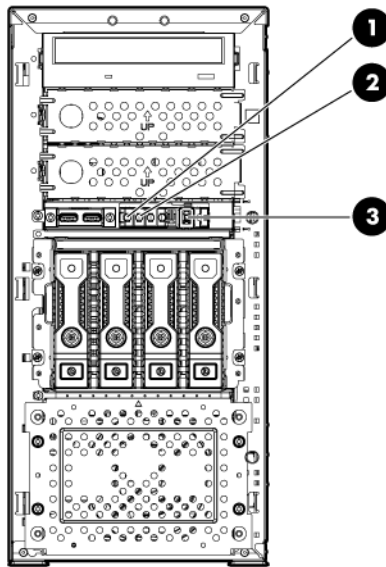


Item	Description
1	Optical drive
2	Optional media bay (2)
3	USB 2.0 connectors (2)



Item	Description
4	Thermal sensor
5	SFF drives (8)
6	Optional drive bay

## Front panel LEDs and buttons

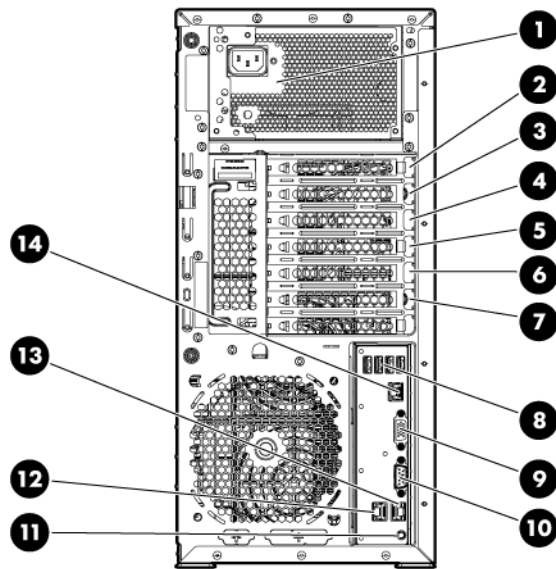


Item	Description	Status
1	Health LED	Solid green = Normal Flashing amber = System degraded Flashing red (1 Hz/cycle per sec) = System critical Fast-flashing red (4 Hz/cycles per sec) = Power fault*
2	NIC status LED	Solid green = Link to network Flashing green (1 Hz/cycle per sec) = Network active Off = No network activity
3	Power On/Standby button and system power LED	Solid green = System on Flashing green (1 Hz/cycle per sec) = Performing power on sequence Solid amber = System in standby Off = No power present**

\* To identify components in a degraded or critical state, see the Systems Insight Display LEDs, check iLO/BIOS logs, and reference the server troubleshooting guide.

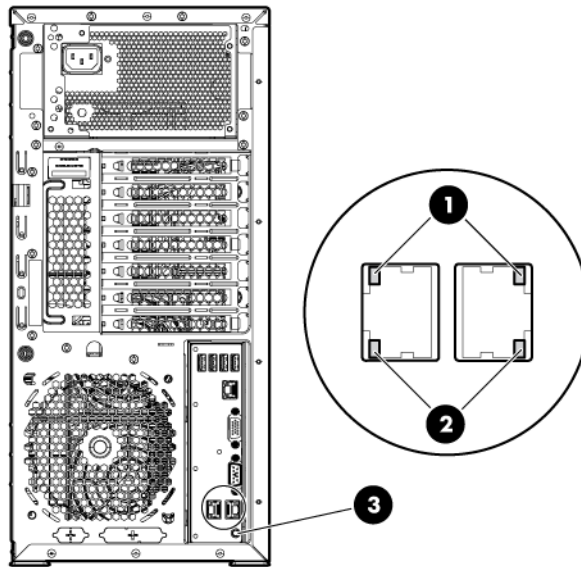
\*\* Facility power is not present, power cord is not attached, no power supplies are installed, power supply failure has occurred, or the power button cable is disconnected.

# Rear panel components



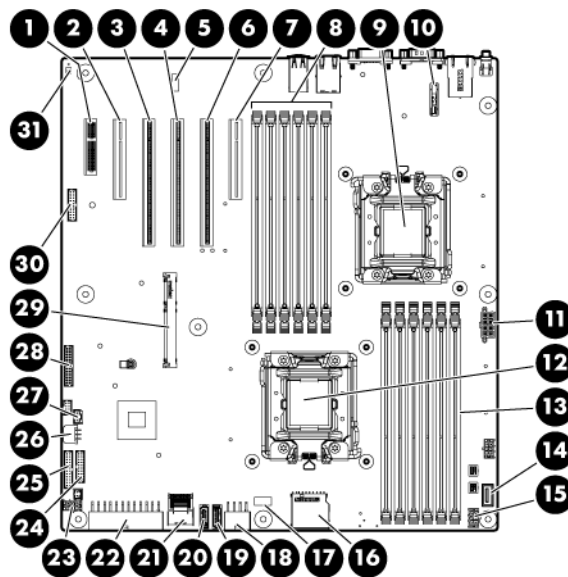
Item	Description
1	Integrated power supply
2	Slot 6 PCIe2 x4(1) for processor 1
3	Slot 5 PCIe2 x8(4,1) for processor 1
4	Slot 4 PCIe3 x16(8,4,1) for processor 2
5	Slot 3 PCIe3 x16(16,8,4,1) for processor 2
6	Slot 2 PCIe3x16 (16,8,4,1) for processor 1
7	Slot 1 PCIe3 x8 (4,1) for processor 1
8	USB 2.0 connectors (4)
9	Video connector
10	Serial connector
11	UID/LED button
12	NIC connector 2
13	NIC connector 1
14	iLO connector

# Rear panel LEDs



Item	Description	Status
1	NIC activity LED	Green = Network activity Flashing green = Network activity Off = No network activity
2	NIC link LED	Green = Network link Off = No network link
3	UID LED button	Blue = Activated Flashing blue = System is being managed remotely Off = Deactivated

# System board components



Item	Description
1	Slot 6 PCIe2 x4 (1)
2	Slot 5 PCIe2 x8 (4,1)
3	Slot 4 PCIe3 x16 (8,4,1)
4	Slot 3 PCIe3 x16 (16,8,4,1)
5	System maintenance switch
6	Slot 2 PCIe3 x16 (16,8,4,1)
7	Slot 1 PCIe3 x8 (4,1)
8	Processor 2 DIMM slots
9	Processor socket 2
10	System battery
11	Processor 2 power connector
12	Processor socket 1 (populated)
13	Processor 1 DIMM slots
14	Internal USB connector
15	Fan connector 3
16	SD card connector
17	Internal USB tape drive connector
18	Processor 1 power connector
19	SATA connector 2
20	SATA connector 1
21	Mini-SAS connector
22	System board power connector
23	Fan connector 2
24	Front panel connector
25	Front panel connector
26	Fan connector 1
27	Ambient temperature sensor connector
28	Redundant power supply connector
29	Cache module connector
30	TPM connector
31	NMI header

## System maintenance switch

The system maintenance switch (SW2) is a twelve-position switch that is used for system configuration.

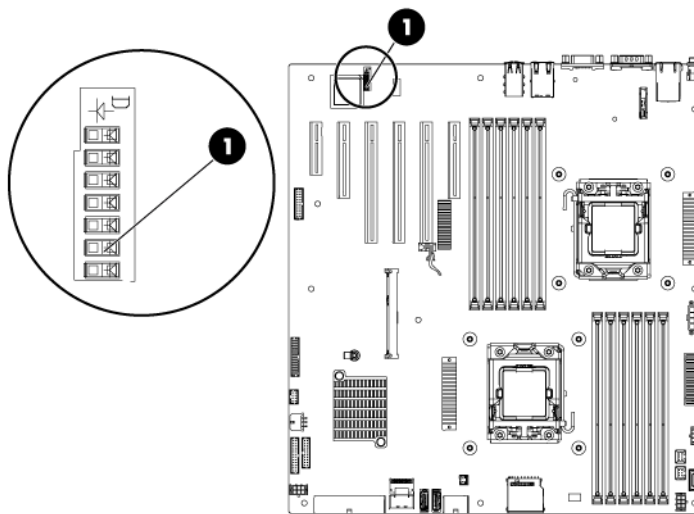
Position	Description	Function
S1	iLO security override	Off = No function. On = Override enabled.
S2	Configuration lock	Off = System configuration can be changed. On = System configuration is locked.
S5	Password disable	Off = Power-on password enabled. On = Power-on password disabled.

Position	Description	Function
S6	Reset configuration	Off = No function On = ROM reads the system configuration as invalid.
S3, S4, S7-S12	—	Reserved

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.

**CAUTION:** Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

## System board LEDs



Item	LED description	Status
1	System power good	Green = System power good Off = System power not ready

## NMI functionality

An NMI crash dump creates a crash dump log before resetting a system which is not responding.

Crash dump log analysis is an essential part of diagnosing reliability problems, such as failures of operating systems, device drivers, and applications. Many crashes freeze a system, and the only available action for administrators is to restart the system. Resetting the system erases any information which could support problem analysis, but the NMI feature preserves that information by performing a memory dump before a system reset.

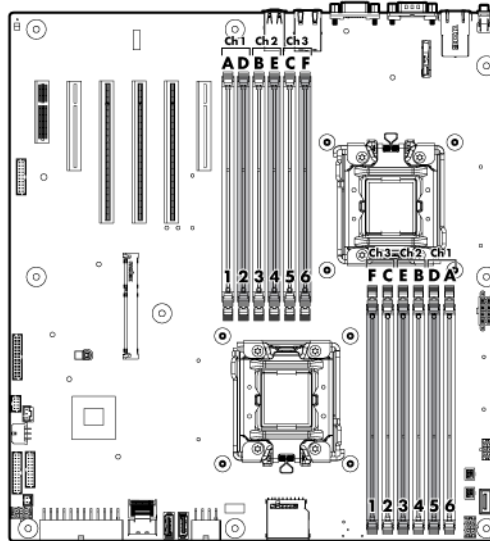
To force the system to invoke the NMI handler and generate a crash dump log, do one of the following:

- Use the iLO Virtual NMI feature.
- Short the NMI header.

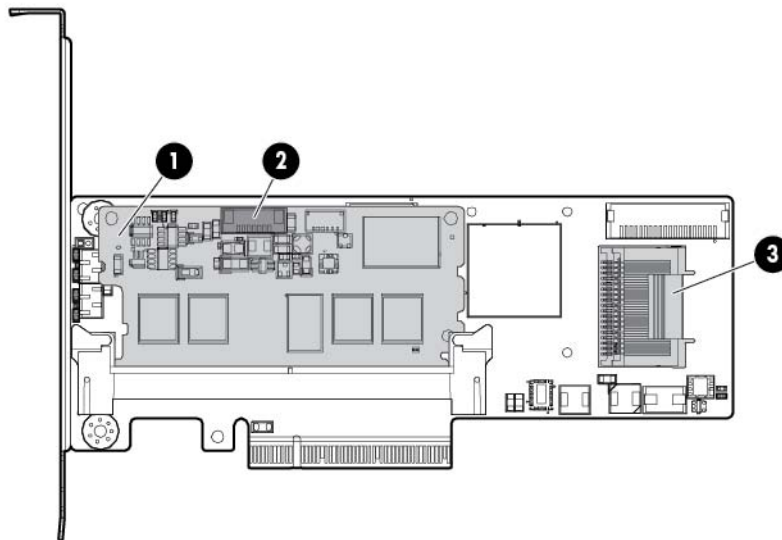
For more information, see the HP website (<http://www.hp.com/support/NMI>).

## DIMM slot locations

DIMM slots are numbered sequentially (1 through 6) for each processor. The supported AMP modes use the letter assignments for population guidelines.



## Smart Array SAS RAID controller card components



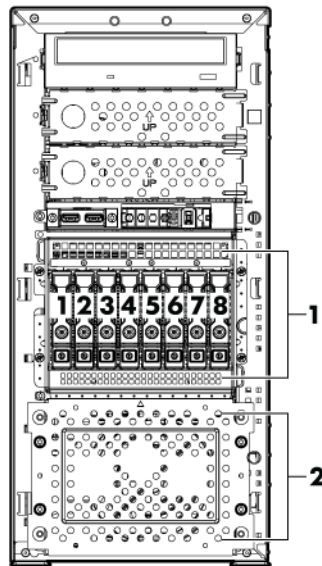
Item	Description
1	Cache module
2	Capacitor pack cable connector
3	Internal SAS connector

# SAS and SATA device numbers

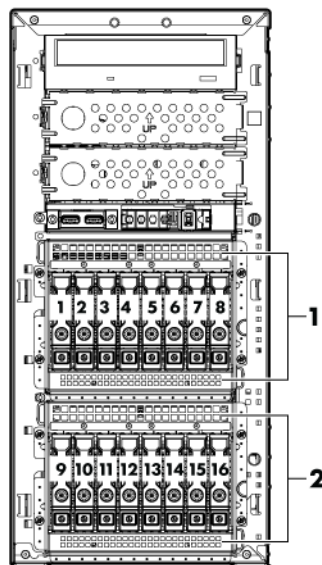
With optional drive cages installed, the server supports up to 16 SFF drives or up to 8 LFF drives. The server does not support mixing SFF and LFF drives.

HP recommends that you populate drive bays starting with the lowest SAS or SATA device number. Drives are numbered from left to right in each component box. Component boxes are numbered 1 to 2 from top to bottom.

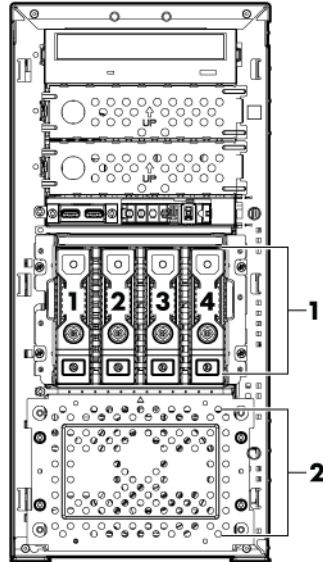
- SFF drive numbering



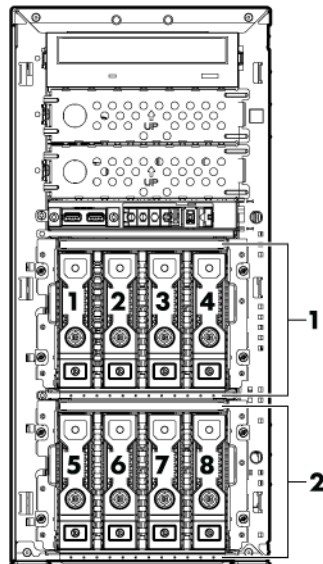
- Eight-bay + eight-bay SFF drive numbering



- LFF drive numbering

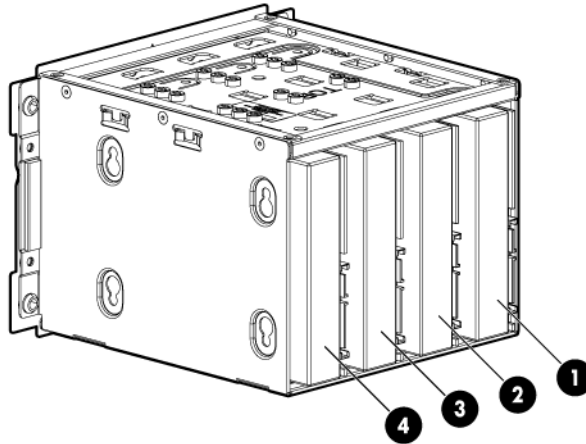


- Four-bay + four-bay LFF drive numbering (hot-plug only)





- Non-hot-plug drive numbering



## SAS and SATA drive LED combinations

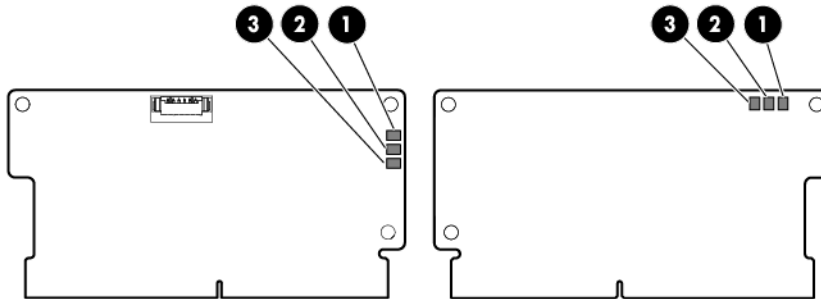
Online/activity LED (green)	Fault/UID LED (amber/blue)	Interpretation
On, off, or flashing	Alternating amber and blue	The drive has failed, or a predictive failure alert has been received for this drive. The drive also has been selected by a management application.
On, off, or flashing	Steadily blue	The drive is operating normally, and it has been selected by a management application.
On	Amber, flashing regularly (1 Hz)	A predictive failure alert has been received for this drive. Replace the drive as soon as possible.
On	Off	The drive is online, but it is not active currently.
Flashing regularly (1 Hz)	Amber, flashing regularly (1 Hz)	The drive is part of an array that is undergoing capacity expansion or stripe migration, but a predictive failure alert has been received for this drive. To minimize the risk of data loss, do not replace the drive until the expansion or migration is complete.*
Flashing regularly (1 Hz)	Off	The drive is rebuilding, or it is part of an array that is undergoing capacity expansion or stripe migration.*
Flashing irregularly	Amber, flashing regularly (1 Hz)	The drive is active, but a predictive failure alert has been received for this drive. Replace the drive as soon as possible.
Flashing irregularly	Off	The drive is active, and it is operating normally.
Off	Steadily amber	A critical fault condition has been identified for this drive, and the controller has placed it offline. Replace the drive as soon as possible.
Off	Amber, flashing regularly (1 Hz)	A predictive failure alert has been received for this drive. Replace the drive as soon as possible.
Off	Off	The drive is offline, a spare, or not configured as part of an array.

\* Do not remove the drive. Removing a drive might terminate the current operation and cause data loss.

# FBWC module LED definitions

## P222 and P430 modules

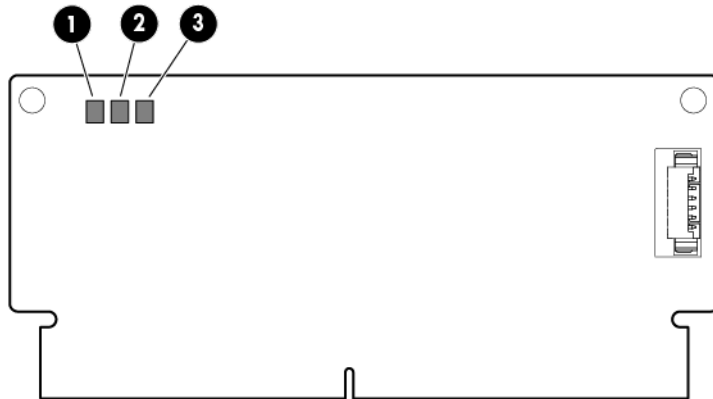
The FBWC module has three LEDs (one amber and two green). The LEDs are duplicated on the reverse side of the FBWC module to facilitate status viewing.



1 - Amber	2 - Green	3 - Green	Interpretation
Off	Off	Off	The FBWC module is not powered.
Off	Flashing 0.5 Hz	Flashing 0.5 Hz	The FBWC microcontroller is executing from within its boot loader and receiving new flash code from the host controller.
Off	Flashing 1 Hz	Flashing 1 Hz	The FBWC module is powering up, and the capacitor pack is charging.
Off	Off	Flashing 1 Hz	The FBWC module is idle, and the capacitor pack is charging.
Off	Off	On	The FBWC module is idle, and the capacitor pack is charged.
Off	On	On	The FBWC module is idle, the capacitor pack is charged, and the cache contains data that has not yet been written to the drives.
Off	Flashing 1 Hz	Off	A backup is in progress.
Off	On	Off	The current backup is complete with no errors.
Flashing 1 Hz	Flashing 1 Hz	Off	The current backup failed, and data has been lost.
Flashing 1 Hz	Flashing 1 Hz	On	A power error occurred during the previous or current boot. Data might be corrupt.
Flashing 1 Hz	On	Off	An overtemperature condition exists.
Flashing 2 Hz	Flashing 2 Hz	Off	The capacitor pack is not attached.
Flashing 2 Hz	Flashing 2 Hz	On	The capacitor has been charging for 10 minutes, but has not reached sufficient charge to perform a full backup.
On	On	Off	The current backup is complete, but power fluctuations occurred during the backup.
On	On	On	The cache module microcontroller has failed.

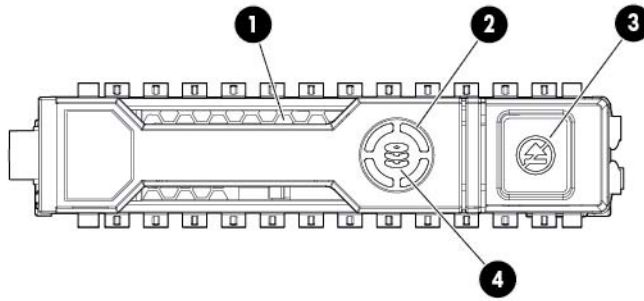
## B120i module

The FBWC module has three LEDs (one amber and two green).



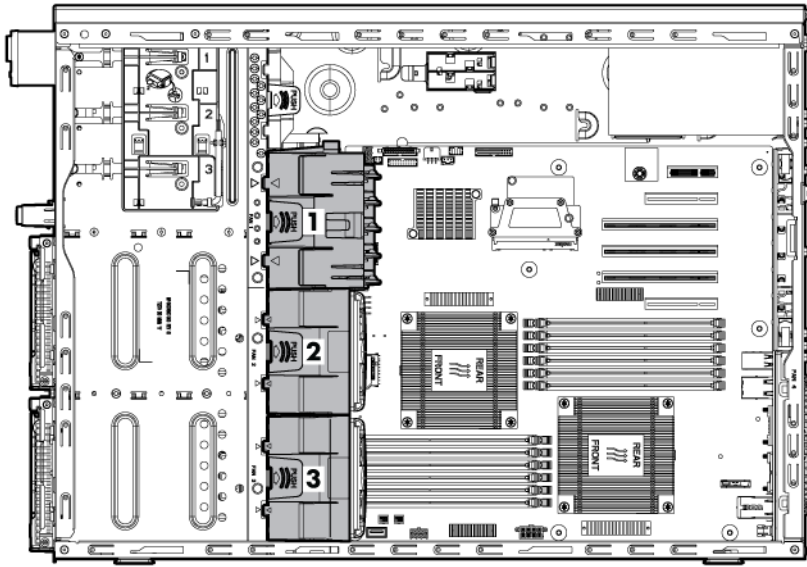
1 - Amber	2 - Green	3 - Green	Interpretation
Off	Off	Off	The FBWC module is not powered.
Off	Flashing 0.5 Hz	Flashing 0.5 Hz	The FBWC microcontroller is executing from within its boot loader and receiving new flash code from the host controller.
Off	Flashing 1 Hz	Flashing 1 Hz	The FBWC module is powering up, and the capacitor pack is charging.
Off	Off	Flashing 1 Hz	The FBWC module is idle, and the capacitor pack is charging.
Off	Off	On	The FBWC module is idle, and the capacitor pack is charged.
Off	On	On	The FBWC module is idle, the capacitor pack is charged, and the cache contains data that has not yet been written to the drives.
Off	Flashing 1 Hz	Off	A backup is in progress.
Off	On	Off	The current backup is complete with no errors.
Flashing 1 Hz	Flashing 1 Hz	Off	The current backup failed, and data has been lost.
Flashing 1 Hz	Flashing 1 Hz	On	A power error occurred during the previous or current boot. Data might be corrupt.
Flashing 1 Hz	On	Off	An overtemperature condition exists.
Flashing 2 Hz	Flashing 2 Hz	Off	The capacitor pack is not attached.
Flashing 2 Hz	Flashing 2 Hz	On	The capacitor has been charging for 10 minutes, but has not reached sufficient charge to perform a full backup.
On	On	Off	The current backup is complete, but power fluctuations occurred during the backup.
On	On	On	The FBWC module microcontroller has failed.

# Hot-plug drive LED definitions



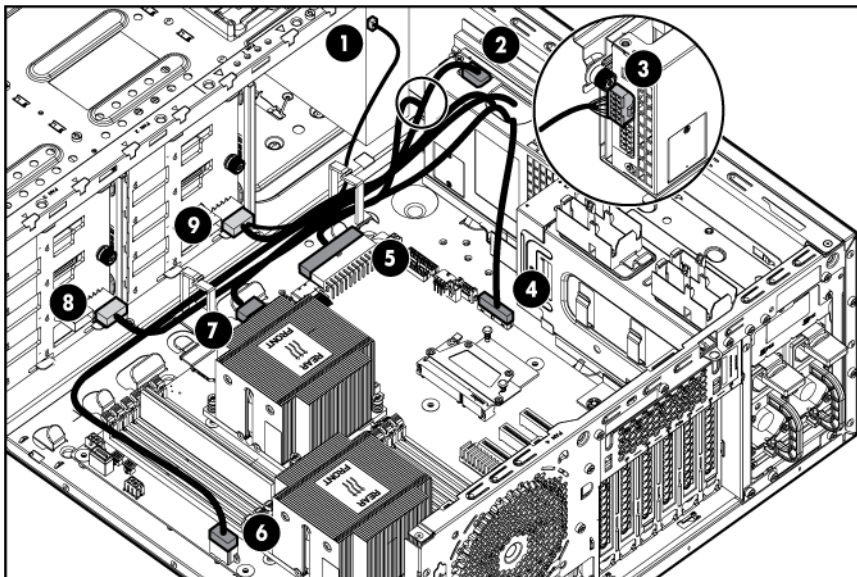
Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, strip size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

# Fan locations



Item	Description	Configuration
1	Fan 1	Primary
2	Fan 2	Primary
3	Fan 3	Optional

# Redundant power supply connectors



Item	Description	Connector identifier
1	Optical drive power connector	P7, P8, P9, P10
2	Processor 2 RPS backplane connector	P3
3	Box 2 RPS backplane connector	P5

<b>Item</b>	<b>Description</b>	<b>Connector identifier</b>
4	RPS connector	N/A
5	System board power connector	P1
6	Processor 2 power connector	P3M
7	Processor 1 power connector	P2
8	Box 2 power connector	P5H
9	Box 1 power connector	BP1

---

# Operations

## Power up the server

1. Connect each power cord to the server.
2. Connect each power cord to the power source.
3. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

## Power down the server

Before powering down the server for any upgrade or maintenance procedures, perform a backup of critical server data and programs.



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**IMPORTANT:** When the server is in standby mode, auxiliary power is still being provided to the system.

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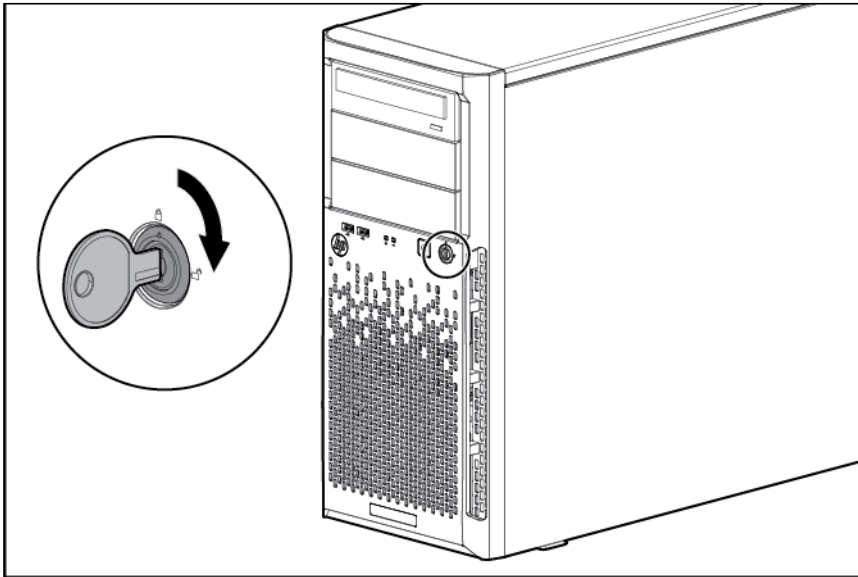
To power down the server, use one of the following methods:

- Press and release the Power On/Standby button.  
This method initiates a controlled shutdown of applications and the OS before the server enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server to enter standby mode.  
This method forces the server to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through iLO 4.  
This method initiates a controlled remote shutdown of applications and the OS before the server enters standby mode.

Before proceeding, verify the server is in standby mode by observing that the system power LED is amber.

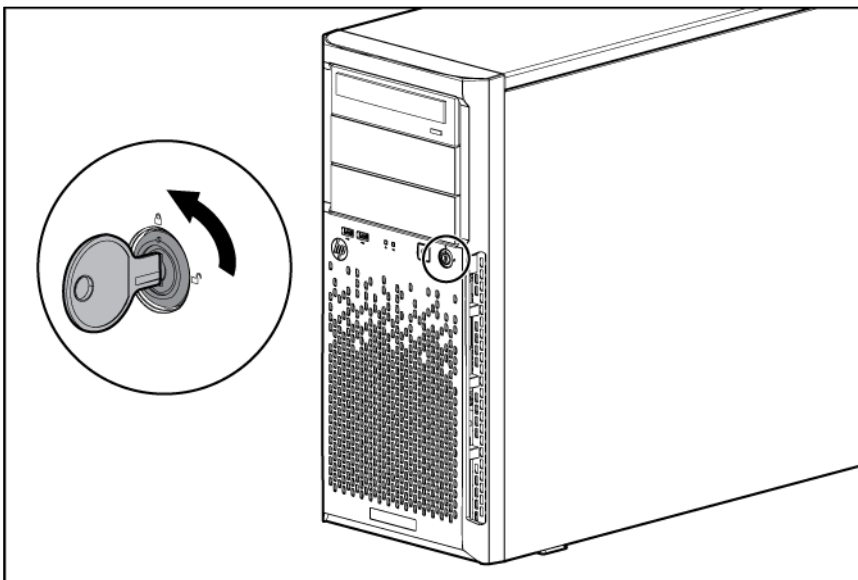
## Unlock the front bezel

Using the key provided with the server, unlock the bezel with a clockwise turn.



## Lock the front bezel

Using the key provided with the server, lock the bezel with a counterclockwise turn.

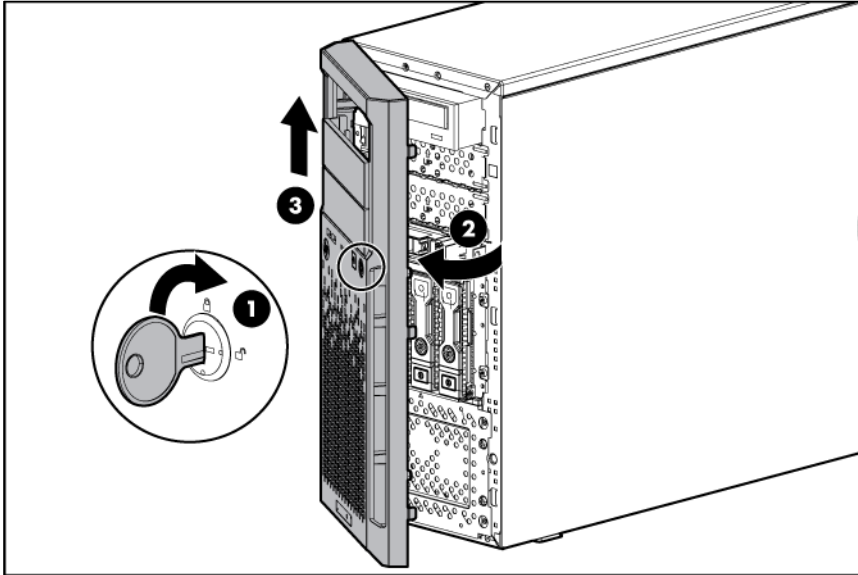


## Remove the front bezel

This server has a removable bezel that must be unlocked and opened before accessing the drives. The bezel must be kept closed during normal server operations.

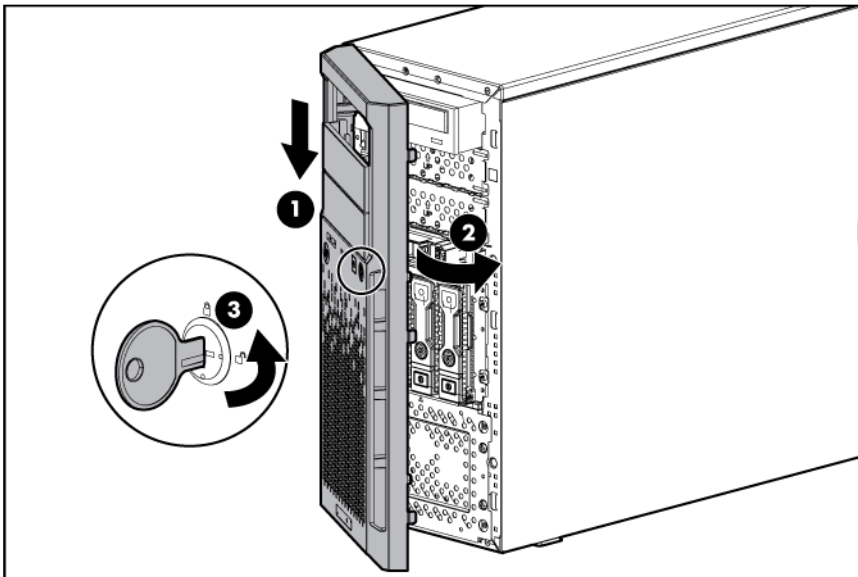


To remove the component, unlock and remove the front bezel.



## Install the front bezel

1. Insert the bezel.
2. Close the bezel.
3. Using the key provided with the server, lock the bezel with a counterclockwise turn.



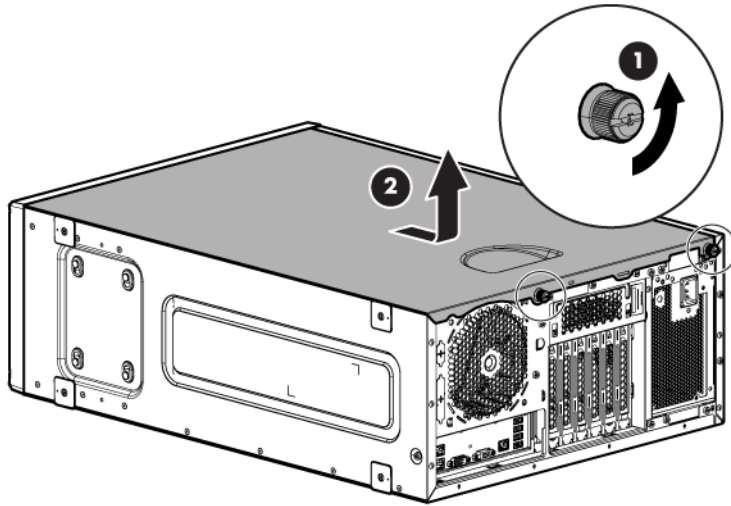
## Remove the access panel



**WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

**CAUTION:** For proper cooling do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed.

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel:
  - a. Loosen the access panel thumbscrews.
  - b. Slide the access panel back.
  - c. Lift the access panel away from the chassis.



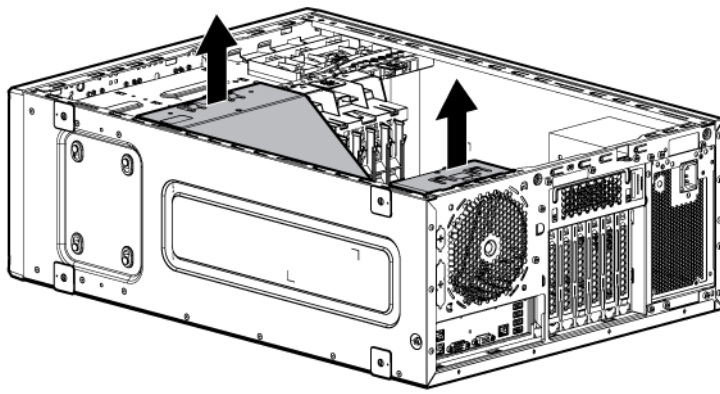
## Install the access panel

1. Install the access panel:
  - a. Place the access panel on the chassis, and slide it toward the front of the server.



# Remove the system air baffle

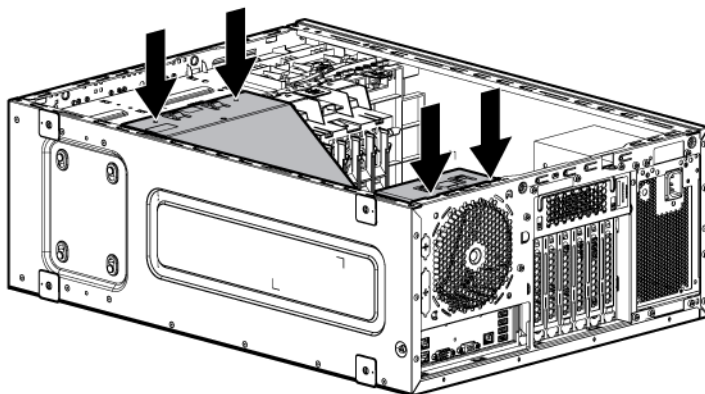
1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle.



# Install the system air baffle

**⚠ CAUTION:** For proper cooling do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed.

1. Insert the system air baffle.

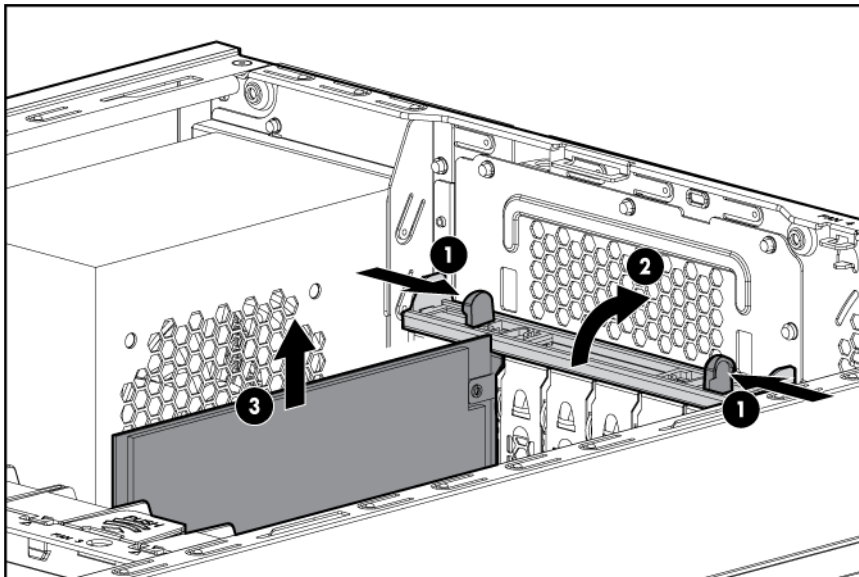


2. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).

3. Install the access panel (on page 26).
4. Return the server to an upright position.
5. Lock the front bezel (on page 24).
6. Power up the server (on page 23).

## Remove the full-length expansion board

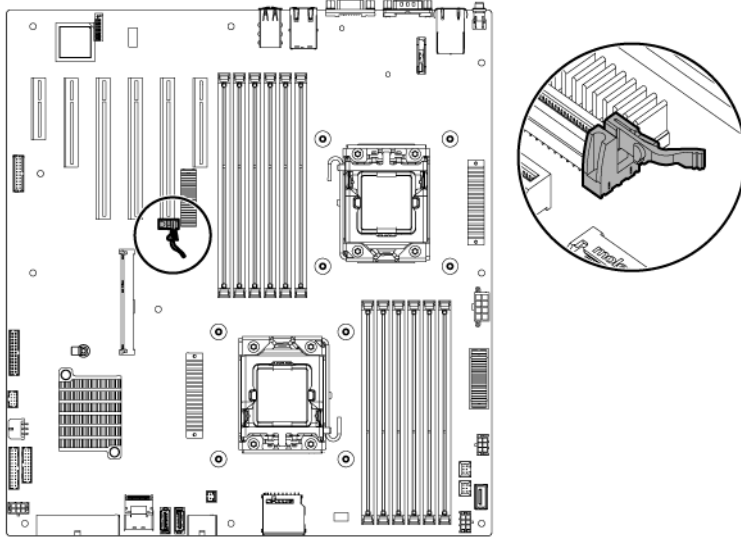
1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Open the PCI slot cover retaining bracket.
8. Open the full-length expansion board retaining bracket and remove the expansion board.



---

**IMPORTANT:** If removing an expansion board from PCI slot 2, release the retainer latch on the system board, and then remove the expansion board from the system.

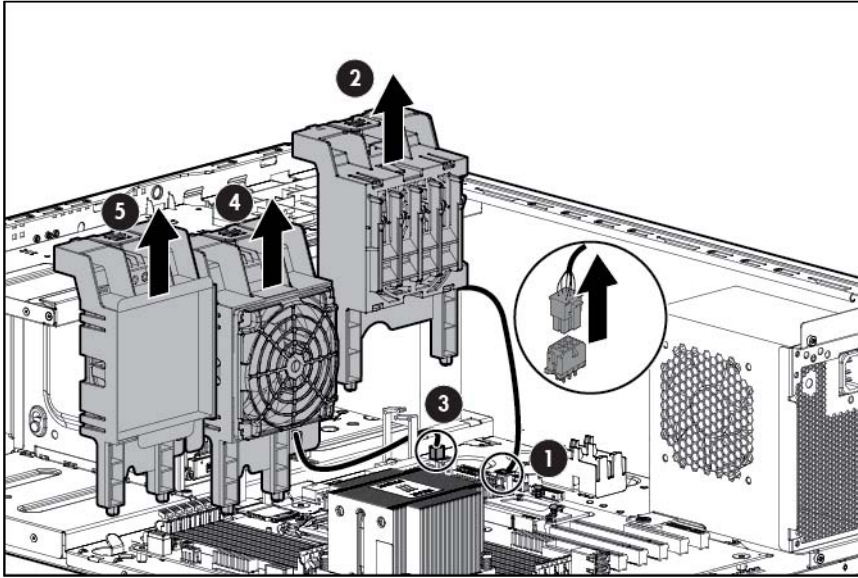
---



## Remove the fan modules and the fan blank

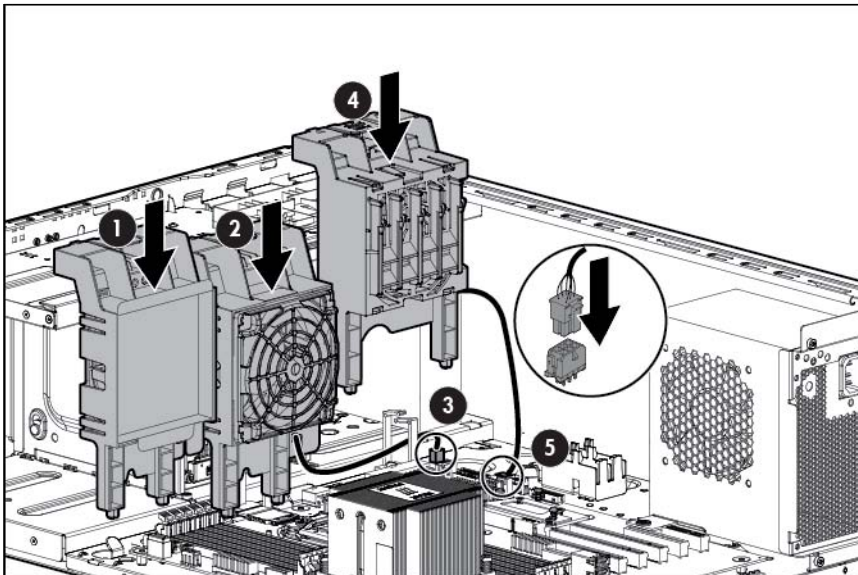
1. Power down the server (on page [23](#)).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page [24](#)).
4. Place the server on its side.
5. Remove the access panel (on page [25](#)).
6. If installed, remove the PCI air baffle (on page [27](#)).
7. Remove any installed full-length PCI expansion cards ("[Remove the full-length expansion board](#)" on page [29](#)).
8. Remove the system air baffle (on page [28](#)).
9. Remove the fan modules and the fan blank:
  - a. Disconnect the fan 1 cable from the connector.
  - b. Remove fan 1.
  - c. Disconnect the fan 2 cable from the connector.
  - d. Remove fan 2.

- e. Remove the fan blank.



## Install the fan modules and the fan blank

1. Install the fan blank and the fan modules:
  - a. Install the fan blank.
  - b. Install fan 2.
  - c. Connect the fan 2 cable to the connector.
  - d. Install fan 1.
  - e. Connect the fan 1 cable to the connector.



2. Install the system air baffle (on page 28).
3. Install any full-length PCI expansion cards that were removed ("[Installing an expansion board](#)" on page 63).

4. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page [38](#)).
5. Install the access panel (on page [26](#)).
6. Return the server to an upright position.
7. Lock the front bezel (on page [24](#)).
8. Power up the server (on page [23](#)).



---

# Setup

## Optional installation services

Delivered by experienced, certified engineers, HP Care Pack services help you keep your servers up and running with support packages tailored specifically for HP ProLiant systems. HP Care Packs let you integrate both hardware and software support into a single package. A number of service level options are available to meet your needs.

HP Care Pack Services offer upgraded service levels to expand your standard product warranty with easy-to-buy, easy-to-use support packages that help you make the most of your server investments. Some of the Care Pack services are:

- Hardware support
  - 6-Hour Call-to-Repair
  - 4-Hour 24x7 Same Day
  - 4-Hour Same Business Day
- Software support
  - Microsoft®
  - Linux
  - HP ProLiant Essentials (HP SIM and RDP)
  - VMware
- Integrated hardware and software support
  - Critical Service
  - Proactive 24
  - Support Plus
  - Support Plus 24
- Startup and implementation services for both hardware and software

For more information on HP Care Pack Services, see the HP website (<http://www.hp.com/services/carepack>).

## Optimum environment

When installing the server, select a location that meets the environmental standards described in this section.

### Space and airflow requirements

#### **Tower server**

In a tower configuration, leave at least a 7.6-cm (3-in) clearance space at the front and back of the server for proper ventilation.

## Temperature requirements

To ensure continued, safe, and reliable equipment operation, install or position the system in a well-ventilated, climate-controlled environment.

The maximum recommended TMRA for most server products is 35°C (95°F). The temperature in the room where the server is located must not exceed 35°C (95°F).

- 
- △ **CAUTION:** To reduce the risk of damage to the equipment when installing third-party options:
- Do not permit optional equipment to impede airflow around the server beyond the maximum allowable limits.
  - Do not exceed the manufacturer's TMRA.
- 

## Power requirements

Installation of this equipment must comply with local and regional electrical regulations governing the installation of information technology equipment by licensed electricians. This equipment is designed to operate in installations covered by NFPA 70, 1999 Edition (National Electric Code) and NFPA-75, 1992 (code for Protection of Electronic Computer/Data Processing Equipment). For electrical power ratings on options, see the product rating label or the user documentation supplied with that option.

- 
- △ **CAUTION:** Protect the server from power fluctuations and temporary interruptions with a regulating uninterruptible power supply. This device protects the hardware from damage caused by power surges and voltage spikes and keeps the system in operation during a power failure.
- 

When installing more than one server, you might have to use additional power distribution devices to safely provide power to all devices. Observe the following guidelines:

- Balance the server power load between available AC supply branch circuits.
- Do not allow the overall system AC current load to exceed 80% of the branch circuit AC current rating.
- Do not use common power outlet strips for this equipment.
- Provide a separate electrical circuit for the server.

## Electrical grounding requirements

The server must be grounded properly for proper operation and safety. In the United States, you must install the equipment in accordance with NFPA 70, 1999 Edition (National Electric Code), Article 250, as well as any local and regional building codes. In Canada, you must install the equipment in accordance with Canadian Standards Association, CSA C22.1, Canadian Electrical Code. In all other countries, you must install the equipment in accordance with any regional or national electrical wiring codes, such as the International Electrotechnical Commission (IEC) Code 364, parts 1 through 7. Furthermore, you must be sure that all power distribution devices used in the installation, such as branch wiring and receptacles, are listed or certified grounding-type devices.

Because of the high ground-leakage currents associated with multiple servers connected to the same power source, HP recommends the use of a PDU that is either permanently wired to the building's branch circuit or includes a nondetachable cord that is wired to an industrial-style plug. NEMA locking-style plugs or those complying with IEC 60309 are considered suitable for this purpose. Using common power outlet strips for the server is not recommended.

# Server warnings and cautions

Before installing a server, be sure that you understand the following warnings and cautions.



**WARNING:** To reduce the risk of electric shock or damage to the equipment:

- Do not disable the power cord grounding plug. The grounding plug is an important safety feature.
- Plug the power cord into a grounded (earthed) electrical outlet that is easily accessible at all times.
- Unplug the power cord from the power supply to disconnect power to the equipment.
- Do not route the power cord where it can be walked on or pinched by items placed against it. Pay particular attention to the plug, electrical outlet, and the point where the cord extends from the server.



**WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



**WARNING:** To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



**CAUTION:** Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.



**CAUTION:** Protect the server from power fluctuations and temporary interruptions with a regulating uninterruptible power supply. This device protects the hardware from damage caused by power surges and voltage spikes and keeps the system in operation during a power failure.

## Identifying tower server shipping carton contents

Unpack the server shipping carton and locate the materials and documentation necessary for installing the server.

The contents of the server shipping carton include:

- Server
- Power cord
- Hardware documentation and software products

In addition to the supplied items, you might need:

- Hardware options
- Operating system or application software
- PDU

# Installing hardware options

Install any hardware options before initializing the server. For options installation information, refer to the option documentation. For server-specific information, refer to "Hardware options installation (on page 38)."

## Setting up a tower server

Follow the steps in this section to set up a tower server.

1. Place the server on a flat, stable surface.
2. Connect peripheral devices to the server.



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**WARNING:** To reduce the risk of electric shock, fire, or damage to the equipment, do not plug telephone or telecommunications connectors into RJ-45 connectors.

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3. Connect the power cord to the rear of the server.
4. Connect the power cord to the AC power source.



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**WARNING:** To reduce the risk of electric shock or damage to the equipment:

- Do not disable the power cord grounding plug. The grounding plug is an important safety feature.
  - Plug the power cord into a grounded (earthed) electrical outlet that is easily accessible at all times.
  - Unplug the power cord from the power supply to disconnect power to the equipment.
  - Do not route the power cord where it can be walked on or pinched by items placed against it. Pay particular attention to the plug, electrical outlet, and the point where the cord extends from the server.
- 

## Powering on and selecting boot options

1. Connect the Ethernet cable between the network connector on the server and a network jack.
2. Press the Power On/Standby button.
3. During the initial boot:
  - To modify the server configuration ROM default settings, press **F9** when prompted from the start up sequence to enter the RBSU. By default, RBSU runs in the English language.
  - If you do not need to modify the server configuration and are ready to install the system software, press **F10** to access Intelligent Provisioning.

---

**NOTE:** If an HP Smart Array controller has been added or is embedded in the system, the controller defaults to a RAID configuration based on the size and number of drives installed. For more information on modifying the controller default settings, see the documentation in the HP Smart Storage Information Library (<http://www.hp.com/go/smartstorage/docs>).

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For more information on automatic configuration, see the *HP ROM-Based Setup Utility User Guide* in the HP RBSU Information Library (<http://www.hp.com/go/rbsu/docs>).

# Installing the operating system

This HP ProLiant server does not ship with provisioning media. Everything needed to manage and install the system software and firmware is preloaded on the server.

To operate properly, the server must have a supported operating system. For the latest information on operating system support, see the HP website (<http://www.hp.com/go/supportos>).

To install an operating system on the server, use one of the following methods:

- **Intelligent Provisioning**—The iLO Management Engine is a new feature on ProLiant servers that contains Intelligent Provisioning for embedded deployment, updating, and provisioning capabilities. Intelligent Provisioning can configure the server and install an operating system, eliminating the need for SmartStart CDs and Smart Update Firmware DVDs.

To install an operating system on the server with Intelligent Provisioning (local or remote):

- a. Connect the Ethernet cable between the network connector on the server and a network jack.
  - b. Press the Power On/Standby button.
  - c. During server POST, press the **F10** key.
  - d. Complete the initial Preferences and Registration portion of Intelligent Provisioning (on page 94).
  - e. At the 1 Start screen, click the **Configure and Install** button.
  - f. To finish the installation, follow the onscreen prompts. An Internet connection is required to update the firmware and systems software.
- **Remote deployment installation**—To deploy an operating system remotely, use Insight Control server deployment for an automated solution.

For additional system software and firmware updates, download the HP Service Pack for ProLiant from the HP website (<http://www.hp.com/go/spp/download>). Software and firmware must be updated before using the server for the first time, unless any installed software or components require an older version. For more information, see "Keeping the system current (on page 101)."

For more information on using these installation methods, see the HP website (<http://www.hp.com/go/ilo>).

# Registering the server

To experience quicker service and more efficient support, register the product at the HP Product Registration website (<http://register.hp.com>).

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# Hardware options installation

## Introduction

If more than one option is being installed, read the installation instructions for all the hardware options and identify similar steps to streamline the installation process.

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**⚠ WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

---

**⚠ CAUTION:** To prevent damage to electrical components, properly ground the server before beginning any installation procedure. Improper grounding can cause electrostatic discharge.

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## PCI air baffle option

Install the PCI air baffle option when a PCI expansion card is installed in the server.

To install the component:

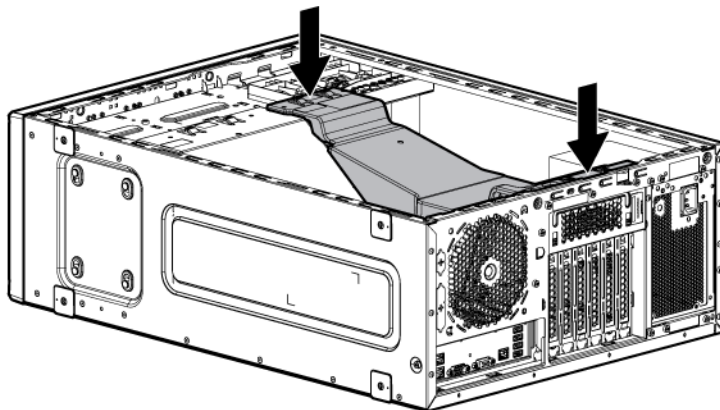
1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).

---

**⚠ CAUTION:** For proper cooling do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed.

---

6. Insert the PCI air baffle.



7. Install the access panel (on page 26).
8. Return the server to an upright position.
9. Lock the front bezel (on page 24).
10. Connect each power cord to the server.
11. Connect each power cord to the power source.
12. Power up the server (on page 23).

## Second processor option

The server supports single-processor and dual-processor operation.



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**CAUTION:** To avoid damage to the processor and system board, only authorized personnel should attempt to replace or install the processor in this server.

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**CAUTION:** To prevent possible server malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.

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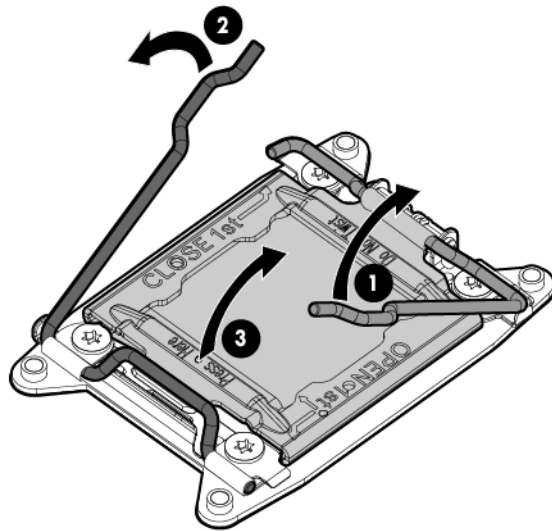
**IMPORTANT:** If installing a processor with a faster speed, update the system ROM before installing the processor.

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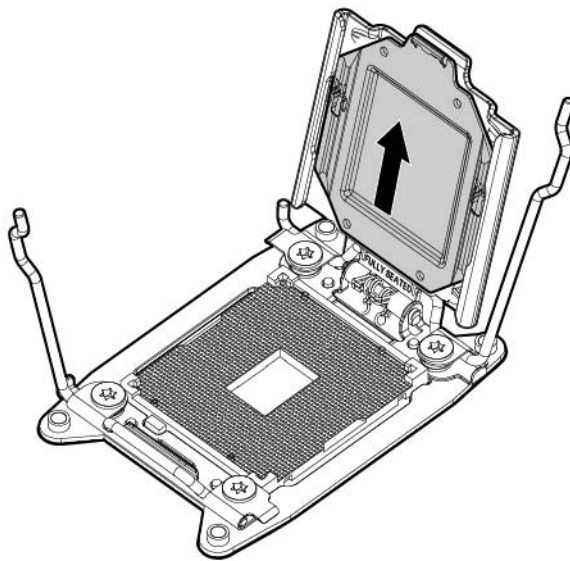
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).

8. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.

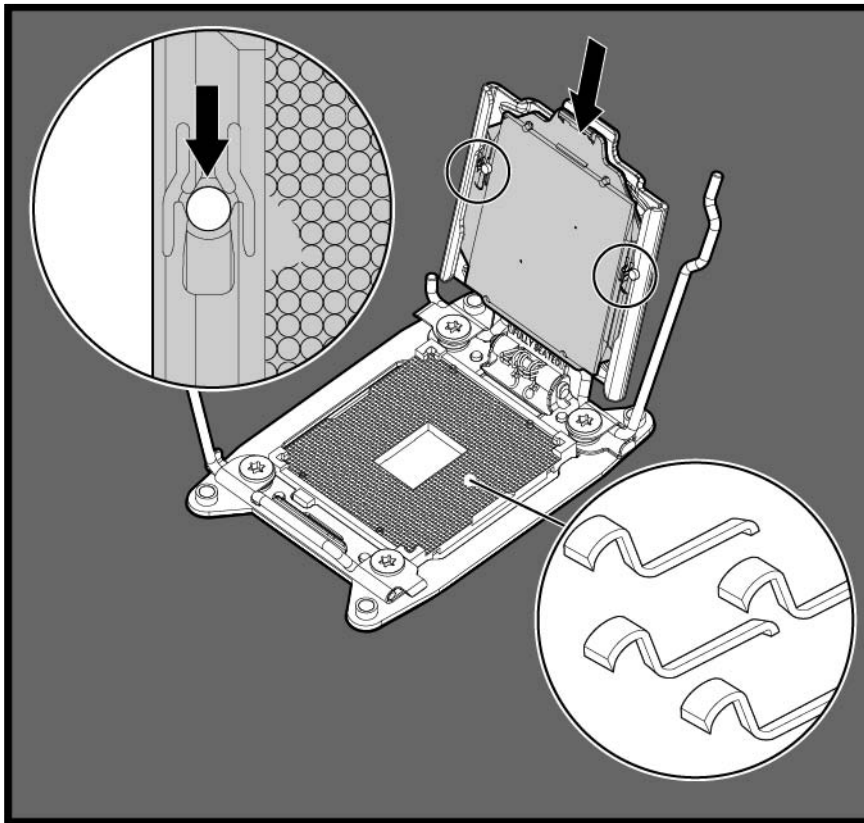


9. Remove the clear processor socket cover. Retain the processor socket cover for future use.





10. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**

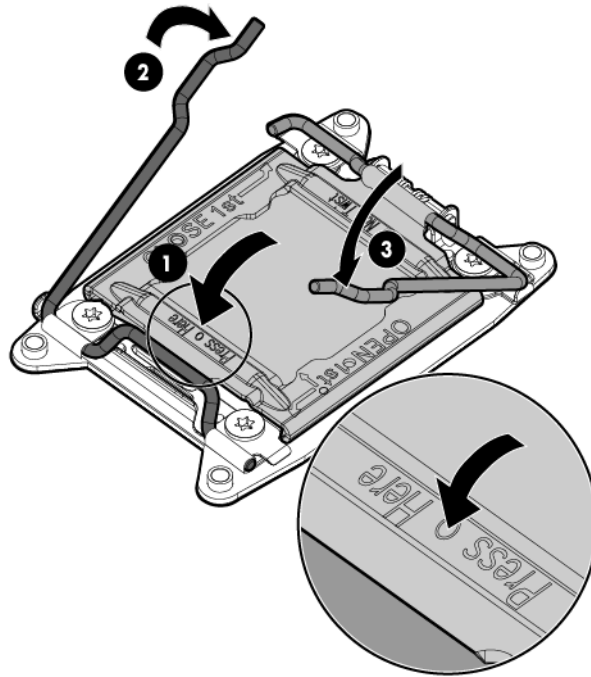


**CAUTION:** THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

11. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.

**CAUTION:** Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

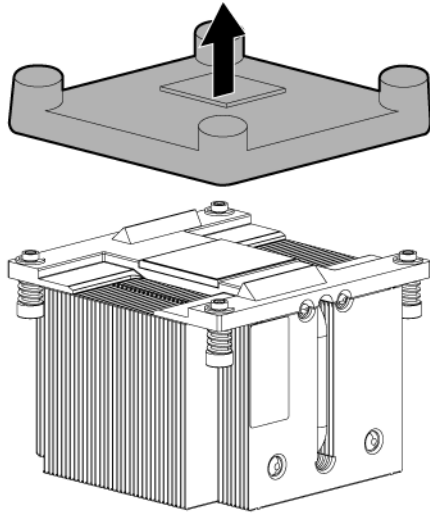
12. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.



- 
- △ **CAUTION:** Close and hold down the processor cover socket while closing the processor locking levers. The levers should close without resistance. Forcing the levers closed can damage the processor and socket, requiring system board replacement.
- 
- △ **CAUTION:** The pins on the processor socket are very fragile. Any damage to them may require replacing the system board.
- 
- △ **CAUTION:** Failure to completely open the processor locking lever prevents the processor from seating during installation, leading to hardware damage.
- 

13. Remove the thermal interface protective cover from the heatsink.

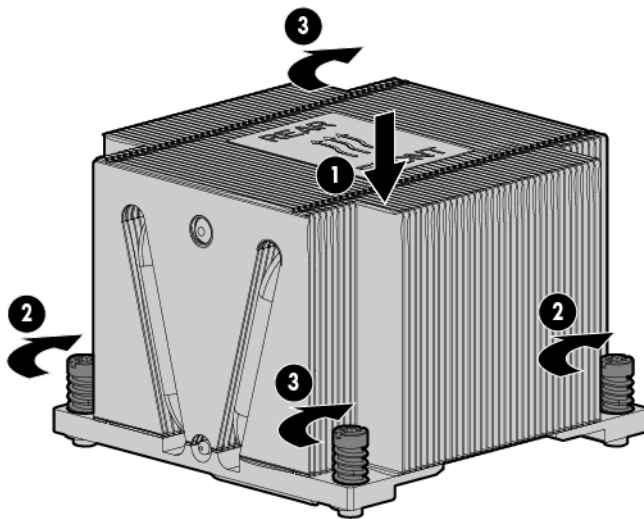
- △ **CAUTION:** After the cover is removed, do not touch the thermal interface media.
-



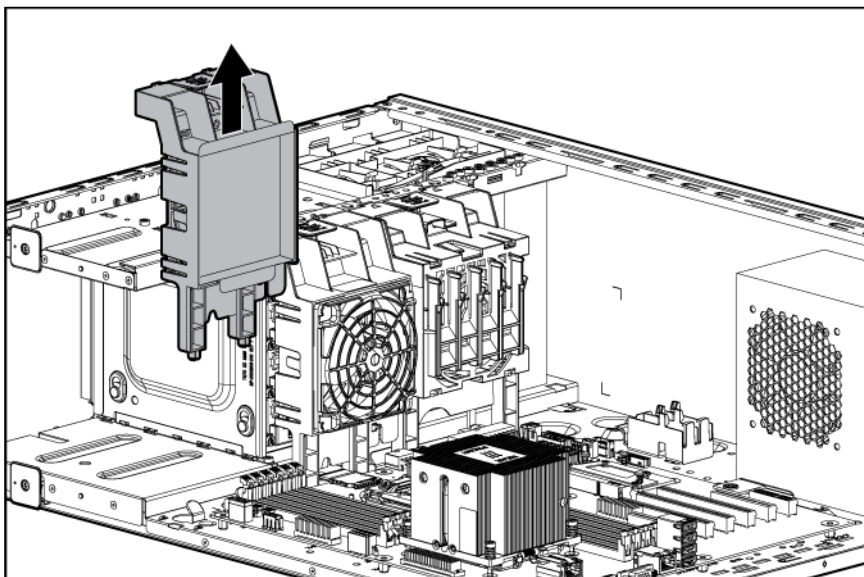
14. Install the heatsink:

- a. Position the heatsink on the processor backplate.
- b. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.
- c. Finish the installation by completely tightening the screws in the same sequence.

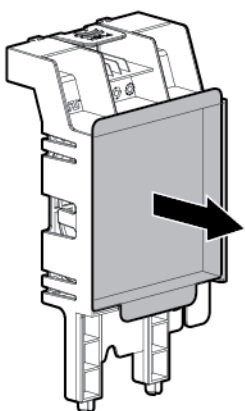
△ **CAUTION:** Heatsink retaining screws should be tightened or loosened in diagonally opposite pairs (in an "X" pattern). Do not overtighten the screws as this can damage the board, connectors, or screws. Use the wrench supplied with the system to reduce the possibility of overtightening the screws.



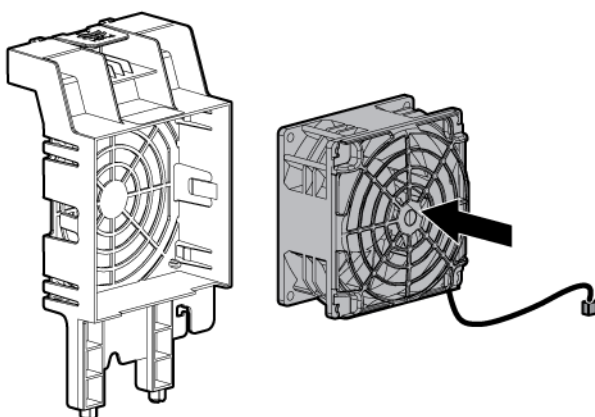
15. Remove the fan blank from fan location 3.



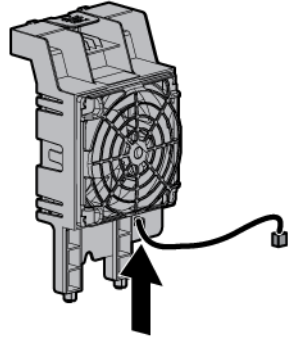
16. Remove the mylar cover from the fan blank.



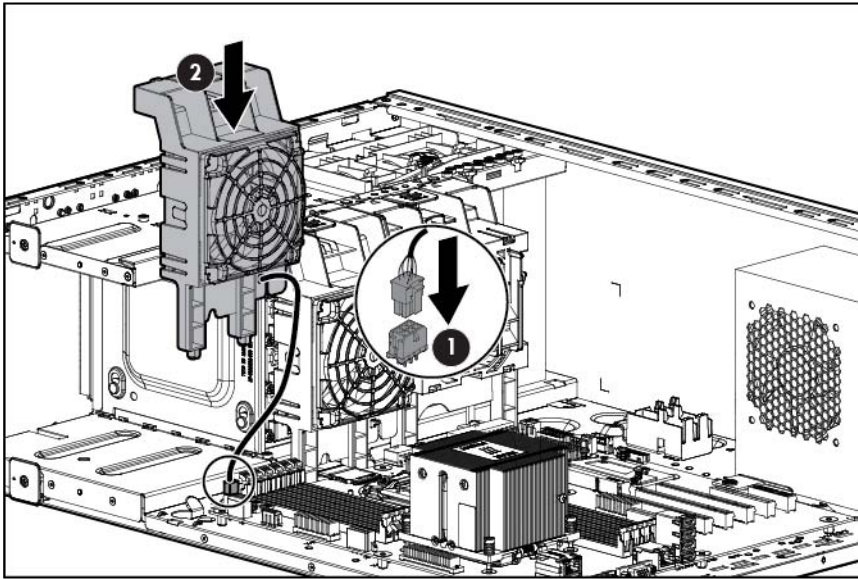
17. Install the fan into the blank.



18. Route the fan cable through the cable slot.



19. Connect the fan cable to the system board, and then insert the fan.



20. Install the system air baffle (on page 28).
21. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).
22. Install the access panel (on page 26).
23. Return the server to an upright position.
24. Lock the front bezel (on page 24).
25. Connect each power cord to the server.
26. Connect each power cord to the power source.
27. Power up the server (on page 23).

## Memory options



**IMPORTANT:** This server does not support mixing LRDIMMs, RDIMMs, or UDIMMs. Attempting to mix any combination of these DIMMs can cause the server to halt during BIOS initialization.

The memory subsystem in this server can support RDIMMs or UDIMMs:

- UDIMMs represent the most basic type of memory module and offer lower latency in one DIMM per channel configurations and relatively low power consumption, but are limited in capacity.
- RDIMMs offer larger capacities than UDIMMs and include address parity protection.

When information applies to all types of memory, the memory are referred to as DIMMs. When memory is specified as RDIMM or UDIMM, the information applies to only that type of memory. All memory installed in the server must be the same type.

The server supports the following DIMM speeds:

- Single-rank and dual-rank PC3-10600 (DDR3-1333) RDIMMs operating at up to 1333 MT/s
- Single-rank and dual-rank PC3-12800 (DDR3-1600) RDIMMs operating at up to 1600 MT/s
- Single-rank and dual-rank PC3-10600 (DDR3-1333) UDIMMs operating at up to 1333 MT/s
- Single-rank and dual-rank PC3-12800 (DDR3-1600) UDIMMs operating at up to 1600 MT/s

### Speed, voltage, and capacity

DIMM type	DIMM rank	DIMM capacity	Native speed (MT/s)	Voltage
RDIMM	Dual	8 GB/16 GB	1333/1600	LV/STD
RDIMM	Single	4 GB/8 GB	1333/1600	LV/STD
UDIMM	Dual	4 GB/8 GB	1333/1600	LV/STD
UDIMM	Single	2 GB	1333/1600	LV/STD

Depending on the processor model, the number of DIMMs installed, and whether UDIMMs or RDIMMs are installed, the memory clock speed can be reduced to 1333 or 1066 MT/s. Clock speed can also be reduced when using low voltage DIMMs.

### Populated DIMM speed (MT/s)

DIMM type	1 DIMM per channel	1 DIMM per channel	2 DIMMs per channel	2 DIMMs per channel
—	<b>1.35V</b>	<b>1.5V</b>	<b>1.35V</b>	<b>1.5V</b>
RDIMM	DDR3-1333	DDR3-1600	DDR3-1333	DDR3-1600
UDIMM	DDR3-1333	DDR3-1600*	DDR3-1333**	DDR3-1600***

\* UDIMM is supported at 1DPC at 1600 MT/s at 1.5V using HP SmartMemory only. Third-party memory supports 1DPC at 1333 MT/s at 1.5V.

\*\* UDIMM is supported at 2DPC at 1333 MT/s at 1.35V using HP SmartMemory only. Third-party memory supports 2DPC at 1066 MT/s at 1.35V.

\*\*\* UDIMM is supported at 2DPC at 1600 MT/s at 1.5V using HP SmartMemory only. Third-party memory supports 2DPC at 1066 MT/s at 1.5V.

## HP SmartMemory

HP SmartMemory, introduced for Gen8 servers, authenticates and unlocks certain features available only on HP Qualified memory and verifies whether installed memory has passed HP qualification and test processes. Qualified memory is performance-tuned for HP ProLiant and BladeSystem servers and provides future enhanced support through HP Active Health and manageability software.

Certain performance features are unique with HP SmartMemory. HP SmartMemory 1.35V DDR3-1333 Registered memory is engineered to achieve the same performance level as 1.5V memory. For example, while the industry supports DDR3-1333 RDIMM at 1.5V, the ML350e server supports DDR3-1333 RDIMM up to 2 DIMMs per channel at 1333 MT/s running at 1.35V. This equates to up to 20% less power at the DIMM

level with no performance penalty. In addition, the industry supports UDIMM at 2 DIMMs per channel at 1066 MT/s. HP SmartMemory supports 2 DIMMs per channel at 1333 MT/s at 1.35V, or 25% greater bandwidth, and supports 2 DIMMs per channel at 1600 MT/s at 1.5V, or 50% greater bandwidth.

## Memory subsystem architecture

The memory subsystem in this server is divided into channels. Each processor supports three channels, and each channel supports two DIMM slots.

-	Memory subsystem channel (Processor 2)	Population order	Slot number (Processor 2)	-	Memory subsystem channel (Processor 1)	Population order	Slot number (Processor 1)
Processor 2	1	A D	1 2	Processor 1	3	F C	1 2
Processor 2	2	B E	3 4	Processor 1	2	E B	3 4
Processor 2	3	C F	5 6	Processor 1	1	D A	5 6

For the location of the slot numbers, see "DIMM slots ("[DIMM slot locations](#)" on page 14)."

This multi-channel architecture provides enhanced performance in Advanced ECC mode. This architecture also enables Lockstep and Online Spare Memory modes.

DIMM slots in this server are identified by number and by letter. Letters identify the population order. Slot numbers indicate the DIMM slot ID for spare replacement.

## Single-rank, dual-rank, and quad-rank DIMMs

To understand and configure memory protection modes properly, an understanding of single-, dual-, and quad-rank DIMMs is helpful. Some DIMM configuration requirements are based on these classifications.

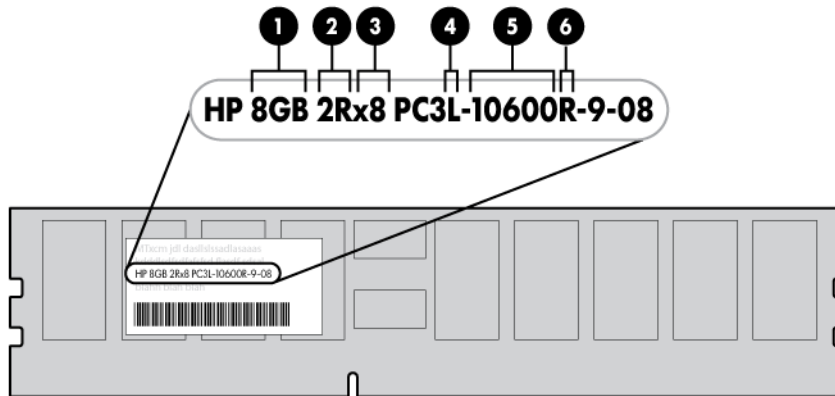
A single-rank DIMM has one set of memory chips that is accessed while writing to or reading from the memory. A dual-rank DIMM is similar to having two single-rank DIMMs on the same module, with only one rank accessible at a time. A quad-rank DIMM is, effectively, two dual-rank DIMMs on the same module. Only one rank is accessible at a time. The server memory control subsystem selects the proper rank within the DIMM when writing to or reading from the DIMM.

Dual- and quad-rank DIMMs provide the greatest capacity with the existing memory technology. For example, if current DRAM technology supports 8-GB single-rank DIMMs, a dual-rank DIMM would be 16 GB, and a quad-rank DIMM would be 32 GB.

LRDIMMs are labeled as quad-rank DIMMs; however, they function more like dual-rank DIMMs. There are four ranks of DRAM on the DIMM, but the LRDIMM buffer creates an abstraction that allows the DIMM to appear as a dual-rank DIMM to the system. The LRDIMM buffer also isolates the electrical loading of the DRAM from the system to allow for faster operation. These two changes allow the system to support up to three LRDIMMs per memory channel, providing for up to 50% greater memory capacity and higher memory operating speed compared to quad-rank RDIMMs.

## DIMM identification

To determine DIMM characteristics, use the label attached to the DIMM and the following illustration and table.



Item	Description	Definition
1	Size	—
2	Rank	1R = Single-rank 2R = Dual-rank 3R = Three-rank 4R = Quad-rank
3	Data width	x4 = 4-bit x8 = 8-bit
4	Voltage rating	L = Low voltage (1.35V) U = Ultra low voltage (1.25V) Blank or omitted = Standard
5	Memory speed	12800 = 1600-MT/s 10600 = 1333-MT/s 8500 = 1066-MT/s
6	DIMM type	R = RDIMM (registered) E = UDIMM (unbuffered with ECC) L = LRDIMM (load reduced)

For the latest supported memory information, see the QuickSpecs on the HP website (<http://h18000.www1.hp.com/products/quickspecs/ProductBulletin.html>). At the website, choose the geographic region, and then locate the product by name or product category.

## Memory configurations

To optimize server availability, the server supports the following AMP modes:

- Advanced ECC—Provides up to 4-bit error correction and enhanced performance over Lockstep mode. This mode is the default option for this server.



- Online spare memory—Provides protection against failing or degraded DIMMs. Certain memory is reserved as spare, and automatic failover to spare memory occurs when the system detects a DIMM that is degrading. This feature enables DIMMs that have a higher probability of receiving an uncorrectable memory error (which would result in system downtime) to be removed from operation.

Advanced Memory Protection options are configured in RBSU. If the requested AMP mode is not supported by the installed DIMM configuration, the server boots in Advanced ECC mode. For more information, see "HP ROM-Based Setup Utility (on page 97)."

The server also can operate in independent channel mode or combined channel mode (lockstep). When running in lockstep mode, you gain reliability in one of two ways:

- If running with UDIMMs (built with x8 DRAM devices), the system can survive a complete DRAM failure (SDDC). In independent channel mode, this failure would be an uncorrectable error.
- If running with RDIMM (built with x4 DRAM devices), the system can survive the complete failure of two DRAM devices (DDDC). Running in independent mode, the server can only survive the complete failure of a single DRAM device (SDDC).

#### Maximum capacity

DIMM type	DIMM rank	One processor	Two processors
RDIMM	Single-rank	48 GB	96 GB
RDIMM	Dual-rank	96 GB	192 GB
UDIMM	Single-rank	24 GB	48 GB
UDIMM	Dual-rank	48 GB	96 GB

For the latest memory configuration information, see the QuickSpecs on the HP website (<http://www.hp.com>).

## General DIMM slot population guidelines

Observe the following guidelines for all AMP modes:

- Install DIMMs only if the corresponding processor is installed.
- When two processors are installed, balance the DIMMs across the two processors.
- White DIMM slots denote the first slot of a channel (Ch 1-A, Ch 2-B, Ch 3-C).
- Do not mix UDIMMs or RDIMMs.
- When two processors are installed, install the DIMMs in sequential alphabetical order balanced between the two processors: P1-A, P2-A, P1-B, P2-B, P1-C, P2-C, and so on.

For detailed memory configuration rules and guidelines, use the Online DDR3 Memory Configuration Tool on the HP website (<http://www.hp.com/go/ddr3memory-configurator>).

## Advanced ECC memory configuration

Advanced ECC memory is the default memory protection mode for this server. Standard ECC can correct single-bit memory errors and detect multi-bit memory errors. When multi-bit errors are detected using Standard ECC, the error is signaled to the server and causes the server to halt.

Advanced ECC protects the server against some multi-bit memory errors. Advanced ECC can correct both single-bit memory errors and 4-bit memory errors if all failed bits are on the same DRAM device on the DIMM.

Advanced ECC provides additional protection over Standard ECC because it is possible to correct certain memory errors that would otherwise be uncorrected and result in a server failure. Using HP Advanced Memory Error Detection technology, the server provides notification when a DIMM is degrading and has a higher probability of uncorrectable memory error.

## Online Spare memory configuration

Online spare memory provides protection against degraded DIMMs by reducing the likelihood of uncorrected memory errors. This protection is available without any operating system support.

Online spare memory protection dedicates one rank of each memory channel for use as spare memory. The remaining ranks are available for OS and application use. If correctable memory errors occur at a rate higher than a specific threshold on any of the non-spare ranks, the server automatically copies the memory contents of the degraded rank to the online spare rank. The server then deactivates the failing rank and automatically switches over to the online spare rank.

## Lockstep memory configuration

Lockstep mode provides protection against multi-bit memory errors that occur on the same DRAM device. Lockstep mode can correct any single DRAM device failure on x4 and x8 DIMM types. The DIMMs in each channel must have identical HP part numbers.

## Advanced ECC population guidelines

For Advanced ECC mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines.
- DIMMs may be installed individually.

## Online spare population

For Online Spare memory mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines.
- Each channel must have a valid online spare configuration.
- Each channel can have a different valid online spare configuration.
- Each populated channel must have a spare rank:
  - A single dual-rank DIMM is not a valid configuration.
  - LRDIMMs are treated as dual-rank DIMMs.

## Lockstep Memory population guidelines

For Lockstep memory mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines.
- DIMM configuration on all channels of a processor must be identical.
- In multi-processor configurations, each processor must have a valid Lockstep Memory configuration.

- In multi-processor configurations, each processor may have a different valid Lockstep Memory configuration.

## Population order

For memory configurations with a single processor or multiple processors, populate the DIMM slots in the following order:

- RDIMM: Sequentially in alphabetical order (A through F)
- UDIMM: A through F, sequentially in alphabetical order

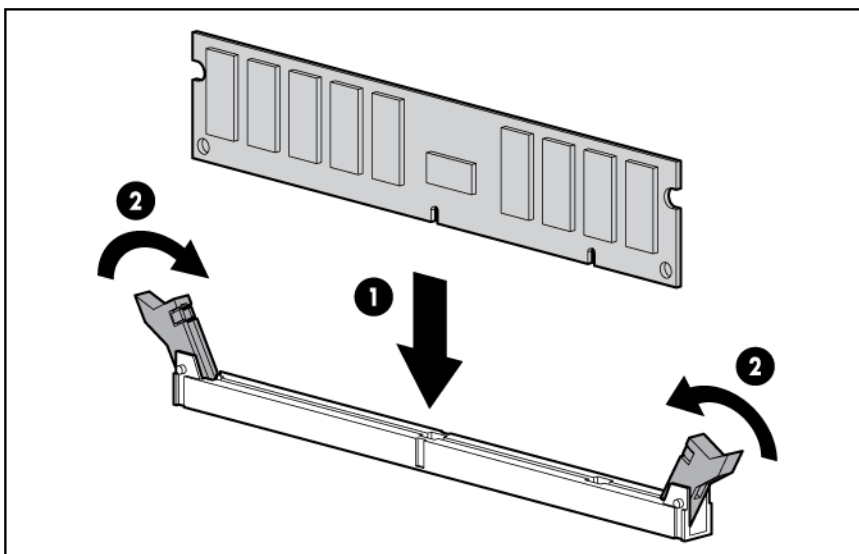
After installing the DIMMs, use RBSU to configure Advanced ECC, online spare, or lockstep memory support.

## Installing a DIMM

**⚠ CAUTION:** To avoid damage to the hard drives, memory, and other system components, the air baffle, drive blanks, and access panel must be installed when the server is powered up.

To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Open the DIMM slot latches.
9. Install the DIMM.



10. Install the system air baffle (on page 28).
11. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).
12. Install the access panel (on page 26).
13. Return the server to an upright position.
14. Lock the front bezel (on page 24).
15. Connect each power cord to the server.
16. Connect each power cord to the power source.
17. Power up the server (on page 23).

## Drive options

When adding drives to the server, observe the following general guidelines:

- The system automatically sets all device numbers.
- If only one drive is used, install it in the bay with the lowest device number ("SAS and SATA device numbers" on page 15).

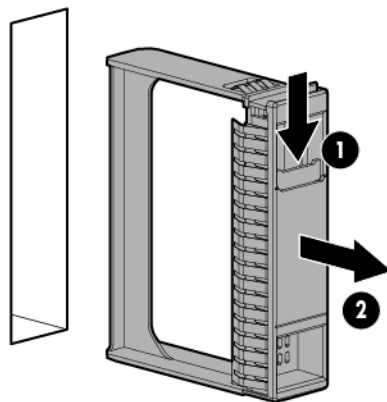
Drives must be the same capacity to provide the greatest storage space efficiency when drives are grouped together into the same drive array.

## Installing a hot-plug drive

**CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

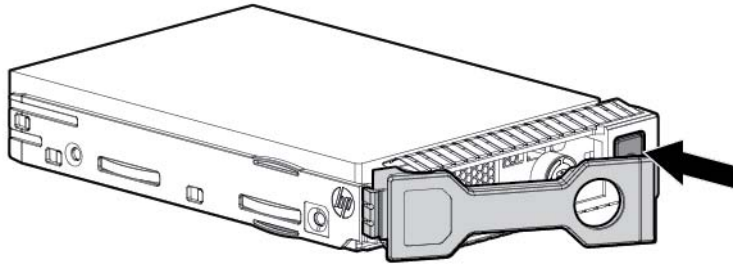
To install the component:

1. Remove the front bezel (on page 24).
2. Remove the drive blank.

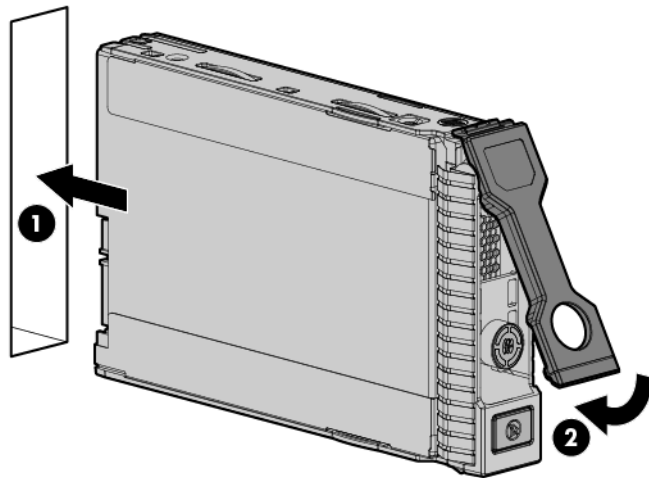


3. Retain the blank for future use.

4. Prepare the drive.



5. Install the drive.



6. Determine the status of the drive from the drive LED definitions ("[Hot-plug drive LED definitions](#)" on page 20).
7. Install the front bezel (on page 25).

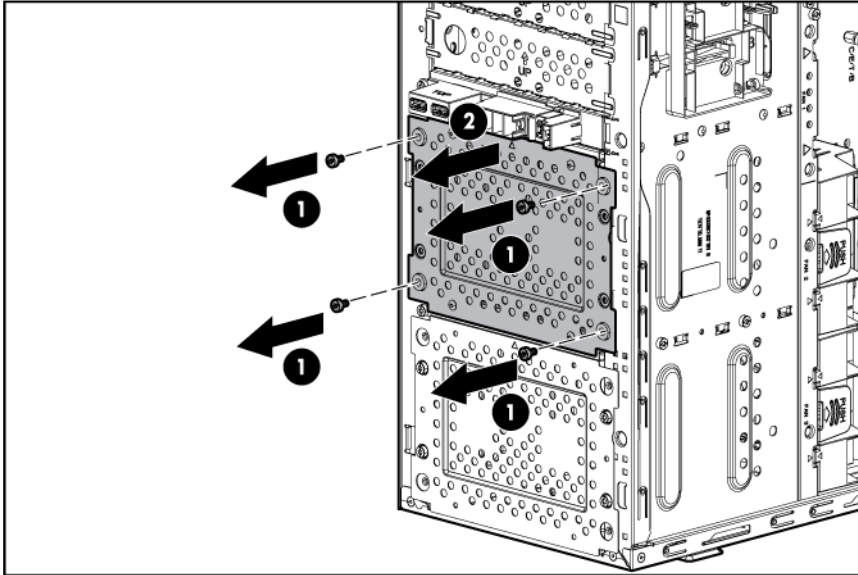
## Installing a non-hot-plug drive

**CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

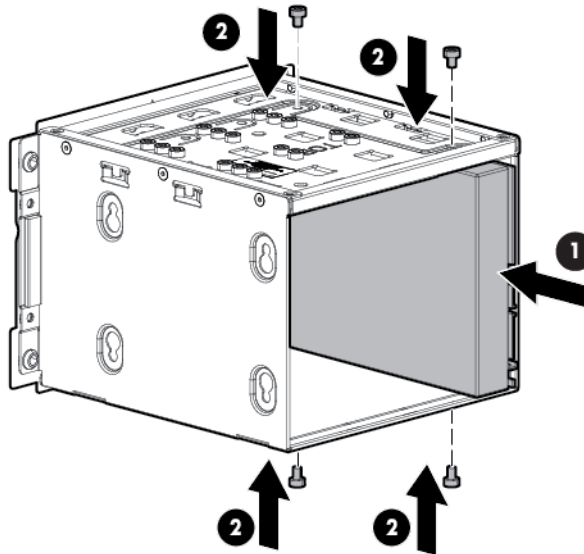
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Remove the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).

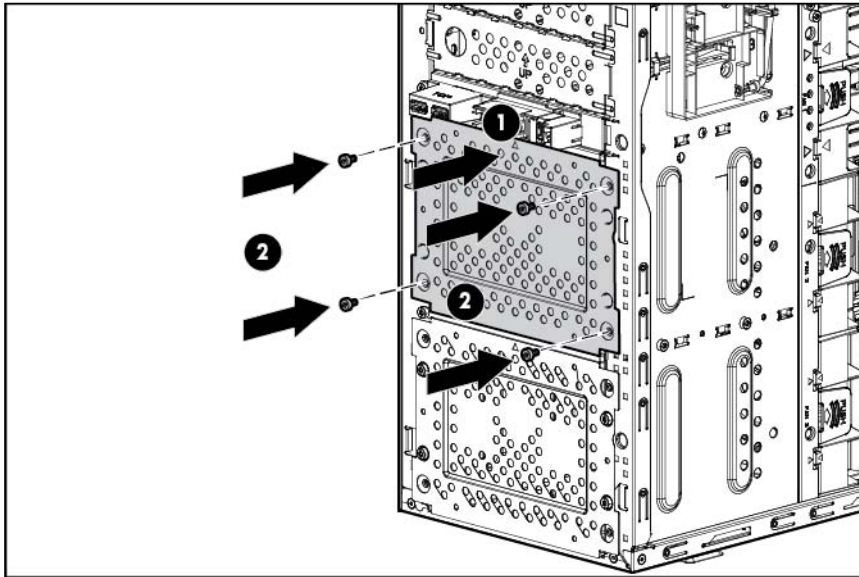
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove any installed full-length PCI expansion cards ("Remove the full-length expansion board" on page 29).
9. Remove the fan modules and the fan blank (on page 30).
10. If already installed, disconnect the drive cables from the rear of the drives.
11. Remove the non-hot-plug drive cage from chassis.



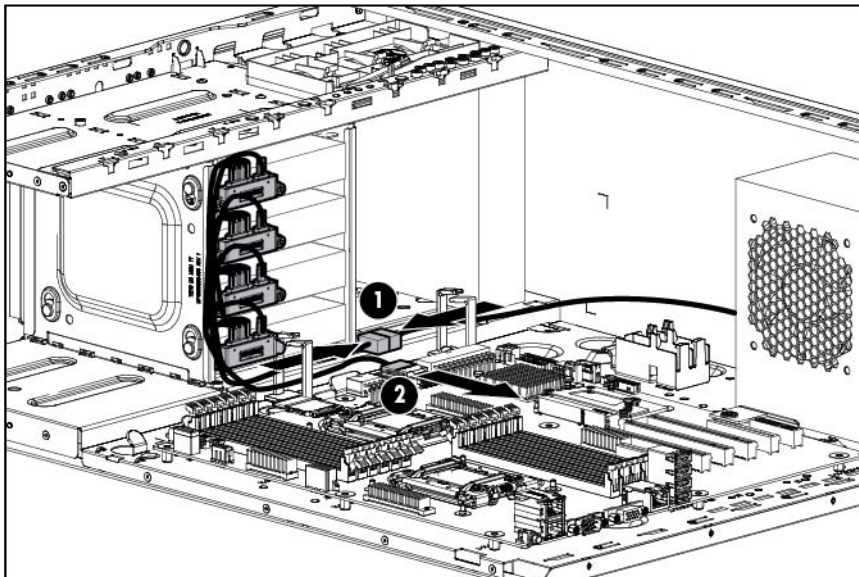
12. Use the screws on the drive cage to install the drives.
13. Install the drive into the non-hot-plug drive cage.



14. Install the drive cage into the chassis.



15. Connect all the drive cables.

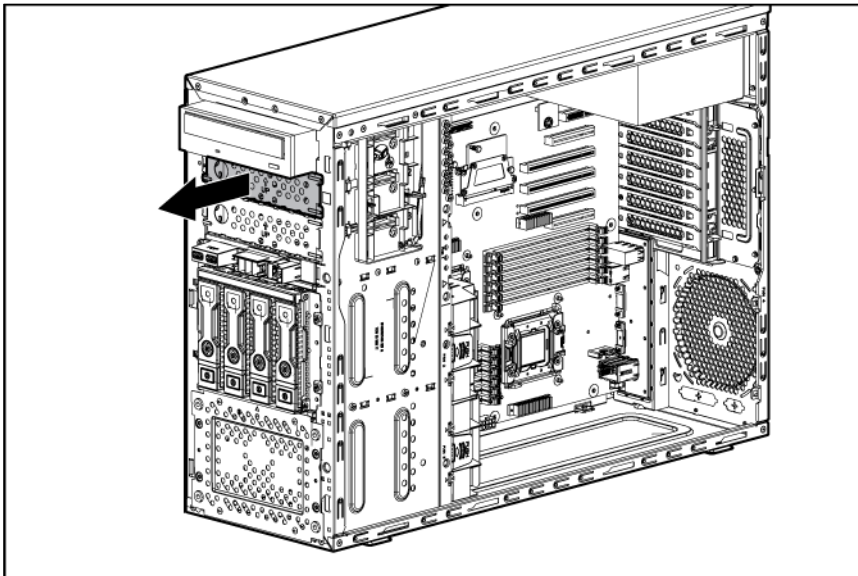


16. Install the fan modules and the fan blank (on page 31).
17. Install the full-length PCI expansion cards that were removed ("[Installing an expansion board](#)" on page 63).
18. Install the system air baffle (on page 28).
19. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page 38).
20. Install the access panel (on page 26).
21. Return the server to an upright position.
22. Install the front bezel (on page 25).
23. Connect each power cord to the server.
24. Connect each power cord to the power source.
25. Power up the server (on page 23).

# Optical drive option

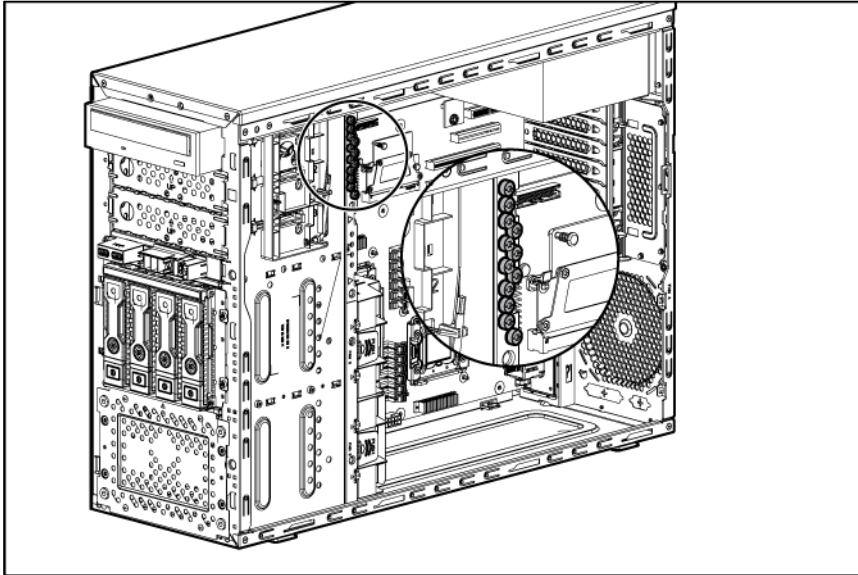
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Remove the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove any installed full-length PCI expansion cards ("Remove the full-length expansion board" on page 29).
9. If installed, remove the RPS rear blank.
10. Remove fan 1 ("Remove the fan modules and the fan blank" on page 30).
11. Remove the optical drive blank, and retain it for future use.

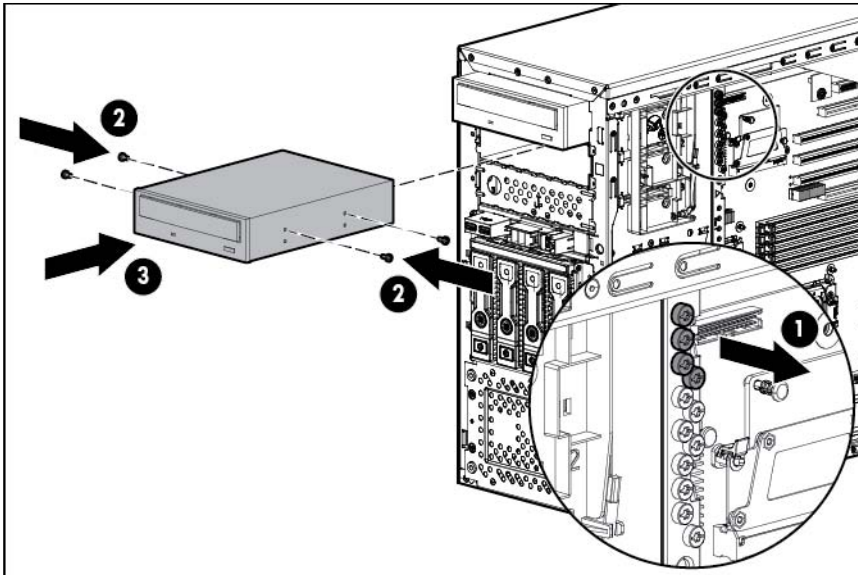




12. Locate the four guide screws for the optical drive on the chassis.

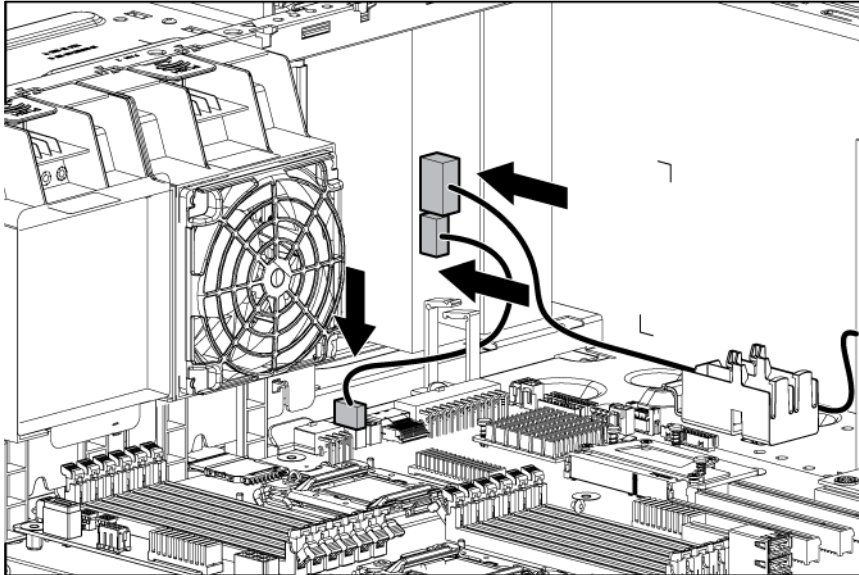


13. Install the optical drive:
- a. Install the guide screws from the chassis to the optical drive.
  - b. Install the optical drive. When fully inserted, the assembly locking latch clicks.



14. Connect the drive cables:
- a. Connect the power cable to the drive.
  - b. Connect one end of the SATA cable to the drive and the other end to the system board.

For cable routing information, see "Optical drive cabling (on page 89)."



15. Install fan1 ("Install the fan modules and the fan blank" on page 31).
16. If removed, install the RPS rear blank.
17. Install the full-length PCI expansion cards that were removed ("Installing an expansion board" on page 63).
18. Install the system air baffle (on page 28).
19. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).
20. Install the access panel (on page 26).
21. Return the server to an upright position.
22. Install the front bezel (on page 25).
23. Connect each power cord to the server.
24. Connect each power cord to the power source.
25. Power up the server (on page 23).


## FBWC options

The server supports FBWC options:


FBWC consists of a cache module and a capacitor pack. The DDR cache module buffers and stores data being written by the controller. When the system is powered on, the capacitor pack charges fully in about 5 minutes. In the event of a system power failure, a fully charged capacitor pack provides power for up to 80 seconds. During that interval, the controller transfers the cached data from DDR memory to flash memory, where the data remains indefinitely or until a controller retrieves the data.

- △ **CAUTION:** The cache module connector does not use the industry-standard DDR3 mini-DIMMs. Do not use the controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.


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 **CAUTION:** To prevent a server malfunction or damage to the equipment, do not add or remove the battery pack while an array capacity expansion, RAID level migration, or stripe size migration is in progress.

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 **CAUTION:** After the server is powered down, wait 15 seconds and then check the amber LED before unplugging the cable from the cache module. If the amber LED blinks after 15 seconds, do not remove the cable from the cache module. The cache module is backing up data, and data is lost if the cable is detached.

---


 **IMPORTANT:** The battery pack might have a low charge when installed. In this case, a POST error message is displayed when the server is powered up, indicating that the battery pack is temporarily disabled. No action is necessary on your part. The internal circuitry automatically recharges the batteries and enables the battery pack. This process might take up to four hours. During this time, the cache module functions properly, but without the performance advantage of the battery pack.

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**NOTE:** The data protection and the time limit also apply if a power outage occurs. When power is restored to the system, an initialization process writes the preserved data to the hard drives.

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## Installing the FBWC module and capacitor pack(P222 and P430)

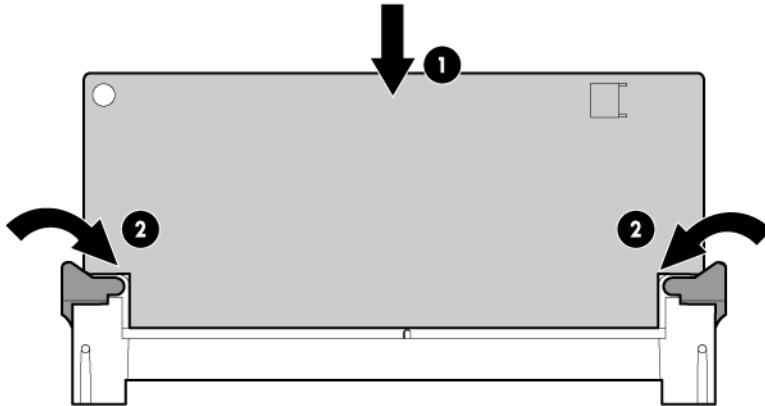
 **CAUTION:** The cache module connector does not use the industry-standard DDR3 mini-DIMMs. Do not use the controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.

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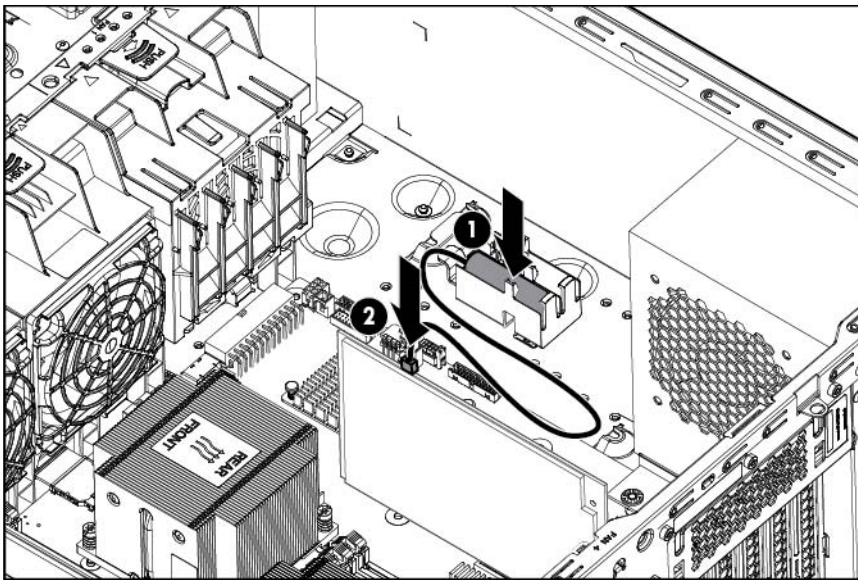
To install the component:

1. Power down the server (on page [23](#)).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page [24](#)).
4. Place the server on its side.
5. Remove the access panel (on page [25](#)).
6. Remove the PCI air baffle (on page [27](#)).

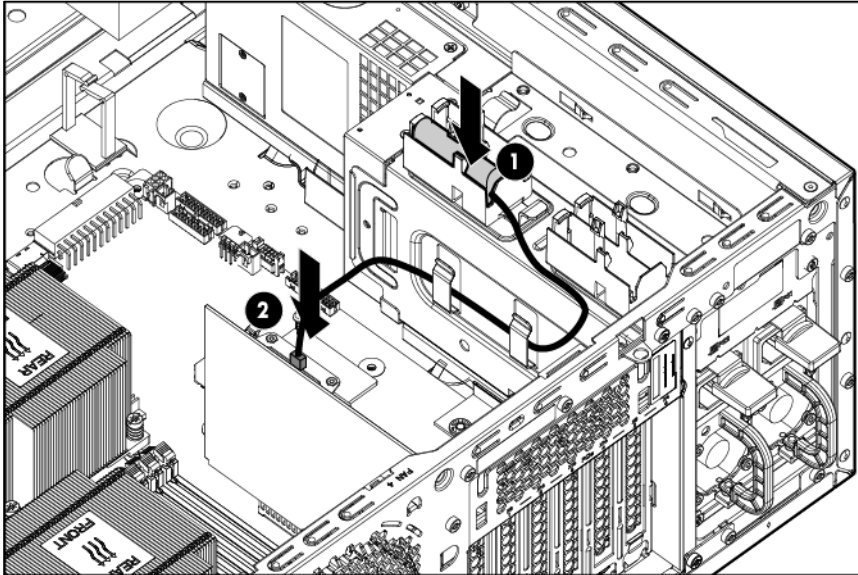
7. Install the FBWC module onto the storage controller.



8. Install the storage controller ("[Installing an expansion board](#)" on page 63), if not already installed.
9. Install the capacitor pack:
  - o For an integrated power supply



- For a redundant power supply



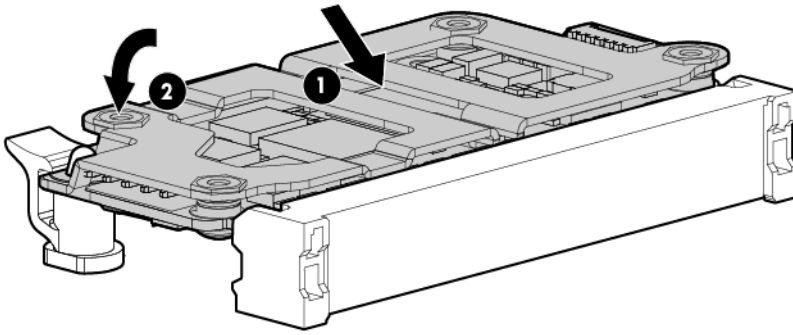
10. Install the PCI air baffle ("[PCI air baffle option](#)" on page [38](#)).
11. Install the access panel (on page [26](#)).
12. Return the server to an upright position.
13. Lock the front bezel (on page [24](#)).
14. Connect each power cord to the server.
15. Connect each power cord to the power source.
16. Power up the server (on page [23](#)).

## Installing the FBWC module and capacitor pack (B120i)


To install the component:

1. Power down the server (on page [23](#)).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page [24](#)).
4. Place the server on its side.
5. Remove the access panel (on page [25](#)).
6. If installed, remove the PCI air baffle (on page [27](#)).
7. Remove any full-length PCI expansion cards installed in PCI slots 3, 4, 5 and 6 ("[Remove the full-length expansion board](#)" on page [29](#)).

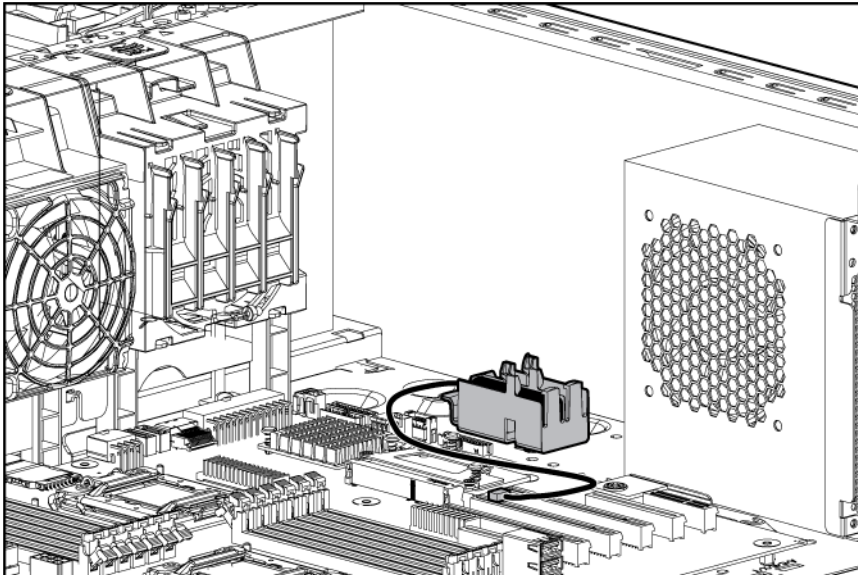
8. Install the FBWC module in the cache module connector on the system board.



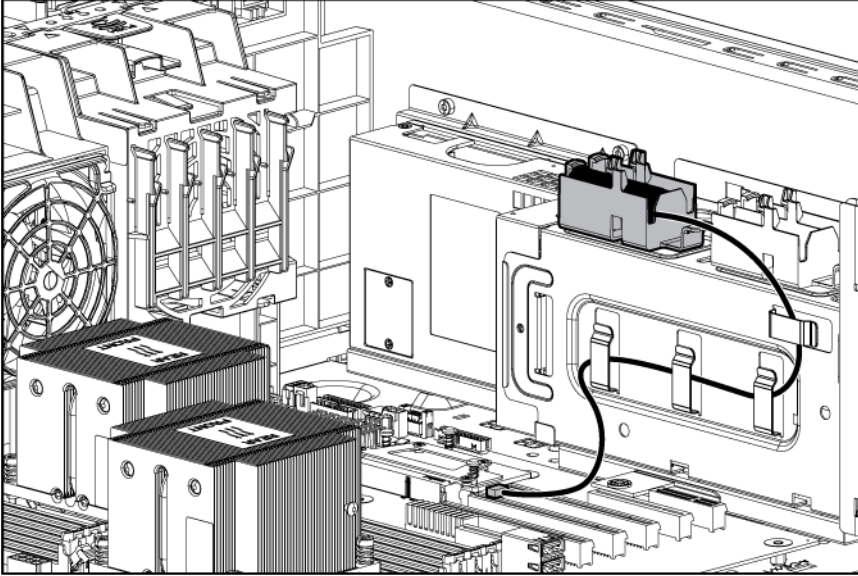
9. Install the FBWC capacitor pack.

 **CAUTION:** When connecting or disconnecting the capacitor pack cable, the connectors on the cache module and cable are susceptible to damage. Avoid excessive force and use caution to avoid damage to these connectors.

- o For an integrated power supply



- For a redundant power supply



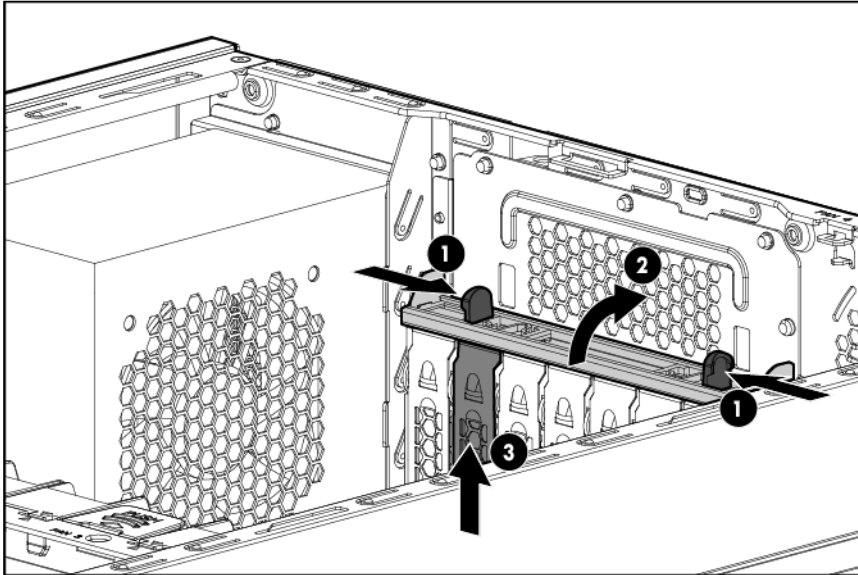
10. Install any full-length PCI expansion cards removed from slots 3, 4, 5 and 6 ("[Installing an expansion board](#)" on page 63).
11. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page 38).
12. Install the access panel (on page 26).
13. Return the server to an upright position.
14. Lock the front bezel (on page 24).
15. Connect each power cord to the server.
16. Connect each power cord to the power source.
17. Power up the server (on page 23).

## Installing an expansion board

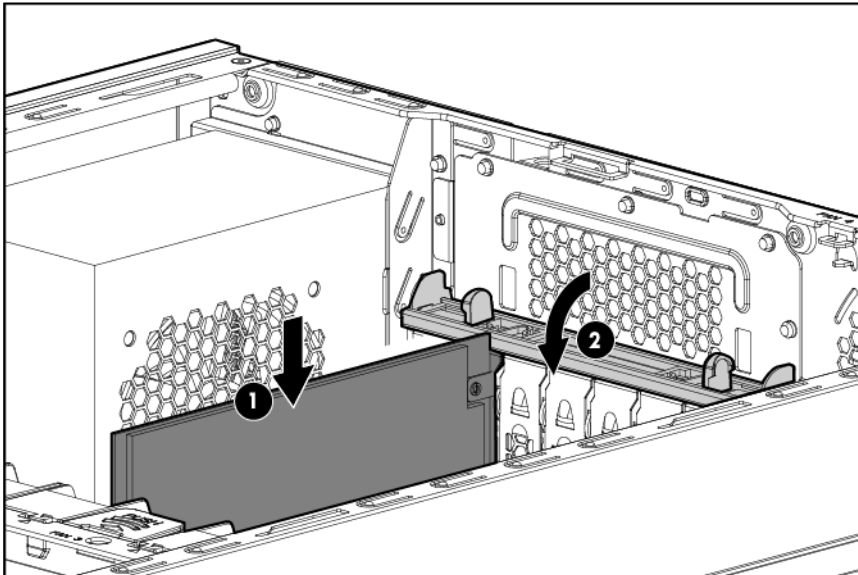
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).

7. Open the retaining bracket and remove the PCI slot cover.



8. Install the expansion board and close the retaining bracket.



9. Connect any required internal or external cables to the expansion board. See the documentation that ships with the expansion board for more information.
10. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page [38](#)).
11. Install the access panel (on page [26](#)).
12. Return the server to an upright position.
13. Lock the front bezel (on page [24](#)).
14. Connect each power cord to the server.
15. Connect each power cord to the power source.
16. Power up the server (on page [23](#)).



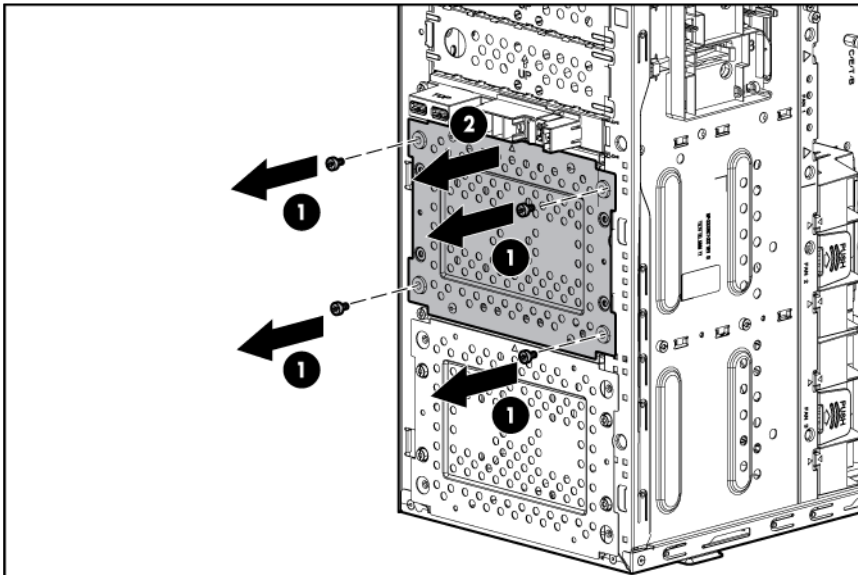
# Eight-bay SFF drive cage option

Install the optional eight-bay SFF drive cage in drive box 1 or box 2.

To install an eight-bay SFF drive cage, an optional Smart Array controller is required. If installing a second eight-bay SFF drive cage option, the redundant power supply is also required. To obtain the options, contact an HP authorized reseller.

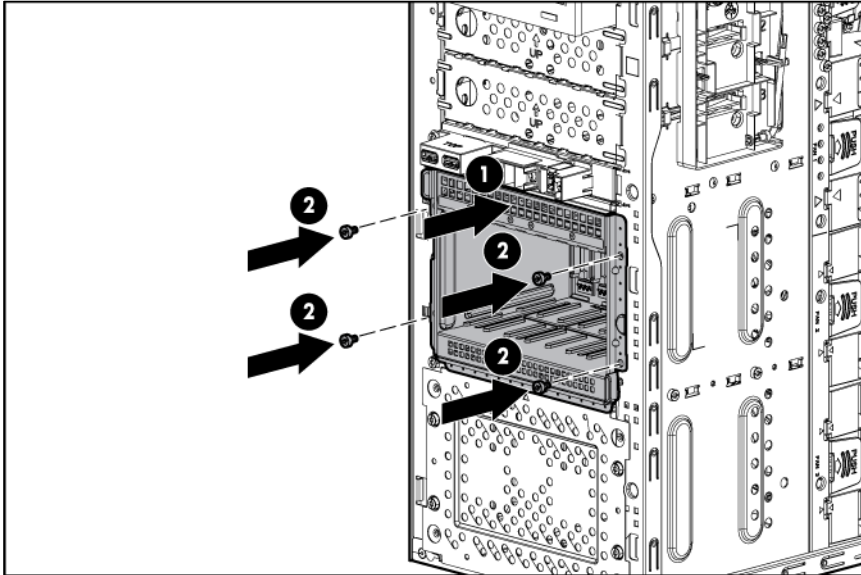
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Remove the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove any installed full-length PCI expansion cards ("Remove the full-length expansion board" on page 29).
9. Remove the fan modules and the fan blank (on page 30).
10. Disconnect the drive cage cables:
  - a. Disconnect the Mini-SAS cable from the system board or from the storage controller option.
  - b. Disconnect the drive power cable from the drive cage power connector.
11. Remove the LFF non-hot-plug drive cage assembly.

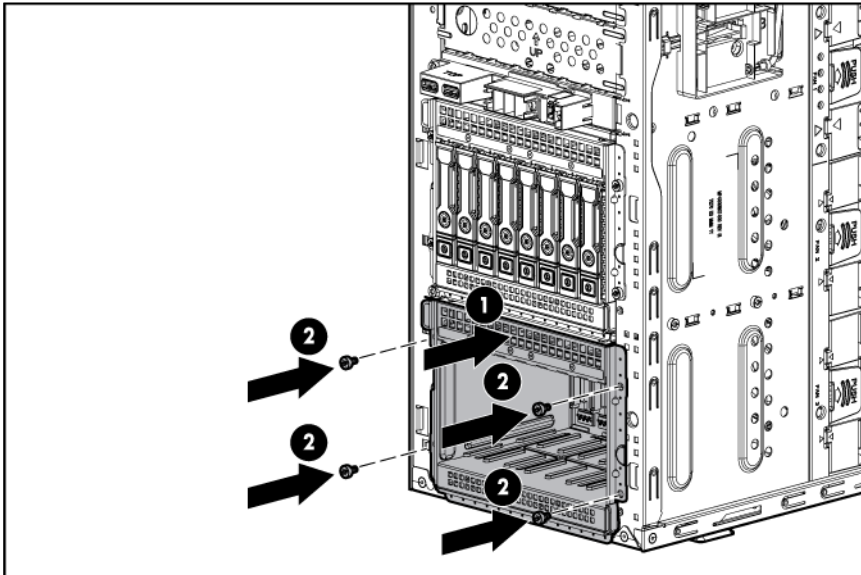


12. Install the SFF hot-plug drive cage assembly:

- Box 1

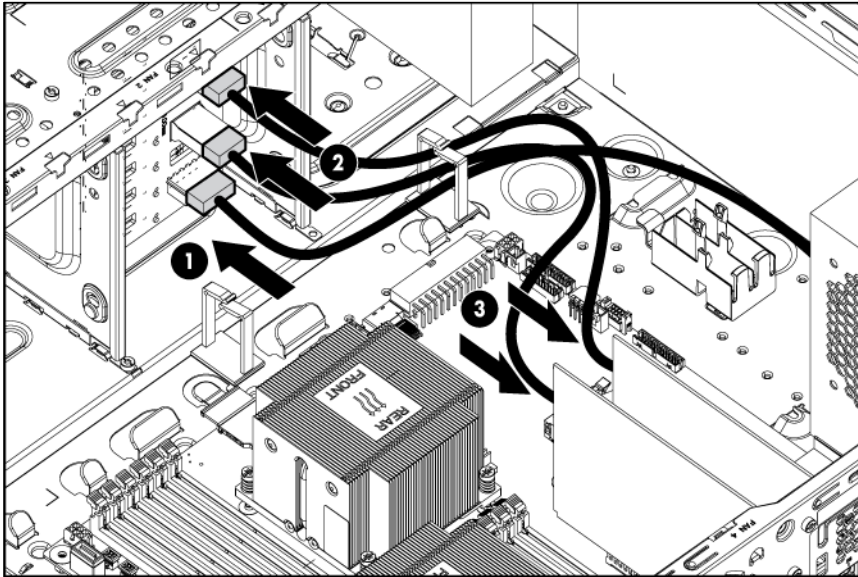


- Box 2



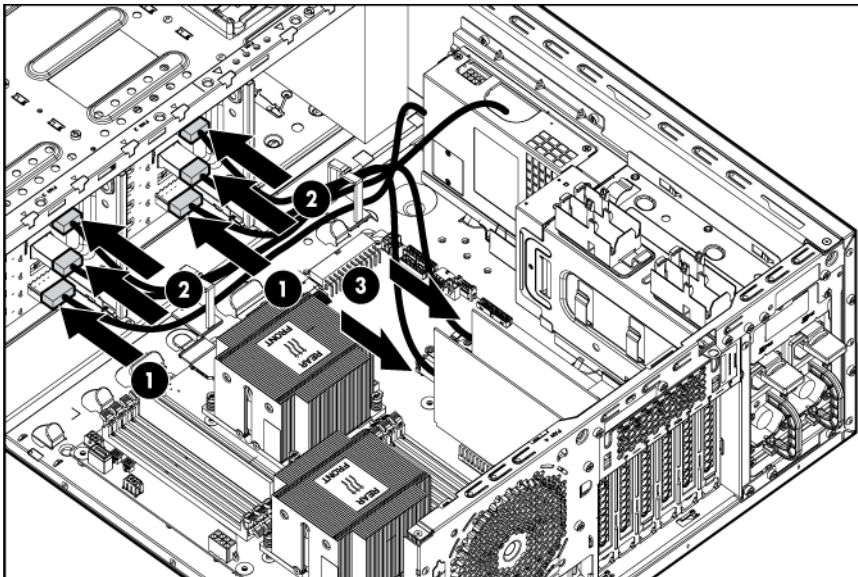
13. Connect the drive cage cables, for box 1:
  - a. Route the drive cage power cable through the cable management clip, and then connect the cable to the drive cage backplane.
  - b. Connect the Mini-SAS cables to the drive cage backplane.

- c. Route the opposite ends of the Mini-SAS cables through the cable management clip, and then connect the cables to the storage controllers.

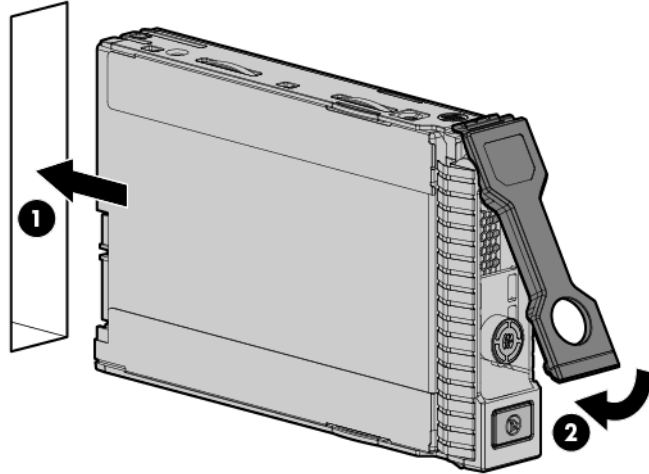


14. If box 2 is installed, connect the drive cage cables for box 1 and box 2:

- a. Route the drive cage power cable through the cable management clip, and then connect the cable to the drive cage backplane.
- b. Connect the Mini-SAS cables to the drive cage backplane.
- c. Route the opposite ends of the Mini-SAS cables through the cable management clip, and then connect the cables to the storage controllers.



15. Install hot-plug drives.



**CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

Populate drive bays based on the drive numbering sequence. Start from the drive bay with the lowest device number. For device numbering information see "SAS and SATA device numbers (on page 15)."

16. Install the fan modules and the fan blank (on page 31).
17. Install any full-length PCI expansion cards that were removed ("Installing an expansion board" on page 63).
18. Install the system air baffle (on page 28).
19. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).
20. Install the access panel (on page 26).
21. Return the server to an upright position.
22. Install the front bezel (on page 25).
23. Connect each power cord to the server.
24. Connect each power cord to the power source.
25. Power up the server (on page 23).

## Four-bay LFF drive cage option

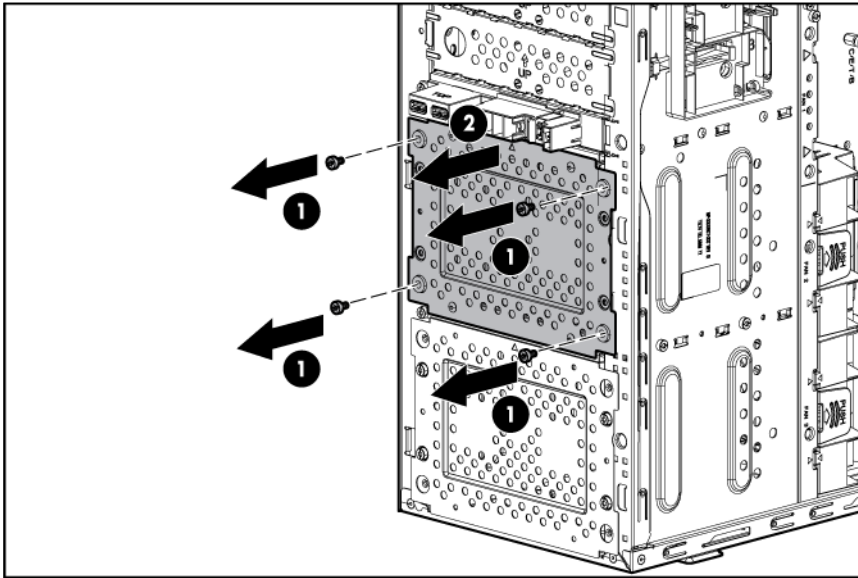
If installing a second four-bay LFF drive cage in the server, a Smart array controller option and redundant power supply option are required.

To obtain the options, contact an HP authorized reseller.

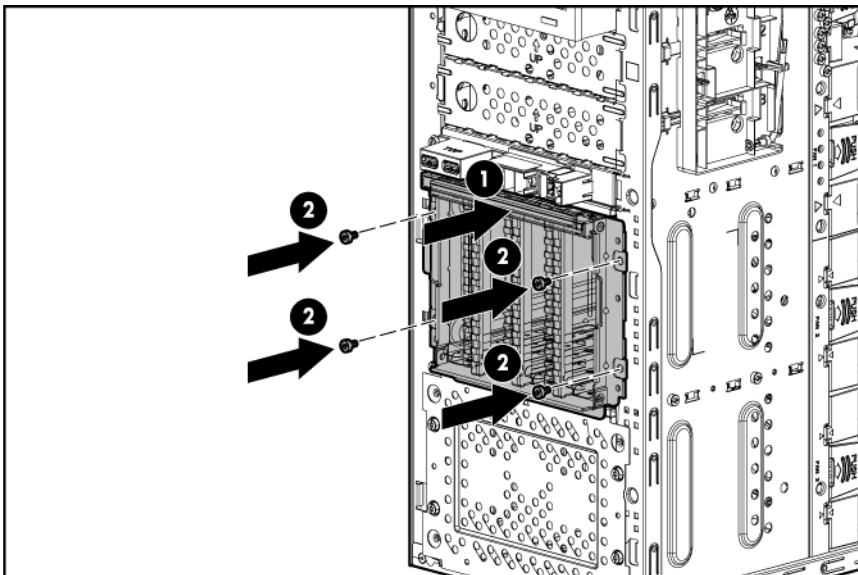
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Remove the front bezel (on page 24).

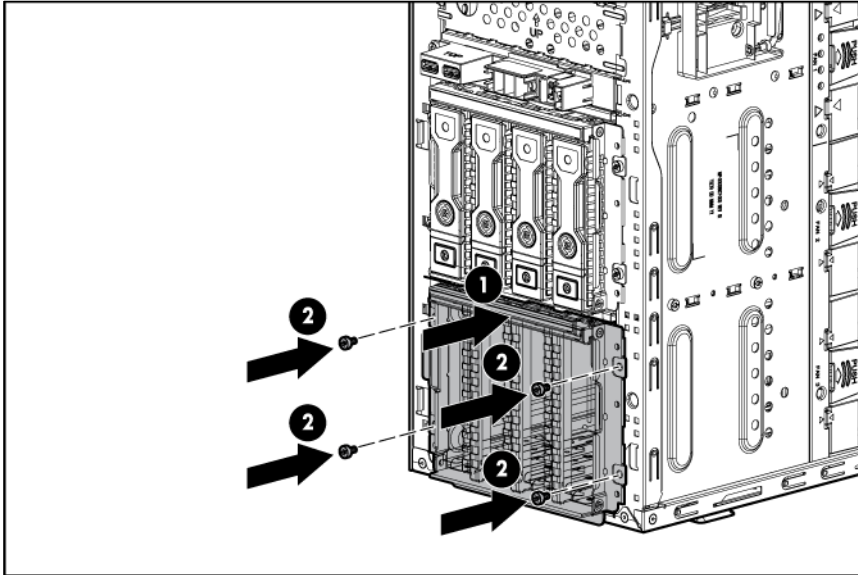
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove any installed full-length PCI expansion cards ("[Remove the full-length expansion board](#)" on page 29).
9. Remove the fan modules and the fan blank (on page 30).
10. Disconnect the drive cage cables:
  - a. Disconnect the Mini-SAS cable from the system board or from the storage controller option.
  - b. Disconnect the drive power cable from the drive power connector.
11. Remove the four-bay LFF non-hot-plug drive cage assembly.



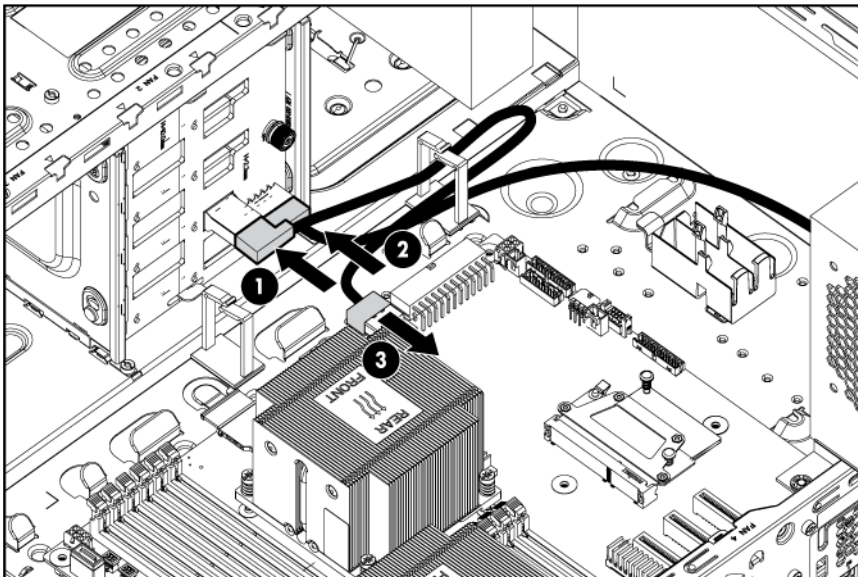
12. Install the LFF hot-plug drive cage assembly.
  - o Box 1



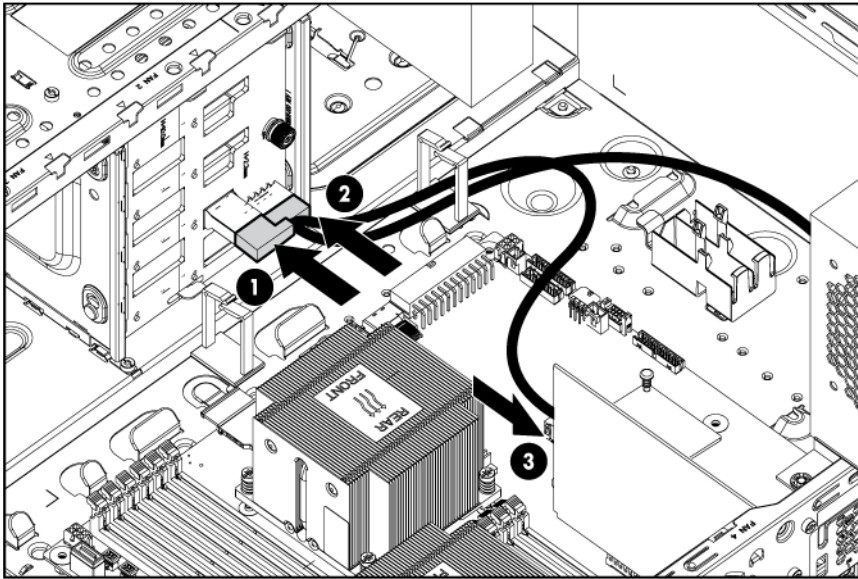
- Box 2



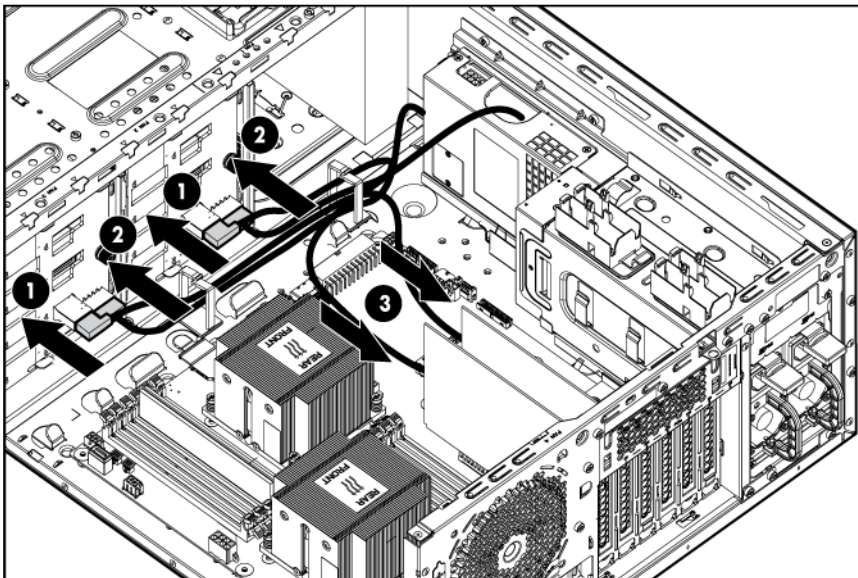
13. Connect the drive cage cables, for box 1:
  - a. Connect the Mini-SAS cable to the drive cage backplane.
  - b. Route the drive cage power cable through the cable management clip, and then connect the cable to the drive cage backplane.
  - c. Do one of the following:
    - Route the opposite end of the Mini-SAS cable through the cable management clip, and then connect the cable to the connector on the system board.



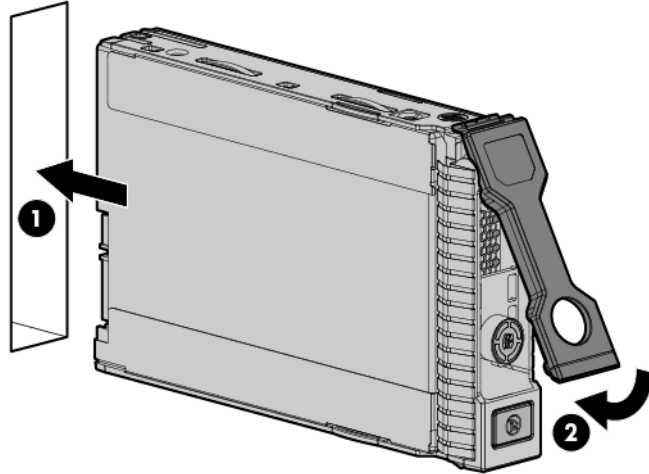
- Route the opposite end of the Mini-SAS cable through the cable management clip, and then connect the cable to the connector on the storage controller.



14. If box 2 is installed, connect the drive cage cables to box 1 and box 2:
- Connect the Mini-SAS cable to the drive cage backplane.
  - Route the drive cage power cable through the cable management clip, and then connect the cable to the drive cage backplane.
  - Route the opposite ends of the Mini-SAS cables through the cable management clip, and then connect the cables to the connector on the storage controllers.



15. Install hot-plug drives.



**CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

Populate drive bays based on the drive numbering sequence. Start from the drive bay with the lowest device number. For device numbering information see "SAS and SATA device numbers (on page 15)."

16. Install the fan modules and the fan blank (on page 31).
17. Install any full-length PCI expansion cards that were removed ("Installing an expansion board" on page 63).
18. Install the system air baffle (on page 28).
19. If removed, install the PCI air baffle ("PCI air baffle option" on page 38).
20. Install the access panel (on page 26).
21. Return the server to an upright position.
22. Install the front bezel (on page 25).
23. Connect each power cord to the server.
24. Connect each power cord to the power source.
25. Power up the server (on page 23).

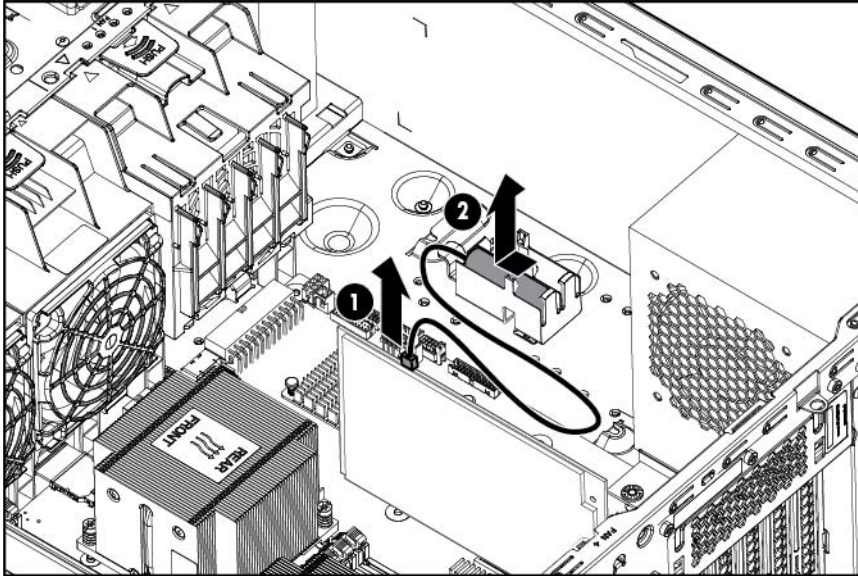
## Redundant hot-plug power supply enablement kit option

To install the component:

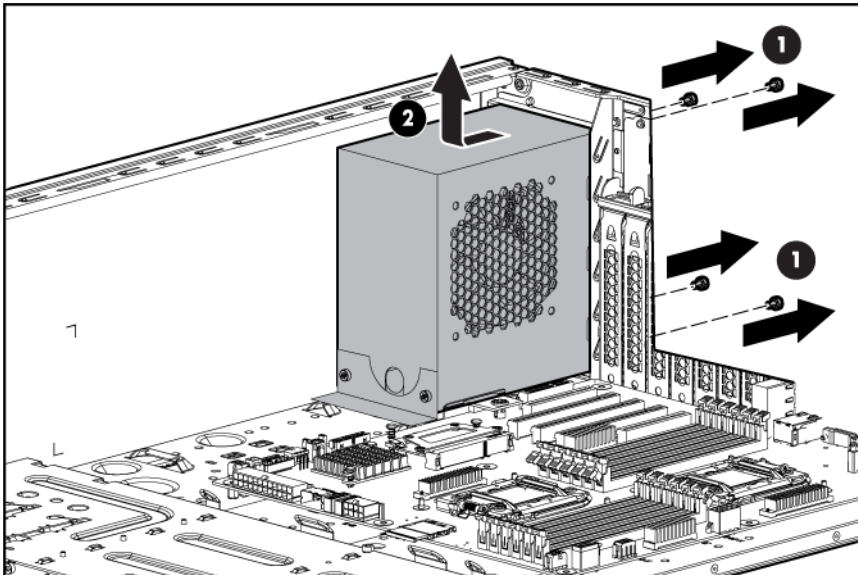
1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.



5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. If a Smart Array controller is installed, disconnect the capacitor pack cable from it, and then remove the capacitor pack holder from the server.

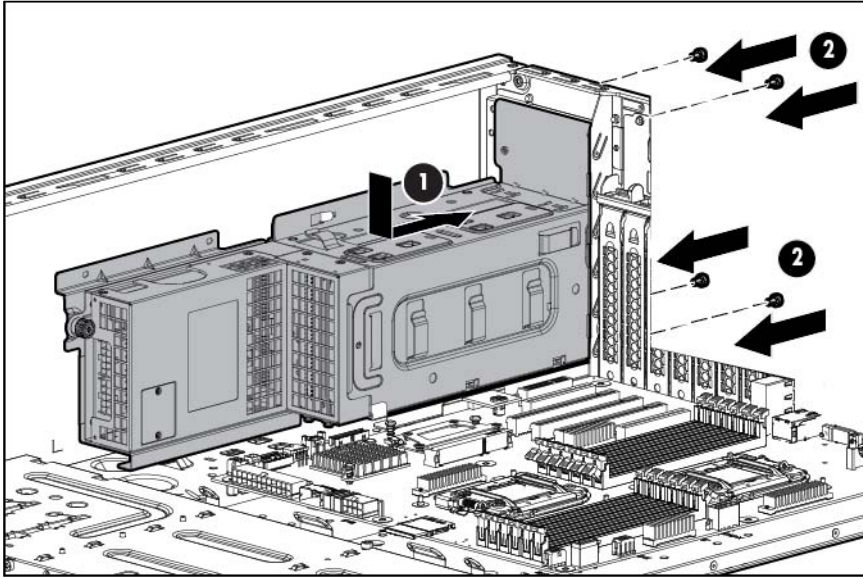


9. Remove any installed full-length PCI expansion cards ("[Remove the full-length expansion board](#)" on page 29).
10. Remove the fan modules and the fan blank (on page 30).
11. Disconnect the power cables from the system board, drive cages, and optical drive.
12. Remove the integrated power supply.

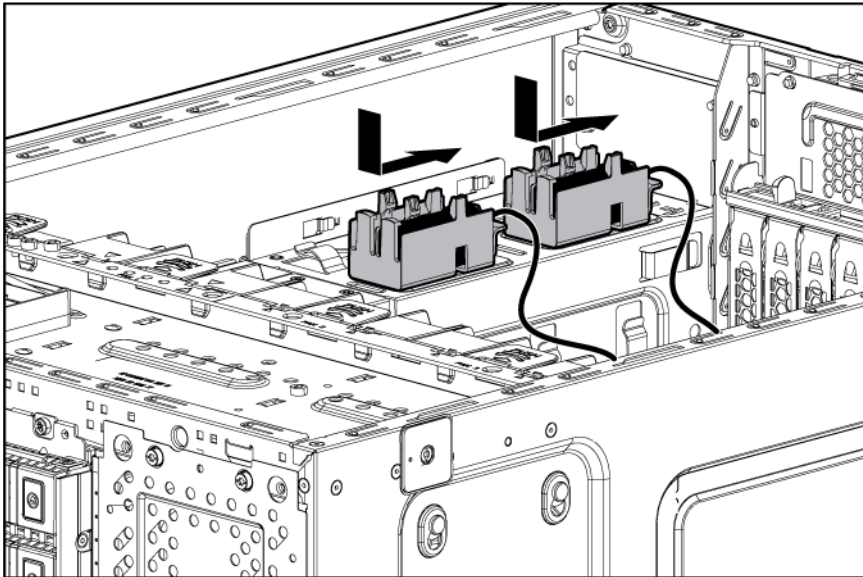


13. Install the redundant power supply assembly:
  - a. Insert the redundant power supply assembly into the server chassis.

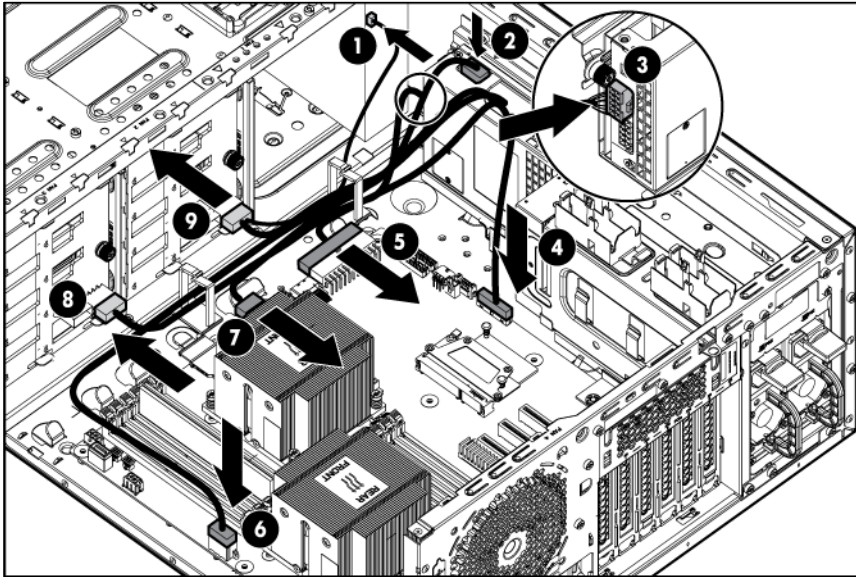
b. Secure the four external screws with T-10 and T-15 screwdrivers, respectively.



14. Install the capacitor pack holders on top of the redundant hot-plug power supply assembly.

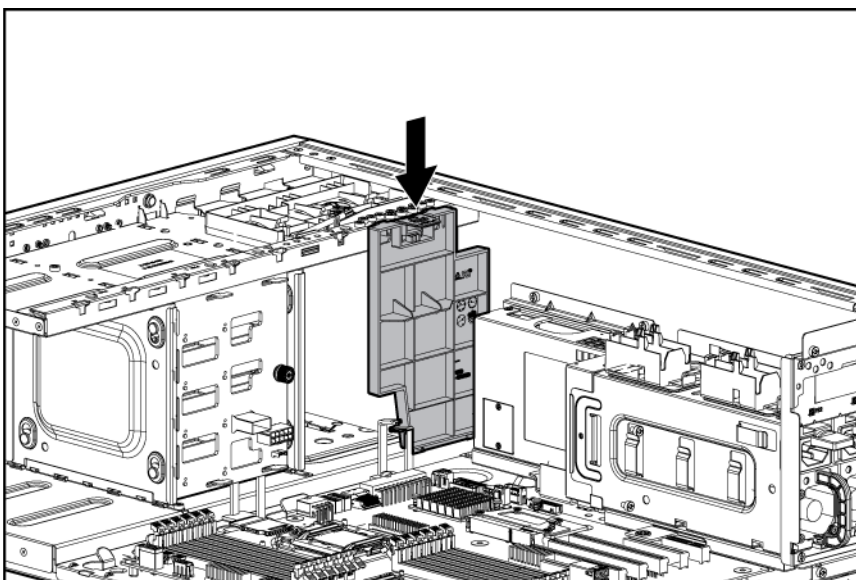


15. Route and connect the redundant power supply, drive cage, and optical drive power cables to the system board.

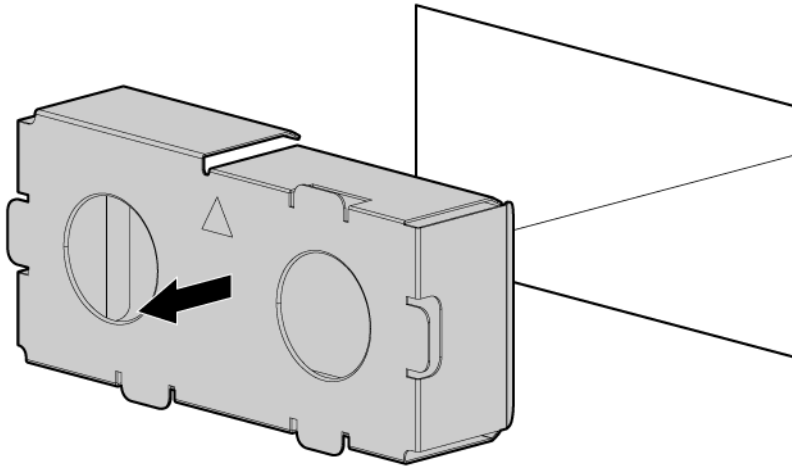


Item	Cables and connectors	Connector identifier
1	Optical drive power cable connector	P7, P8, P9, P10
2	Processor 2 RPS backplane connector	P3
3	Box 2 RPS backplane connector	P5
4	2x13 RPS control cable connector	N/A
5	2x12 pin system board power cable connector	P1
6	2x4 pin processor 2 power cable connector	P3M
7	2x4 pin processor 1 power cable connector	P2
8	2x5 pin box 2 power cable connector	P5H
9	2x5 pin box 1 power cable connector	BP1

16. Install the redundant hot-plug power supply cage rear blank.



17. Install the fan modules and the fan blank (on page 31).
18. Install any full-length PCI expansion cards that were removed ("[Installing an expansion board](#)" on page 63).
19. If a Smart Array controller is installed, connect the capacitor pack cable to it.
20. Install the system air baffle (on page 28).
21. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page 38).
22. If necessary, remove the power supply blank.



---

**CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

---

23. Install one or two common slot power supply modules into the redundant power supply cage ("[Power supply module](#)" on page 79).
24. Install the access panel (on page 26).
25. Return the server to an upright position.
26. Lock the front bezel (on page 24).
27. Connect each power cord to the server.
28. Connect each power cord to the power source.
29. Power up the server (on page 23).

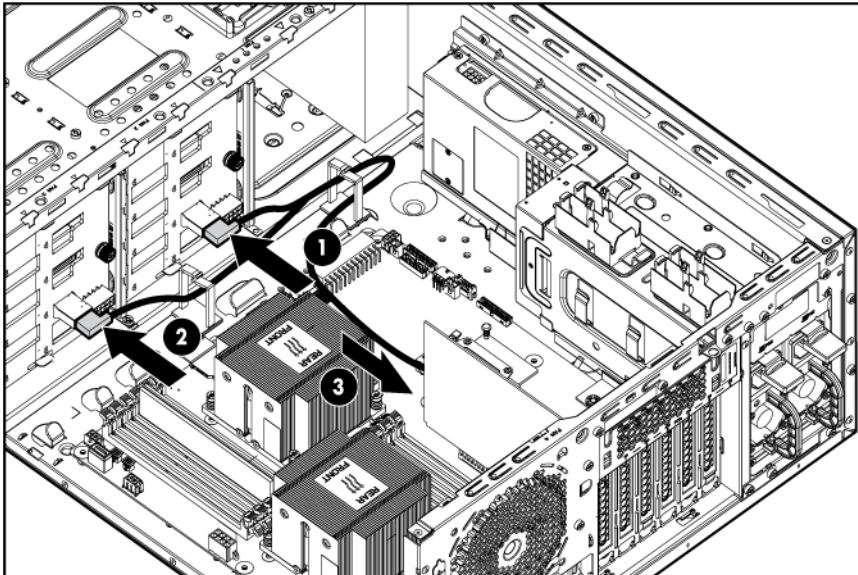
## Smart Array cable option

This cable option is required when installing a P430 Smart Array card.

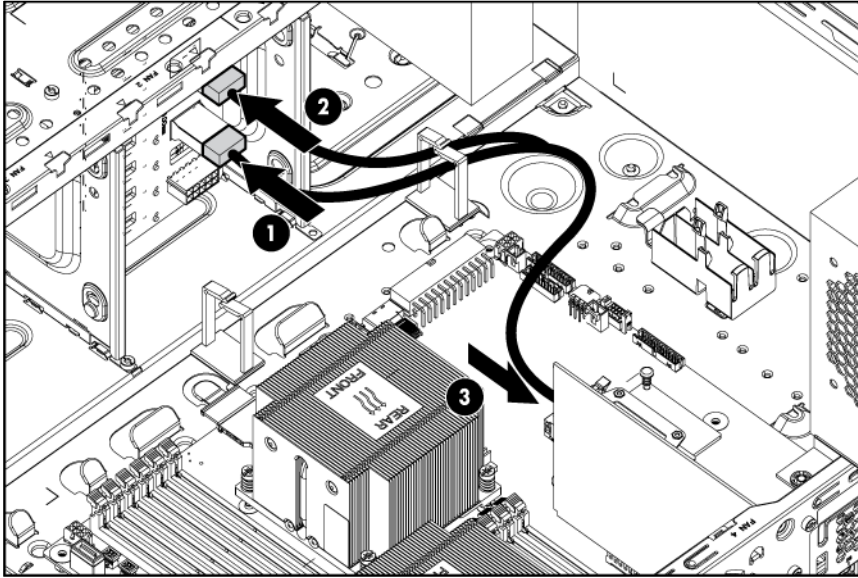
To install the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.

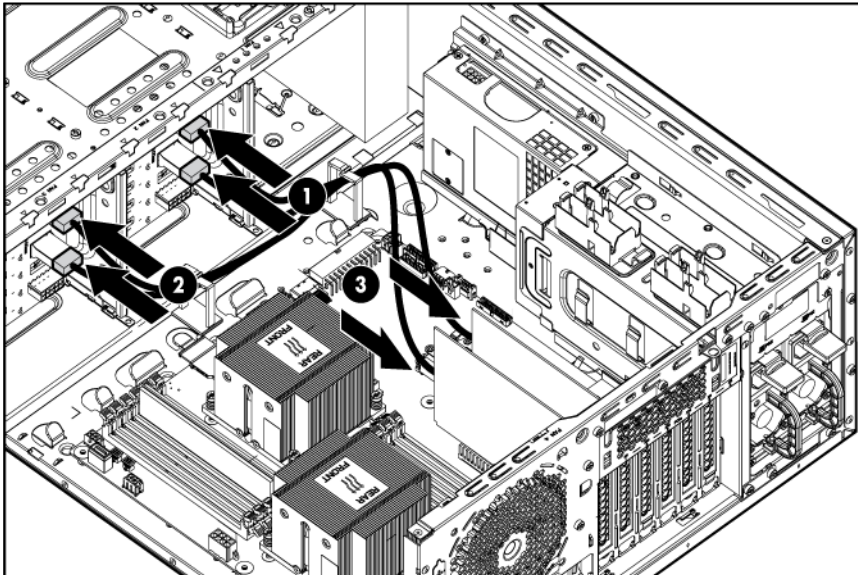
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove any installed full-length PCI expansion cards ("[Remove the full-length expansion board](#)" on page 29).
9. Remove the fan modules and the fan blank (on page 30).
10. Install the Smart Array controller ("[Installing an expansion board](#)" on page 63).
11. Connect the common end of the Mini-SAS Y-cable to the controller option.
  - o For 4+4 LFF configuration, use the right-angle connector cable
  - o For 8 SFF configuration, use the straight connector cable
12. Route the two ends of the Mini-SAS Y-cable through the cable management clips, and then connect them to the drive backplane.
  - o Four-bay + four-bay LFF cable routing to boxes 1 and 2



- o Eight-bay SFF cable routing to box 1



- o Eight-bay + eight-bay SFF cable routing to boxes 1 and 2



13. Install the fan modules and the fan blank (on page 31).
14. Install any full-length PCI expansion cards that were removed ("[Installing an expansion board](#)" on page 63).
15. Install the system air baffle (on page 28).
16. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page 38).
17. Install the access panel (on page 26).
18. Return the server to an upright position.
19. Lock the front bezel (on page 24).
20. Connect each power cord to the server.
21. Connect each power cord to the power source.
22. Power up the server (on page 23).

# Power supply module

Power redundancy requires the presence of two power supply modules in the system.

- ⚠ **CAUTION:** All power supplies installed in the server must have the same output power capacity. Verify that all power supplies have the same part number and label color. The system becomes unstable and may shut down when it detects mismatched power supplies.

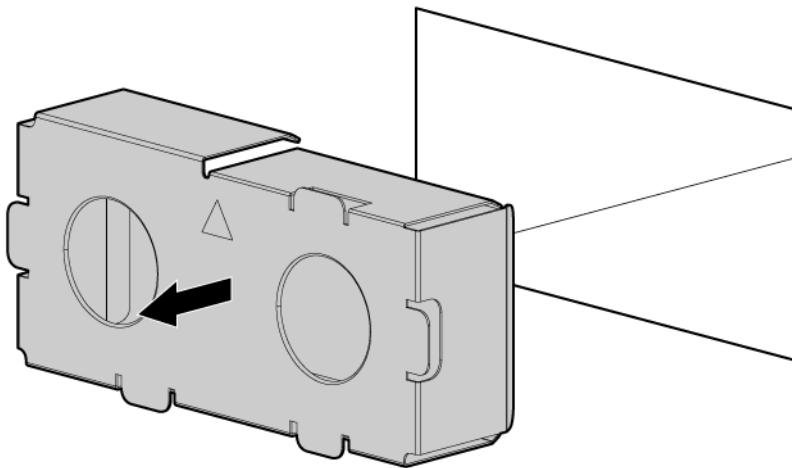
Label color	Output
Blue	460 W
Orange	750 W

- ⚠ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

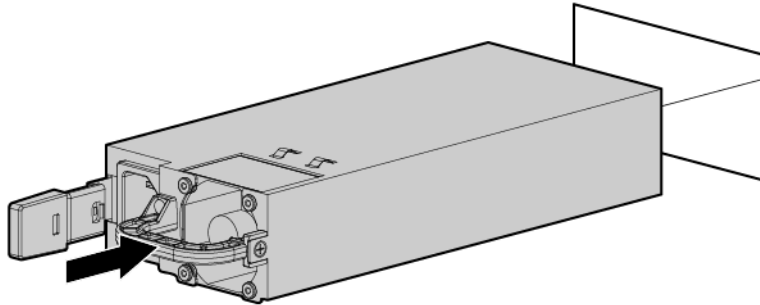
To install the component:

1. Access the product rear panel.
2. If necessary, remove the blank.

- ⚠ **WARNING:** To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.



3. Insert the power supply module into the power supply bay until it clicks into place.



4. Connect the power cord to the power supply module.
5. Connect the power cord to the AC power source.
6. Be sure that the power supply LED is green.

## HP Trusted Platform Module option

For more information about product features, specifications, options, configurations, and compatibility, see the product QuickSpecs on the HP Product Bulletin website (<http://www.hp.com/go/productbulletin>).

Use these instructions to install and enable a TPM on a supported server. This procedure includes three sections:

1. Installing the Trusted Platform Module board (on page 81).
2. Retaining the recovery key/password (on page 83).
3. Enabling the Trusted Platform Module (on page 83).

Enabling the TPM requires accessing RBSU. For more information about RBSU, see the HP website (<http://www.hp.com/support/rbsu>).

TPM installation requires the use of drive encryption technology, such as the Microsoft Windows BitLocker Drive Encryption feature. For more information on BitLocker, see the Microsoft website (<http://www.microsoft.com>).



**CAUTION:** Always observe the guidelines in this document. Failure to follow these guidelines can cause hardware damage or halt data access.

When installing or replacing a TPM, observe the following guidelines:


- Do not remove an installed TPM. Once installed, the TPM becomes a permanent part of the system board.
- When installing or replacing hardware, HP service providers cannot enable the TPM or the encryption technology. For security reasons, only the customer can enable these features.
- When returning a system board for service replacement, do not remove the TPM from the system board. When requested, HP Service provides a TPM with the spare system board.




- Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.
- When using BitLocker, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker detects a possible compromise of system integrity.
- HP is not liable for blocked data access caused by improper TPM use. For operating instructions, see the encryption technology feature documentation provided by the operating system.

## Installing the Trusted Platform Module board

---

 **WARNING:** To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.

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 **WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

---

To install the component:

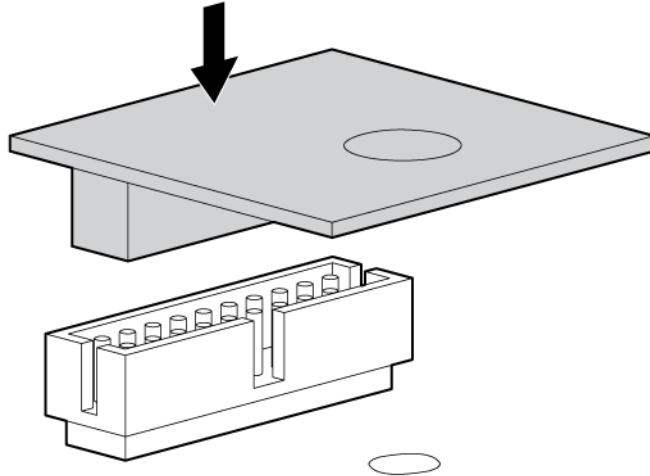
1. Power down the server (on page [23](#)).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page [24](#)).
4. Place the server on its side.
5. Remove the access panel (on page [25](#)).
6. If installed, remove the PCI air baffle (on page [27](#)).
7. If installed, remove the full-length PCI expansion cards from slots 5 and 6 ("[Remove the full-length expansion board](#)" on page [29](#)).

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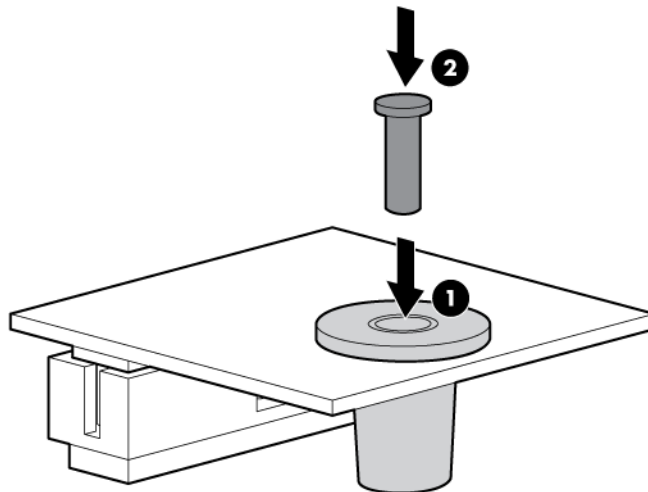
 **CAUTION:** Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

---

8. Install the TPM board. Press down on the connector to seat the board.



9. Install the TPM security rivet by pressing the rivet firmly into the system board.



10. If removed, install the full-length PCI expansion cards in slots 5 and 6 ("[Installing an expansion board](#)" on page [63](#)).
11. If removed, install the PCI air baffle ("[PCI air baffle option](#)" on page [38](#)).
12. Install the access panel (on page [26](#)).
13. Return the server to an upright position.
14. Lock the front bezel (on page [24](#)).
15. Connect each power cord to the server.
16. Connect each power cord to the power source.
17. Power up the server (on page [23](#)).

## Retaining the recovery key/password

The recovery key/password is generated during BitLocker™ setup, and can be saved and printed after BitLocker™ is enabled. When using BitLocker™, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker™ detects a possible compromise of system integrity.

To help ensure maximum security, observe the following guidelines when retaining the recovery key/password:

- Always store the recovery key/password in multiple locations.
- Always store copies of the recovery key/password away from the server.
- Do not save the recovery key/password on the encrypted hard drive.

## Enabling the Trusted Platform Module

1. When prompted during the start-up sequence, access RBSU by pressing the **F9** key.
2. From the Main Menu, select **Server Security**.
3. From the Server Security Menu, select **Trusted Platform Module**.
4. From the Trusted Platform Module Menu, select **TPM Functionality**.
5. Select **Enable**, and then press the **Enter** key to modify the TPM Functionality setting.
6. Press the **Esc** key to exit the current menu, or press the **F10** key to exit RBSU.
7. Reboot the server.
8. Enable the TPM in the OS. For OS-specific instructions, see the OS documentation.



---

**CAUTION:** When a TPM is installed and enabled on the server, data access is locked if you fail to follow the proper procedures for updating the system or option firmware, replacing the system board, replacing a hard drive, or modifying OS application TPM settings.

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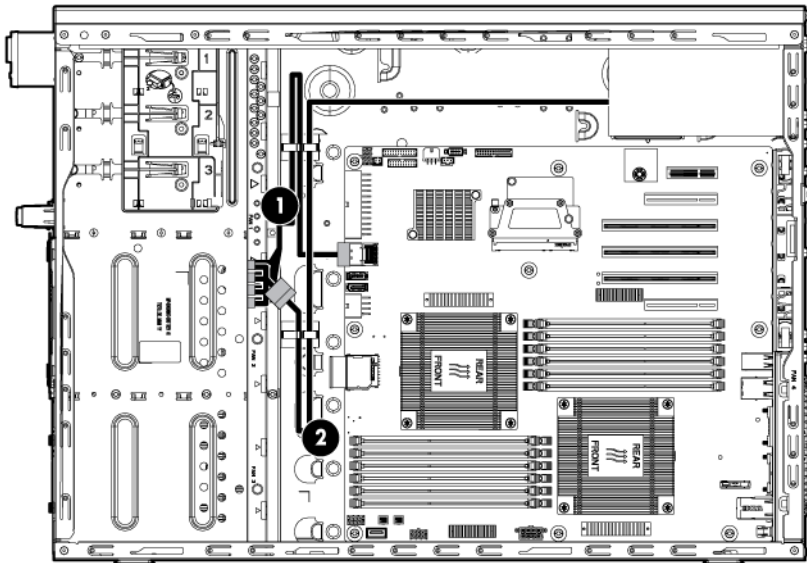
For more information on firmware updates and hardware procedures, see the *HP Trusted Platform Module Best Practices White Paper* on the HP website (<http://www.hp.com/support>).

For more information on adjusting TPM usage in BitLocker™, see the Microsoft website (<http://technet.microsoft.com/en-us/library/cc732774.aspx>).

# Cabling

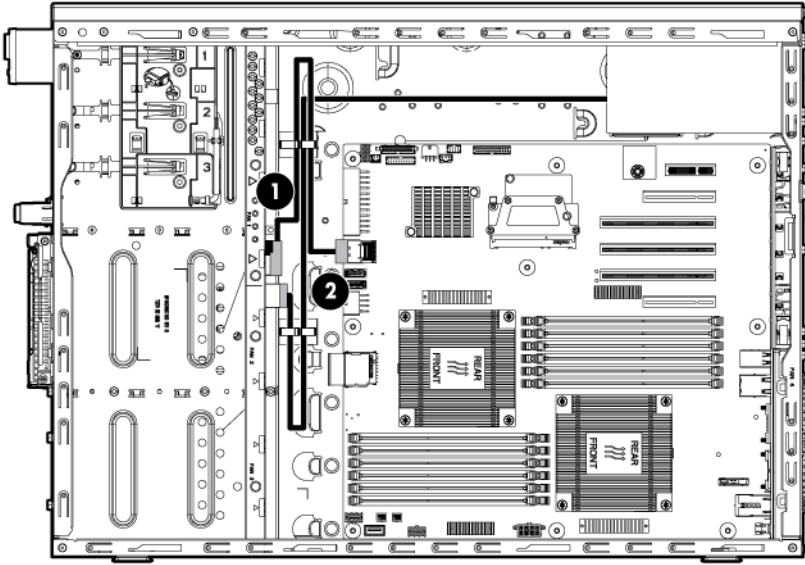
## Storage cabling

### Non-hot-plug, four-bay LFF drive cabling



Item	Description
1	Mini-SAS cable to system board
2	Box 1 power cable

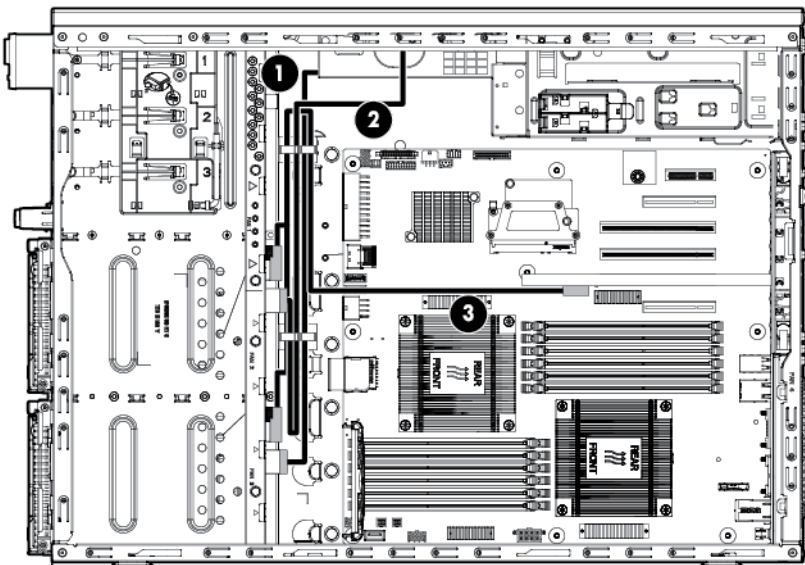
## Hot-plug, four-bay LFF drive cabling



Item	Description
1	Mini-SAS cable to system board
2	Box 1 power cable

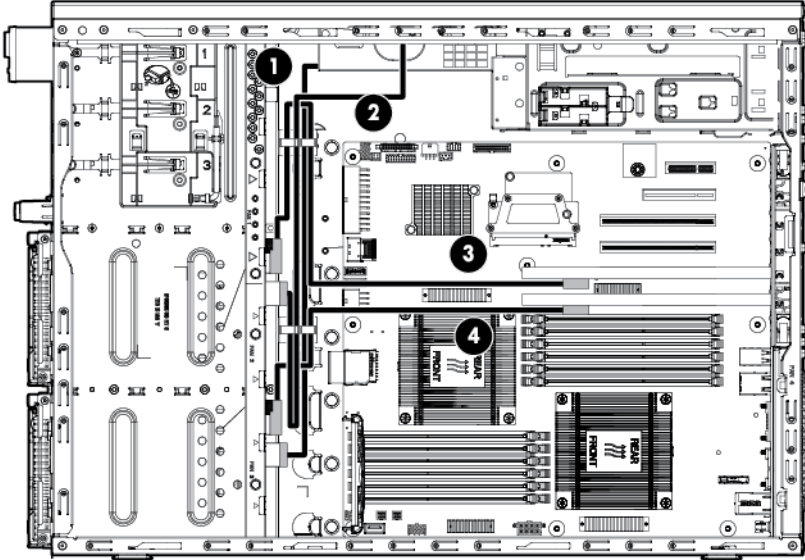
## Hot-plug, four-bay + four-bay LFF drive cabling

- Four-bay + four-bay LFF drive cabling with P430 controller card



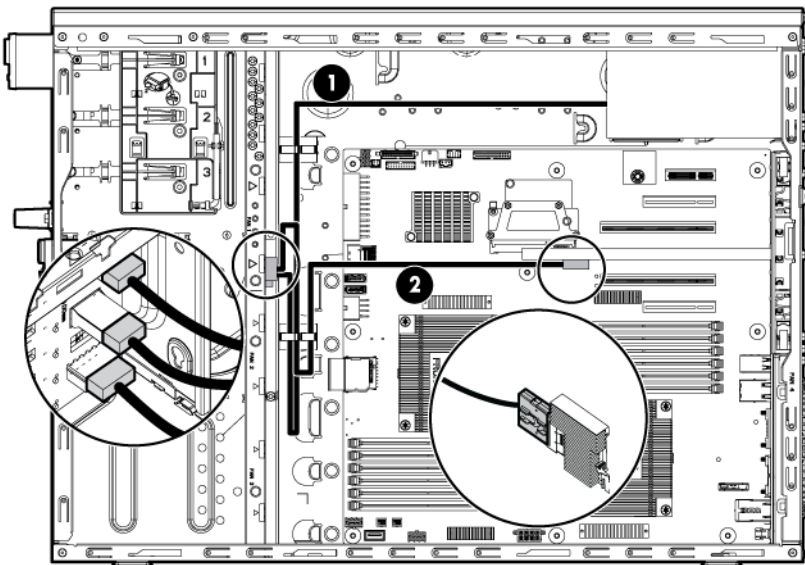
Item	Description
1	Box 2 power cable
2	Box 1 power cable
3	Mini-SAS Y cable to storage controller

- Four-bay + four-bay LFF drive cabling with two P222 controller cards



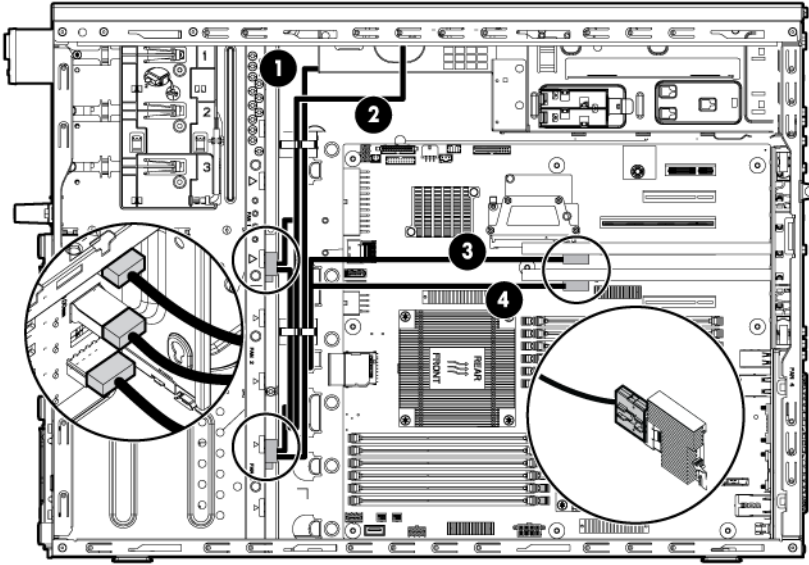
Item	Description
1	Box 2 power cable
2	Box 1 power cable
3	Box 1 Mini-SAS cable to storage controller
4	Box 2 Mini-SAS cable to storage controller

## Hot-plug, eight-bay SFF drive cabling



Item	Description
1	Power cable
2	Mini-SAS Y-cable to storage controller

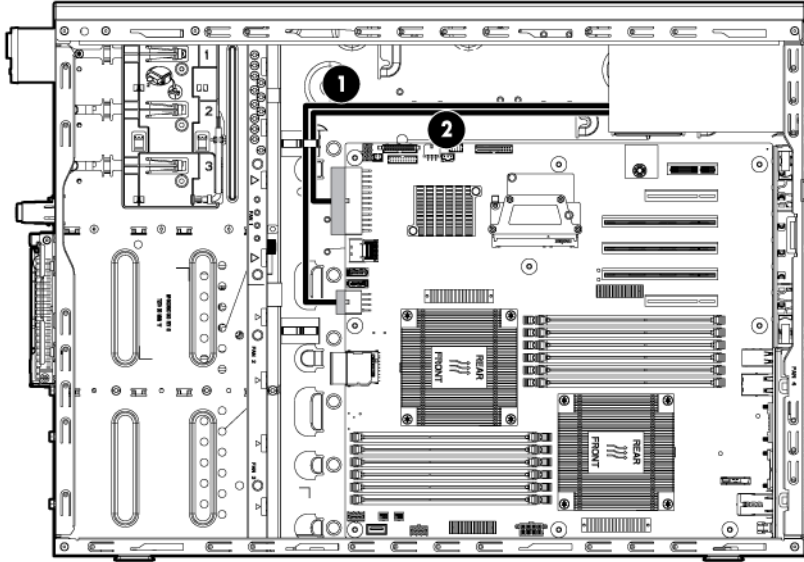
# Hot-plug, eight-bay + eight-bay SFF drive cabling



Item	Description
1	Box 2 power cable
2	Box 1 power cable
3	Mini-SAS Y-cable to storage controller
4	Mini-SAS Y-cable to storage controller

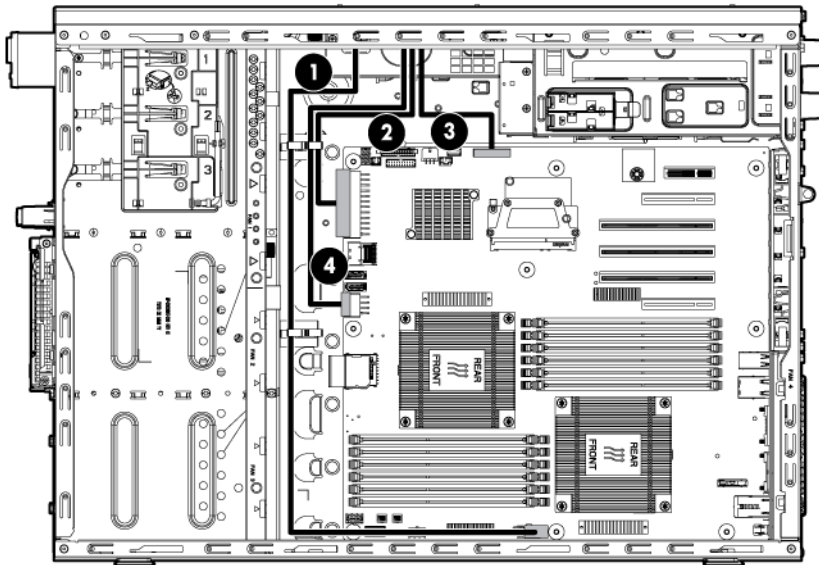
# Power cabling

## Integrated power cabling



Item	Description	Connector identifier
1	Processor 1 power cable	P1
2	System board power cable	P3

## RPS power cabling

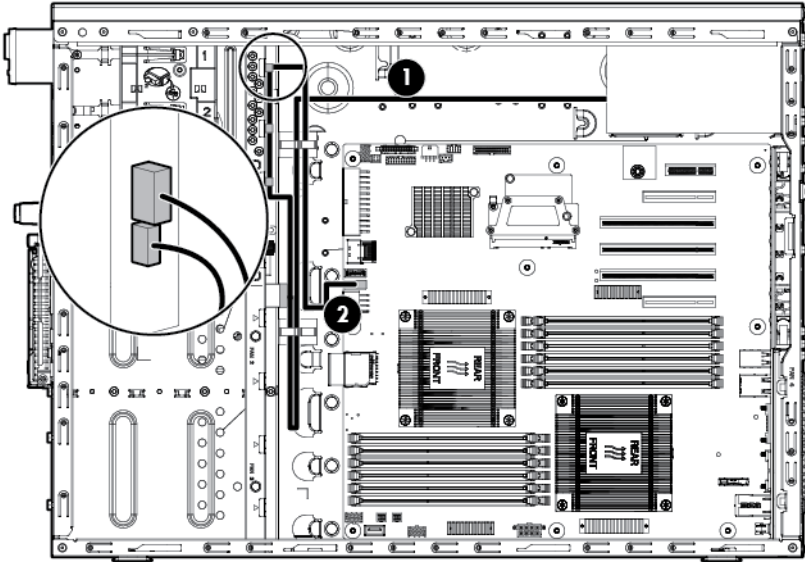


Item	Description	Connector identifier
1	Processor 2 power cable	P3M
2	System board power cable	P1



Item	Description	Connector identifier
3	RPS cable	N/A
4	Processor 1 power cable	P2

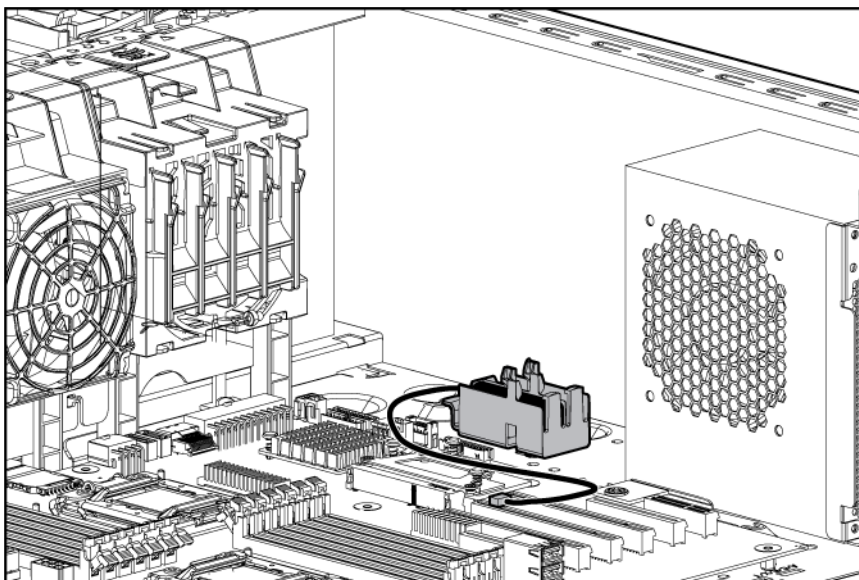
## Optical drive cabling



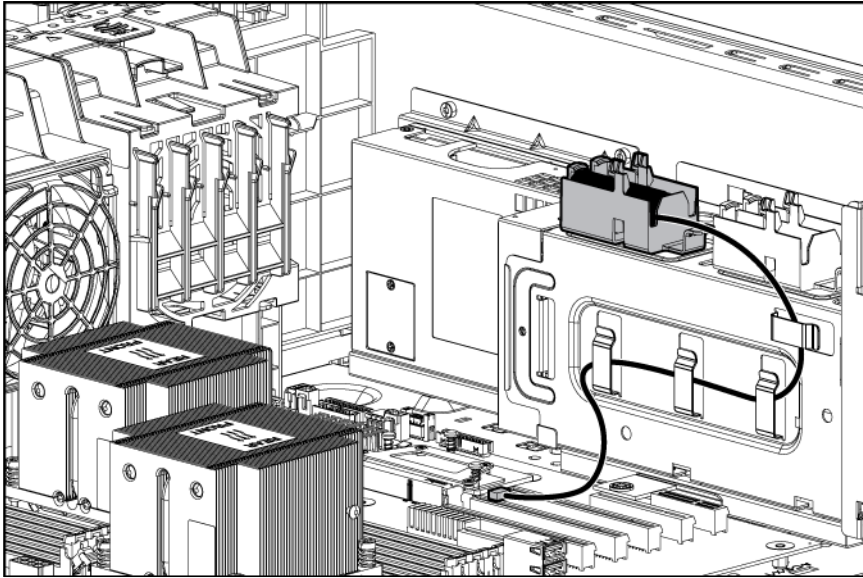
Item	Description	Connector identifier
1	Power cable	P7, P8, P9, P10
2	SATA cable	N/A

## Capacitor pack cabling

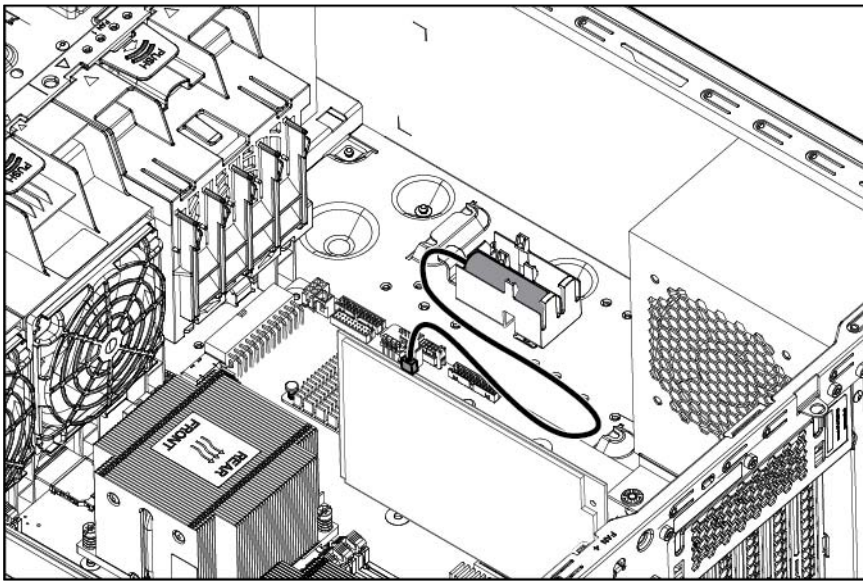
- Integrated configuration



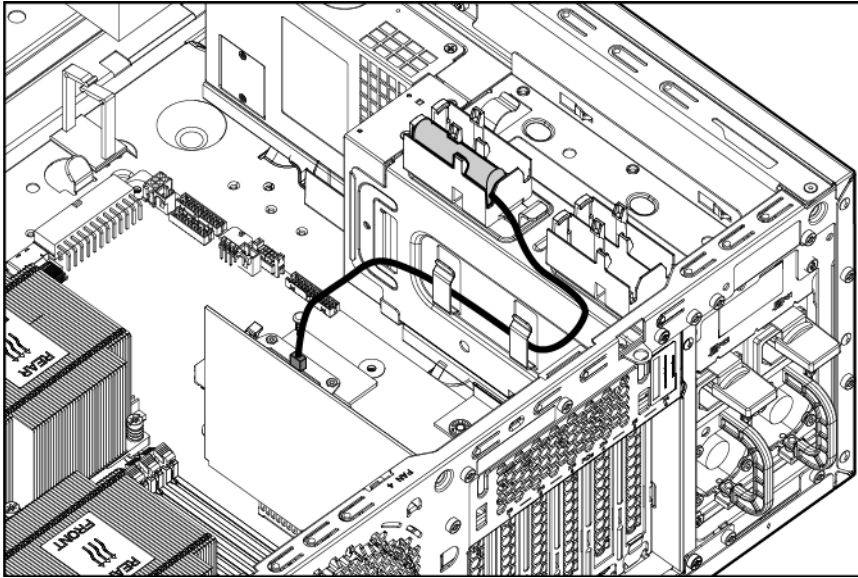
- RPS configuration



- Integrated configuration showing Smart Array controller card installed



- RPS configuration showing Smart Array controller card installed



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# Software and configuration utilities

## Server mode

The software and configuration utilities presented in this section operate in online mode, offline mode, or in both modes.

Software or configuration utility	Server mode
HP iLO (on page 92)	Online and Offline
Active Health System (on page 93)	Online and Offline
Integrated Management Log (on page 94)	Online and Offline
Intelligent Provisioning (on page 94)	Offline
HP Insight Diagnostics (on page 95)	Online and Offline
HP Insight Remote Support software (on page 95)	Online
HP Insight Online (on page 96)	Online
Erase Utility (on page 95)	Offline
Scripting Toolkit (on page 96)	Online
HP Service Pack for ProLiant (on page 96)	Online and Offline
HP Smart Update Manager (on page 97)	Online and Offline
HP ROM-Based Setup Utility (on page 97)	Offline
HP Smart Storage Administrator (on page 99)	Online and Offline
Option ROM Configuration for Arrays (on page 99)	Offline
ROMPaq utility (on page 100)	Offline

## HP product QuickSpecs

For more information about product features, specifications, options, configurations, and compatibility, see the product QuickSpecs on the HP Product Bulletin website (<http://www.hp.com/go/productbulletin>).

## HP iLO Management Engine

The HP iLO Management Engine is a set of embedded management features supporting the complete lifecycle of the server, from initial deployment through ongoing management.

## HP iLO

The iLO 4 subsystem is a standard component of selected HP ProLiant servers that simplifies initial server setup, server health monitoring, power and thermal optimization, and remote server administration. The iLO 4 subsystem includes an intelligent microprocessor, secure memory, and a dedicated network interface. This design makes iLO 4 independent of the host server and its operating system.

iLO 4 enables and manages the Active Health System (on page 93) and also features Agentless Management. All key internal subsystems are monitored by iLO 4. SNMP alerts are sent directly by iLO 4 regardless of the host operating system or even if no host operating system is installed.

HP Insight Remote Support software (on page 95) is also available in HP iLO with no operating system software, drivers, or agents.

Using iLO 4, you can do the following:

- Access a high-performance and secure Remote Console to the server from anywhere in the world.
- Use the shared iLO 4 Remote Console to collaborate with up to six server administrators.
- Remotely mount high-performance Virtual Media devices to the server.
- Securely and remotely control the power state of the managed server.
- Have true Agentless Management with SNMP alerts from iLO 4 regardless of the state of the host server.
- Access Active Health System troubleshooting features through the iLO 4 interface.
- Subscribe to HP Insight Remote Support software without installing any drivers or agents.

For more information about iLO 4 features (which may require an iLO Advanced Pack or iLO Advanced for BladeSystem license), see the iLO 4 documentation on the HP website (<http://www.hp.com/go/ilo/docs>).

## Active Health System

HP Active Health System provides the following features:

- Combined diagnostics tools/scanners
- Always on, continuous monitoring for increased stability and shorter downtimes
- Rich configuration history
- Health and service alerts
- Easy export and upload to Service and Support

The HP Active Health System monitors and records changes in the server hardware and system configuration. The Active Health System assists in diagnosing problems and delivering rapid resolution when server failures occur.

The Active Health System collects the following types of data:

- Server model
- Serial number
- Processor model and speed
- Storage capacity and speed
- Memory capacity and speed
- Firmware/BIOS

HP Active Health System does not collect information about Active Health System users' operations, finances, customers, employees, partners, or data center, such as IP addresses, host names, user names, and passwords. HP Active Health System does not parse or change operating system data from third-party error event log activities, such as content created or passed through by the operating system.

The data that is collected is managed according to the HP Data Privacy policy. For more information see the HP website (<http://www.hp.com/go/privacy>).

The Active Health System log, in conjunction with the system monitoring provided by Agentless Management or SNMP Pass-thru, provides continuous monitoring of hardware and configuration changes, system status, and service alerts for various server components.

The Agentless Management Service is available in the SPP, which is a disk image (.iso) that you can download from the HP website (<http://www.hp.com/go/spp/download>). The Active Health System log can be downloaded manually from iLO 4 or HP Intelligent Provisioning and sent to HP.

For more information, see the following documents:

- *HP iLO User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>)
- *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/intelligentprovisioning/docs>)

## Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within operating system-specific IML viewers
  - For Windows: IML Viewer
  - For Linux: IML Viewer Application
- From within the iLO 4 user interface
- From within HP Insight Diagnostics (on page [95](#))

## Intelligent Provisioning

Several packaging changes have taken place with HP ProLiant Gen8 servers: SmartStart CDs and the Smart Update Firmware DVD no longer ship with these new servers. Instead, the deployment capability is embedded in the server as part of HP iLO Management Engine's Intelligent Provisioning.

Intelligent Provisioning is a single-server deployment tool embedded in HP ProLiant Gen8 servers that simplifies HP ProLiant server setup, providing a reliable and consistent way to deploy HP ProLiant server configurations:

- Intelligent Provisioning assists with the OS installation process by preparing the system for installing "off-the-shelf" and HP branded versions of leading operating system software and integrating optimized HP ProLiant server support software from SPP. SPP is a comprehensive systems software and firmware solution for HP ProLiant servers and server blades and their enclosures.
- Intelligent Provisioning provides maintenance-related tasks through Perform Maintenance Options features.
- Intelligent Provisioning provides installation help for Microsoft Windows, Red Hat and SUSE Linux, and VMware operating systems. For specific OS support, see the *HP Intelligent Provisioning Release Notes* on the HP website (<http://www.hp.com/go/intelligentprovisioning/docs>).

For more information about Intelligent Provisioning software, see the HP website (<http://www.hp.com/go/intelligentprovisioning>). For more information about Intelligent Provisioning drivers, firmware, and SPP, see the HP website (<http://www.hp.com/go/spp/download>).

## HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, boot the server using Intelligent Provisioning (on page 94).

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft Windows and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, see the HP website (<http://www.hp.com/servers/diags>). HP Insight Diagnostics Online Edition is also available in the SPP. For more information, see the HP website (<http://www.hp.com/go/spp/download>).

### HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 95) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that are supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every Intelligent Provisioning-assisted HP Insight Diagnostics installation, or it can be installed through the SPP ("HP Service Pack for ProLiant" on page 96).

## Erase Utility



---

**CAUTION:** Perform a backup before running the Erase Utility. The utility sets the system to its original factory state, deletes the current hardware configuration information, including array setup and disk partitioning, and erases all connected hard drives completely. Before using this utility, see the instructions in the *HP Intelligent Provisioning User Guide*.

---

Use the Erase Utility to erase drives and Active Health System logs, and to reset RBSU settings. Run the Erase Utility if you must erase the system for the following reasons:

- You want to install a new operating system on a server with an existing operating system.
- You encounter an error when completing the steps of a factory-installed operating system installation.

To access the Erase Utility, click the Perform Maintenance icon from the Intelligent Provisioning home screen, and then select **Erase**.

For more information about the Erase Utility, see the *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/intelligentprovisioning/docs>).

## HP Insight Remote Support software

HP strongly recommends that you install HP Insight Remote Support software to complete the installation or upgrade of your product and to enable enhanced delivery of your HP Warranty, HP Care Pack Service, or HP contractual support agreement. HP Insight Remote Support supplements your monitoring continuously to ensure maximum system availability by providing intelligent event diagnosis, and automatic, secure

submission of hardware event notifications to HP, which will initiate a fast and accurate resolution, based on your product's service level. Notifications may be sent to your authorized HP Channel Partner for onsite service, if configured and available in your country.

For more information, see the HP website (<http://www.hp.com/go/insightremotesupport>). The *HP Insight Remote Support Release Notes* detail the prerequisites, supported hardware, and associated operating systems. The release notes are available on the HP website (<http://www.hp.com/go/insightremotesupport/docs>). HP Insight Remote Support is included as part of HP Warranty, HP Care Pack Service, or HP contractual support agreement.

## HP Insight Online

HP Insight Online is a new capability of the HP Support Center portal. Combined with HP Insight Remote Support 7.x, it automatically aggregates device health, asset, and support information from iLO Management Engine with contract and warranty information, and then secures it in a single, personalized dashboard that is viewable from anywhere at any time. The dashboard organizes your IT and service data to help you understand and respond to that information more quickly. With specific authorization from you, an authorized HP Channel Partner can also view your IT environment remotely at HP Insight Online.

- For more information about using HP Insight Online, see the *HP Insight Online Getting Started Guide* on the HP website (<http://www.hp.com/go/proliantgen8/docs>).
- To install HP Insight Remote Support and enable HP Insight Online, see the *HP Insight Online Integrated Solution and Management Setup Guide* on the HP website (<http://www.hp.com/go/proliantgen8/docs>).

## Scripting Toolkit

The Scripting Toolkit is a server deployment product that delivers an unattended automated installation for high-volume server deployments. The Scripting Toolkit is designed to support ProLiant BL, ML, DL, and SL servers. The toolkit includes a modular set of utilities and important documentation that describes how to apply these tools to build an automated server deployment process.

The Scripting Toolkit provides a flexible way to create standard server configuration scripts. These scripts are used to automate many of the manual steps in the server configuration process. This automated server configuration process cuts time from each deployment, making it possible to scale rapid, high-volume server deployments.

For more information, and to download the Scripting Toolkit, see the HP website (<http://www.hp.com/go/ProLiant/STK>).

## HP Service Pack for ProLiant

SPP is a comprehensive systems software and firmware solution delivered as a single ISO file. This solution uses HP SUM as the deployment tool and is tested on all supported HP ProLiant servers including HP ProLiant Gen8 servers.

SPP has several key features for updating HP ProLiant servers. Using HP SUM as the deployment tool, SPP can be used in an online mode on a Windows or Linux hosted operating system, or in an offline mode where the server is booted to an operating system included on the ISO file so that the server can be updated automatically with no user interaction or updated in interactive mode.

For more information or to download SPP, see the HP website (<http://www.hp.com/go/spp>).



# HP Smart Update Manager

HP SUM is a product used to install and update firmware and software on HP ProLiant servers. HP SUM provides a GUI and a command-line scriptable interface for deployment of firmware and software for single or one-to-many HP ProLiant servers and network-based targets, such as iLOs, OAs, and VC Ethernet and Fibre Channel modules.

For more information about HP SUM, see the product page on the HP website (<http://www.hp.com/go/hpsum>).

To download HP SUM, see the HP website (<http://www.hp.com/go/hpsum/download>).

To access the *HP Smart Update Manager User Guide*, see the HP SUM Information Library (<http://www.hp.com/go/hpsum/documentation>).

# HP ROM-Based Setup Utility

RBSU is a configuration utility embedded in HP ProLiant servers that performs a wide range of configuration activities that can include the following:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller
- Configuring memory options
- Language selection

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the HP RBSU Information Library (<http://www.hp.com/go/rbsu/docs>).

## Using RBSU

To use RBSU, use the following keys:

- To access RBSU, press the **F9** key during power-up when prompted.
- To navigate the menu system, use the arrow keys.
- To make selections, press the **Enter** key.
- To access Help for a highlighted configuration option, press the **F1** key.



---

**IMPORTANT:** RBSU automatically saves settings when you press the **Enter** key. The utility does not prompt you for confirmation of settings before you exit the utility. To change a selected setting, you must select a different setting and press the **Enter** key.

---

Default configuration settings are applied to the server at one of the following times:

- Upon the first system power-up
- After defaults have been restored

Default configuration settings are sufficient for proper typical server operation, but configuration settings can be modified using RBSU. The system will prompt you for access to RBSU with each power-up.

## Auto-configuration process

The auto-configuration process automatically runs when you boot the server for the first time. During the power-up sequence, the system ROM automatically configures the entire system without needing any intervention. During this process, the ORCA utility, in most cases, automatically configures the array to a default setting based on the number of drives connected to the server.

---

**NOTE:** If the boot drive is not empty or has been written to in the past, ORCA does not automatically configure the array. You must run ORCA to configure the array settings.

---

**NOTE:** The server may not support all the following examples.

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Drives installed	Drives used	RAID level
1	1	RAID 0
2	2	RAID 1
3, 4, 5, or 6	3, 4, 5, or 6	RAID 5
More than 6	0	None

To change any ORCA default settings and override the auto-configuration process, press the **F8** key when prompted.

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the HP RBSU Information Library (<http://www.hp.com/go/rbsu/docs>).

## Boot options

Near the end of the boot process, the boot options screen is displayed. This screen is visible for several seconds before the system attempts to boot from a supported boot device. During this time, you can do the following:

- Access RBSU by pressing the **F9** key.
- Access Intelligent Provisioning Maintenance Menu by pressing the **F10** key.
- Access the boot menu by pressing the **F11** key.
- Force a PXE Network boot by pressing the **F12** key.

## Configuring AMP modes

Not all HP ProLiant servers support all AMP modes. RBSU provides menu options only for the modes supported by the server. Advanced memory protection within RBSU enables the following advanced memory modes:

- **Advanced ECC Mode**—Provides memory protection beyond Standard ECC. All single-bit failures and some multi-bit failures can be corrected without resulting in system downtime.
- **Online Spare Mode**—Provides protection against failing or degraded DIMMs. Certain memory is set aside as spare, and automatic failover to spare memory occurs when the system detects a degraded DIMM. DIMMs that are likely to receive a fatal or uncorrectable memory error are removed from operation automatically, resulting in less system downtime.

For DIMM population requirements, see the server-specific user guide.

# Re-entering the server serial number and product ID

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warning appears:  
Warning: The serial number should ONLY be modified by qualified service personnel. This value should always match the serial number located on the chassis.
5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:  
Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID located on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

## Utilities and features

### HP Smart Storage Administrator

HP SSA is a configuration and management tool for HP Smart Array controllers. Starting with HP ProLiant Gen8 servers, HP SSA replaces ACU with an enhanced GUI and additional configuration features.

HP SSA exists in three interface formats: the HP SSA GUI, the HP SSA CLI, and HP SSA Scripting. Although all formats provide support for configuration tasks, some of the advanced tasks are available in only one format.

Some HP SSA features include the following:

- Supports online array capacity expansion, logical drive extension, assignment of online spares, and RAID or stripe size migration
- Suggests the optimal configuration for an unconfigured system
- Provides diagnostic and SmartSSD Wear Gauge functionality on the Diagnostics tab
- For supported controllers, provides access to additional features.

For more information about HP SSA, see the HP website (<http://www.hp.com/go/hpssa>).

### Option ROM Configuration for Arrays

Before installing an operating system, you can use the ORCA utility to create the first logical drive, assign RAID levels, and establish online spare configurations.

The utility also provides support for the following functions:

- Reconfiguring one or more logical drives
- Viewing the current logical drive configuration
- Deleting a logical drive configuration
- Setting the controller to be the boot controller
- Selecting the boot volume

If you do not use the utility, ORCA will default to the standard configuration.

For more information regarding the default configurations that ORCA uses, see the *HP ROM-Based Setup Utility User Guide* on the HP RBSU Information Library (<http://www.hp.com/go/rbsu/docs>).

For more information about the storage controller and its features, select the relevant controller user documentation on the HP website (<http://www.hp.com/go/smartstorage/docs>).

To configure arrays, see the *HP Smart Storage Administrator User Guide* on the HP website (<http://www.hp.com/go/smartstorage/docs>).

## ROMPaq utility

The ROMPaq utility enables you to upgrade the system firmware (BIOS). To upgrade the firmware, insert a ROMPaq USB Key into an available USB port and boot the system. In addition to ROMPaq, Online Flash Components for Windows and Linux operating systems are available for updating the system firmware.

The ROMPaq utility checks the system and provides a choice (if more than one exists) of available firmware revisions.

For more information, go to the HP website (<http://www.hp.com/go/hpsc>) and click on **Drivers, Software & Firmware**. Then, enter your product name in the **Find an HP product** field and click **Go**.

## Automatic Server Recovery

ASR is a feature that causes the system to restart when a catastrophic operating system error occurs, such as a blue screen, ABEND (does not apply to HP ProLiant DL980 Servers), or panic. A system fail-safe timer, the ASR timer, starts when the System Management driver, also known as the Health Driver, is loaded. When the operating system is functioning properly, the system periodically resets the timer. However, when the operating system fails, the timer expires and restarts the server.

ASR increases server availability by restarting the server within a specified time after a system hang. At the same time, the HP SIM console notifies you by sending a message to a designated pager number that ASR has restarted the system. You can disable ASR from the System Management Homepage or through RBSU.

## USB support

HP provides both standard USB 2.0 support and legacy USB 2.0 support. Standard support is provided by the OS through the appropriate USB device drivers. Before the OS loads, HP provides support for USB devices through legacy USB support, which is enabled by default in the system ROM.

Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST

- RBSU
- Diagnostics
- DOS
- Operating environments which do not provide native USB support

## Redundant ROM support

The server enables you to upgrade or configure the ROM safely with redundant ROM support. The server has a single ROM that acts as two separate ROM images. In the standard implementation, one side of the ROM contains the current ROM program version, while the other side of the ROM contains a backup version.

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**NOTE:** The server ships with the same version programmed on each side of the ROM.

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## Safety and security benefits

When you flash the system ROM, ROMPaq writes over the backup ROM and saves the current ROM as a backup, enabling you to switch easily to the alternate ROM version if the new ROM becomes corrupted for any reason. This feature protects the existing ROM version, even if you experience a power failure while flashing the ROM.

## Keeping the system current

### Drivers



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**IMPORTANT:** Always perform a backup before installing or updating device drivers.

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The server includes new hardware that may not have driver support on all OS installation media.

If you are installing an Intelligent Provisioning-supported OS, use Intelligent Provisioning (on page 94) and its Configure and Install feature to install the OS and latest supported drivers.

If you do not use Intelligent Provisioning to install an OS, drivers for some of the new hardware are required. These drivers, as well as other option drivers, ROM images, and value-add software can be downloaded as part of an SPP.

If you are installing drivers from SPP, be sure that you are using the latest SPP version that your server supports. To verify that your server is using the latest supported version and for more information about SPP, see the HP website (<http://www.hp.com/go/spp/download>).

To locate the drivers for a particular server, go to the HP website (<http://www.hp.com/go/hpsc>) and click on **Drivers, Software & Firmware**. Then, enter your product name in the **Find an HP product** field and click **Go**.

## Software and firmware

Software and firmware should be updated before using the server for the first time, unless any installed software or components require an older version. For system software and firmware updates, download the SPP ("HP Service Pack for ProLiant" on page 96) from the HP website (<http://www.hp.com/go/spp>).

## Version control

The VCRM and VCA are web-enabled Insight Management Agents tools that HP SIM uses to schedule software update tasks to the entire enterprise.

- VCRM manages the repository for SPP. Administrators can view the SPP contents or configure VCRM to automatically update the repository with internet downloads of the latest software and firmware from HP.
- VCA compares installed software versions on the node with updates available in the VCRM managed repository. Administrators configure VCA to point to a repository managed by VCRM.

For more information about version control tools, see the *HP Systems Insight Manager User Guide*, the *HP Version Control Agent User Guide*, and the *HP Version Control Repository User Guide* on the HP website (<http://www.hp.com/go/hpsim>).

## HP operating systems and virtualization software support for ProLiant servers

For information about specific versions of a supported operating system, see the HP website (<http://www.hp.com/go/ossupport>).

## HP Technology Service Portfolio

HP Technology Services offers a targeted set of consultancy, deployment, and service solutions to meet the support needs of most business and IT environments.

**Foundation Care services**—Delivers scalable hardware and software support packages for HP ProLiant server and industry-standard software. You can choose the type and level of service that is most suitable for your business needs.

**HP Collaborative Support**—With a single call, HP addresses initial hardware and software support needs and helps to quickly identify if a problem is related to hardware or software. If the problem is related to hardware, HP resolves the problem according to service level commitments. If the reported incident is related to an HP software product or a supported third-party software product and cannot be resolved by applying known fixes, HP contacts the third-party vendor and creates a problem incident on your behalf.

**HP Proactive Care**—For customers running business critical environments where downtime is not an option, HP Proactive Care helps to deliver high levels of availability. Key to these service options is the delivery of proactive service management tools to help you avoid the causes of downtime. If a problem arises, then HP offers advanced technical response from critical system support specialists for problem identification and resolution.

**HP Support Center**—For all service options, the HP Support Center delivers the information, tools, and experts required to support HP business products.

**HP Insight Remote Support**—Provides 24x7 secure remote monitoring, diagnosis, and problem resolution.

For more information, see one of the following websites:

- HP ProLiant Server Services website (<http://www.hp.com/services/proliant>)
- HP BladeSystem Services website (<http://www.hp.com/services/bladesystem>)

## Change control and proactive notification

HP offers Change Control and Proactive Notification to notify customers 30 to 60 days in advance of upcoming hardware and software changes on HP commercial products.

For more information, refer to the HP website (<http://www.hp.com/go/pcn>).

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# Troubleshooting

## Troubleshooting resources

The *HP ProLiant Gen8 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_en](http://www.hp.com/support/ProLiant_TSG_v1_en))
- French ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_fr](http://www.hp.com/support/ProLiant_TSG_v1_fr))
- Spanish ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_sp](http://www.hp.com/support/ProLiant_TSG_v1_sp))
- German ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_gr](http://www.hp.com/support/ProLiant_TSG_v1_gr))
- Japanese ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_jp](http://www.hp.com/support/ProLiant_TSG_v1_jp))
- Simplified Chinese ([http://www.hp.com/support/ProLiant\\_TSG\\_v1\\_sc](http://www.hp.com/support/ProLiant_TSG_v1_sc))

The *HP ProLiant Gen8 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_en](http://www.hp.com/support/ProLiant_EMG_v1_en))
- French ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_fr](http://www.hp.com/support/ProLiant_EMG_v1_fr))
- Spanish ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_sp](http://www.hp.com/support/ProLiant_EMG_v1_sp))
- German ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_gr](http://www.hp.com/support/ProLiant_EMG_v1_gr))
- Japanese ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_jp](http://www.hp.com/support/ProLiant_EMG_v1_jp))
- Simplified Chinese ([http://www.hp.com/support/ProLiant\\_EMG\\_v1\\_sc](http://www.hp.com/support/ProLiant_EMG_v1_sc))



# System battery replacement

If the server no longer automatically displays the correct date and time, then replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.

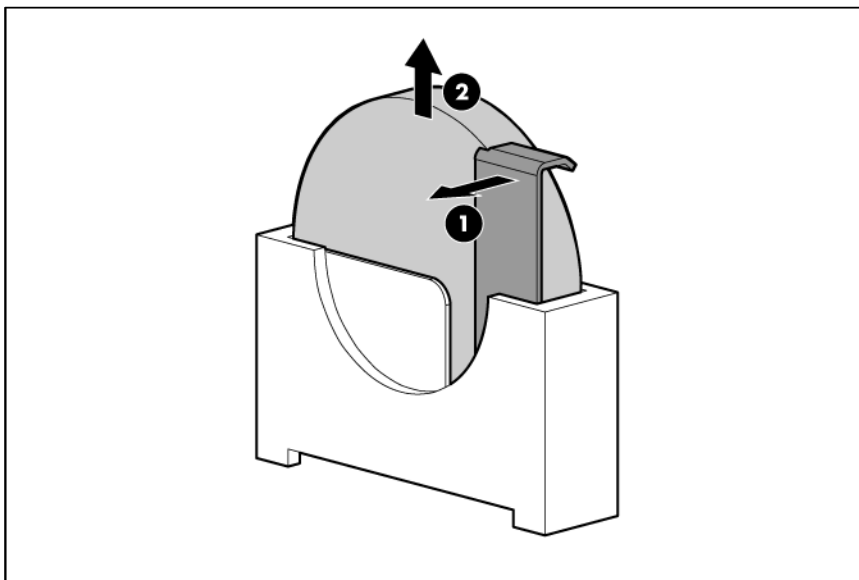


**WARNING:** The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. Power down the server (on page 23).
2. Remove all power:
  - a. Disconnect each power cord from the power source.
  - b. Disconnect each power cord from the server.
3. Unlock the front bezel (on page 24).
4. Place the server on its side.
5. Remove the access panel (on page 25).
6. If installed, remove the PCI air baffle (on page 27).
7. Remove the system air baffle (on page 28).
8. Remove the battery.



**IMPORTANT:** Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

To replace the component, reverse the removal procedure.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

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# Regulatory information

## Safety and regulatory compliance

For safety, environmental, and regulatory information, see *Safety and Compliance Information for Server, Storage, Power, Networking, and Rack Products*, available at the HP website (<http://www.hp.com/support/Safety-Compliance-EnterpriseProducts>).

## Belarus Kazakhstan Russia marking



### Manufacturer

Hewlett-Packard Company, Address: 3000 Hanover Street, Palo Alto, California 94304, U.S.

### Local representative information (Russian)

- HP Russia  
ЗАО «Хьюлетт-Паккард А.О.», 125171, Россия, г. Москва, Ленинградское шоссе, 16А, стр.3, тел./факс: +7 (495) 797 35 00, +7 (495) 287 89 05
- HP Belarus  
ИООО «Хьюлетт-Паккард Бел», 220030, Беларусь, г. Минск, ул. Интернациональная, 36-1, офис 722-723, тел.: +375 (17) 392 28 18, факс: +375 (17) 392 28 21
- HP Kazakhstan  
ТОО «Хьюлетт-Паккард (К)», 050040, Казахстан, г. Алматы, Бостандықский район, ул. Тимирязева, 28В, 1 этаж, тел./факс: +7 (727) 355 35 50, +7 (727) 355 35 51

### Local representative information (Kazakh)

ЖШС «Хьюлетт-Паккард (К)», Қазақстан, Алматы қ., Бостандық ауданы, Тимирязев к-сі, 28В, тел./факс: +7 (727) 355 35 50, +7 (727) 355 35 51

### Manufacturing date

The manufacturing date is defined by the serial number (HP serial number format for this product):

CCSYWWZZZZ

Valid date formats include the following:

- YWW, where Y indicates the year counting from within each new decade, with 2000 as the starting point. For example, 238: 2 for 2002 and 38 for the week of September 9. In addition, 2010 is indicated by 0, 2011 by 1, 2012 by 2, 2013 by 3, and so forth.
- YYWW, where YY indicates the year, using a base year of 2000. For example, 0238: 02 for 2002 and 38 for the week of September 9.

## Turkey RoHS material content declaration

Türkiye Cumhuriyeti: EEE Yönetmeliğine Uygundur

## Ukraine RoHS material content declaration

Обладнання відповідає вимогам Технічного регламенту щодо обмеження використання деяких небезпечних речовин в електричному та електронному обладнанні, затвердженого постановою Кабінету Міністрів України від 3 грудня 2008 № 1057

## Warranty information

HP ProLiant and X86 Servers and Options (<http://www.hp.com/support/ProLiantServers-Warranties>)

HP Enterprise Servers (<http://www.hp.com/support/EnterpriseServers-Warranties>)

HP Storage Products (<http://www.hp.com/support/Storage-Warranties>)

HP Networking Products (<http://www.hp.com/support/Networking-Warranties>)

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# Electrostatic discharge

## Preventing electrostatic discharge

To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

## Grounding methods to prevent electrostatic discharge

Several methods are used for grounding. Use one or more of the following methods when handling or installing electrostatic-sensitive parts:

- Use a wrist strap connected by a ground cord to a grounded workstation or computer chassis. Wrist straps are flexible straps with a minimum of 1 megohm  $\pm 10$  percent resistance in the ground cords. To provide proper ground, wear the strap snug against the skin.
- Use heel straps, toe straps, or boot straps at standing workstations. Wear the straps on both feet when standing on conductive floors or dissipating floor mats.
- Use conductive field service tools.
- Use a portable field service kit with a folding static-dissipating work mat.

If you do not have any of the suggested equipment for proper grounding, have an authorized reseller install the part.

For more information on static electricity or assistance with product installation, contact an authorized reseller.

# Specifications

## Environmental specifications

Specification	Value
<b>Temperature range*</b>	
Operating	10°C to 35°C (50°F to 95°F)
Nonoperating	-30°C to 60°C (-22°F to 140°F)
<b>Relative humidity (noncondensing)</b>	
Operating, maximum wet bulb temperature of 28°C (82.4°F)	10% to 90%
Nonoperating, maximum wet bulb temperature of 38.7°C (101.7°F)	5% to 95%

\* All temperature ratings shown are for sea level. An altitude derating of 1°C per 304.8 m (1.8°F per 1,000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed.

## Server specifications

Specification	Value
<b>Dimensions (with feet/bezel)</b>	—
Height	43 cm (16.93 in)
Depth	63 cm (24.80 in)
Width	20 cm (7.87 in)
<b>Weight (approximate)</b>	—
Maximum (all hard drives, power supplies, and processors installed)	27 kg (59.53 lbs)
Minimum (one hard drive, power supply, and processor installed)	20 kg (44.09 lbs)

## Power supply specifications

Depending on installed options, the server is configured with one of the following power supplies:

- HP ProLiant 460 W non-hot-plug power supply

Specification	Value
<b>Input requirements</b>	
Rated input voltage	100 to 240 V AC
Rated input frequency	50 Hz to 60 Hz
Rated input current	6 A to 3 A

Rated input power	590 W at 115 V AC input 570 W at 230 V AC input
BTUs per hour	2044 at 100 V AC input 2013 at 115 V AC input 2004 at 200 V AC input 1941 at 230 V AC input
<b>Power supply output</b>	
Rated steady-state power	460 W at 100 V to 120 V AC input 460 W at 200 V to 240 V AC input
Maximum peak power	460 W at 100 V to 120 V AC input 460 W at 200 V to 240 V AC input

- HP ProLiant 460 W CS power supply (94% efficiency)

Specification	Value
<b>Input requirements</b>	—
Rated input voltage	100 to 240 VAC
Rated input frequency	47 Hz to 63 Hz
Rated input current	8 A
Rated input power	509 W at 115V AC input 495 W at 230V AC input
Btus per hour	1764 at 100V AC input 1736 at 115V AC input 1694 at 200V AC input 1687 at 230V AC input
<b>Power supply output</b>	—
Rated steady-state power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input
Maximum peak power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input

- HP ProLiant 750 W CS hot-plug power supply (94% efficiency)

Specification	Value
<b>Input requirements</b>	—
Rated input voltage	100 V AC–240 V AC
Rated input frequency	50 Hz–60 Hz
Rated input current	9 A–4.5 A
Maximum rated input power	831 W at 115 V AC input 808 W at 230 V AC input
Btus per hour	2878 at 100 V AC input 2834 at 115 V AC input 2769 at 200 V AC input 2758 at 230 V AC input
<b>Power supply output</b>	—
Rated steady-state power	750 W at 100 V to 120 V AC input

	750 W at 200 V to 240 V AC input
Maximum peak power	750 W at 100 V to 120 V AC input 750 W at 200 V to 240 V AC input

## Hot-plug power supply calculations

For hot-plug power supply specifications and calculators to determine electrical and heat loading for the server, see the HP Power Advisor website (<http://www.hp.com/go/hppoweradvisor>).



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# Support and other resources

## Before you contact HP

Be sure to have the following information available before you call HP:

- Active Health System log (HP ProLiant Gen8 or later products)  
Download and have available an Active Health System log for 3 days before the failure was detected. For more information, see the *HP iLO 4 User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).
- Onboard Administrator SHOW ALL report (for HP BladeSystem products only)  
For more information on obtaining the Onboard Administrator SHOW ALL report, see the HP website (<http://www.hp.com/go/OAlog>).
- Technical support registration number (if applicable)
- Product serial number
- Product model name and number
- Product identification number
- Applicable error messages
- Add-on boards or hardware
- Third-party hardware or software
- Operating system type and revision level

## HP contact information

For United States and worldwide contact information, see the Contact HP website (<http://www.hp.com/go/assistance>).

In the United States:

- To contact HP by phone, call 1-800-334-5144. For continuous quality improvement, calls may be recorded or monitored.
- If you have purchased a Care Pack (service upgrade), see the Support & Drivers website (<http://www8.hp.com/us/en/support-drivers.html>). If the problem cannot be resolved at the website, call 1-800-633-3600. For more information about Care Packs, see the HP website (<http://pro-aq-sama.houston.hp.com/services/cache/10950-0-0-225-121.html>).

## Customer Self Repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service

providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

**NOTE:** Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

## Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

**REMARQUE:** Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

## Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

**Obbligatorie** – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

**Opzionali** – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

**NOTA:** alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

## Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

**Zwingend** – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

**Optional** – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

**HINWEIS:** Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

## Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

**NOTA:** Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas

sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

## Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

**Verplicht:** Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

**Optioneel:** Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garanteservice voor het product.

**OPMERKING:** Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

## Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

**Obrigatória** – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

**OBSERVAÇÃO:** Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

## カスタマーセルフリペア

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数のCSR部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須** - カスタマーセルフリペアが必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意** - カスタマーセルフリペアが任意である部品。この部品もカスタマーセルフリペア用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

**注：** HP製品の一部の部品は、カスタマーセルフリペア用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品がカスタマーセルフリペア除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口に電話していただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともにに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。カスタマーセルフリペアの際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

## 客戶自行維修

HP 產品提供許多客戶自行維修 (CSR) 部件，以尽可能縮短維修時間和在更換缺陷部件方面提供更大的靈活性。如果在診斷期間 HP (或 HP 服務提供商或服務合作夥伴) 確定可以通過使用 CSR 部件完成維修，HP 將直接把該部件發送給您進行更換。有兩類 CSR 部件：

- **強制性的** — 要求客戶必須自行維修的部件。如果您請求 HP 更換這些部件，則必須為該服務支付差旅費和人工費用。
- **可選的** — 客戶可以選擇是否自行維修的部件。這些部件也是為客戶自行維修設計的。不過，如果您要求 HP 為您更換這些部件，則根據為您的產品指定的保修服務類型，HP 可能收取或不再收取任何附加費用。

**注：**某些 HP 部件的設計並未考慮客戶自行維修。為了滿足客戶保修的需要，HP 要求授權服務提供商更換相關部件。這些部件在部件圖解目錄中標記為“否”。

CSR 部件將在下一個工作日發運（取決於備貨情況和允許的地理範圍）。在允許的地理範圍內，可在當天或四小時內發運，但要收取額外費用。如果需要幫助，您可以致電 HP 技術支持中心，將會有技術人員通過電話為您提供幫助。HP 會在隨更換的 CSR 部件發運的材料中指明是否必須將有缺陷的部件返還給 HP。如果要求您將有缺陷的部件返還給 HP，那麼您必須在規定期限內（通常是五 (5) 個工作日）將缺陷部件發給 HP。有缺陷的部件必須隨所提供的發運材料中的相關文件一起返還。如果未能送還有缺陷的部件，HP 可能會要求您支付更換費用。客戶自行維修時，HP 將承擔所有相關運輸和部件返回費用，並指定快遞商/承運商。

有關 HP 客戶自行維修計劃的詳細信息，請與您當地的服務提供商聯繫。有關北美地區的計劃，請訪問 HP 網站 (<http://www.hp.com/go/selfrepair>)。

## 客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

**備註：**某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

## 고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 용통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

**참고:** 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.



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# Acronyms and abbreviations

## ABEND

abnormal end

## ACU

Array Configuration Utility

## AMP

Advanced Memory Protection

## ASR

Automatic Server Recovery

## CSA

Canadian Standards Association

## CSR

Customer Self Repair

## DDR

double data rate

## FBWC

flash-backed write cache

## HP SIM

HP Systems Insight Manager

## HP SUM

HP Smart Update Manager

## IEC

International Electrotechnical Commission

## iLO

Integrated Lights-Out

## IML

Integrated Management Log

## ISO

International Organization for Standardization

## LFF

large form factor

## NMI

nonmaskable interrupt

## NVRAM

nonvolatile memory

## OA

Onboard Administrator

## ORCA

Option ROM Configuration for Arrays

## PATA

parallel ATA

## PCIe

Peripheral Component Interconnect Express

## PDU

power distribution unit

## POST

Power-On Self Test

## PXE

preboot execution environment

## RBSU

ROM-Based Setup Utility

## RDIMM

registered dual in-line memory module

## RDP

Rapid Deployment Pack

## RoHS

Restriction of Hazardous Substances

## RPS

redundant power supply

## SAS

serial attached SCSI

## SATA

serial ATA

## SD

Secure Digital

## SFF

small form factor

## SIM

Systems Insight Manager

## SPP

HP Service Pack for ProLiant

## SSA

HP Smart Storage Administrator

## TMRA

recommended ambient operating temperature

## TPM

Trusted Platform Module

## UDIMM

unregistered dual in-line memory module

## UID

unit identification

USB

universal serial bus

VC

Virtual Connect

VCA

Version Control Agent

VCRM

Version Control Repository Manager

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# Documentation feedback

HP is committed to providing documentation that meets your needs. To help us improve the documentation, send any errors, suggestions, or comments to Documentation Feedback (<mailto:docsfeedback@hp.com>). Include the document title and part number, version number, or the URL when submitting your feedback.

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